Low-Power Sub-GHz RF Transceiver (470-510 MHz & 950-960 MHz)

Applications

- Ultra low-power wireless applications operating in the 470/950 MHz ISM/SRD bands
- Wireless sensor networks
- Home and building automation

- Advanced Metering Infrastructure (AMI)
- Wireless metering
- Wireless alarm and security systems

Product Description

The **CC1100E** is a Sub-GHz high performance radio transceiver designed for very low power RF applications. It is intended for the Industrial, Scientific and Medical (ISM) and Short Range Device (SRD) frequency bands at 470-510 MHz and 950-960 MHz. The **CC1100E** is especially suited for wireless applications targeted at the Japanese ARIB STD-T96 and the Chinese Short Range Device Regulations at 470-510 MHz.

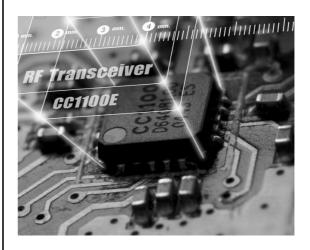
The **CC1100E** is code, package and pin out compatible with both the **CC1101** [1] and **CC1100** [2] RF transceivers. The **CC1100E**, **CC1101** and **CC1100** support complementary frequency bands and can be used to cover RF designs at the most commonly used sub-1 GHz license free frequencies around the world:

- **CC1100E**: 470-510 MHz and 950-960 MHz
- CC1101: 300-348 MHz, 387-464 MHz and 779-928 MHz
- *CC1100*: 300-348 MHz, 400-464 MHz and 800-928 MHz

The **CC1100E** RF transceiver is integrated with a highly configurable baseband modem. The modem supports various modulation formats and has a configurable data rate of up to 500 kBaud.

The **CC1100E** provides extensive hardware support for packet handling, data buffering, burst transmissions, clear channel assessment, link quality indication, and wake-on-radio.

The main operating parameters and the 64-byte transmit/receive FIFOs of the **CC1100E** can be controlled via an SPI interface. In a typical system, the **CC1100E** will be used with a microcontroller and a few additional passive components.



This product shall not be used in any of the following products or systems without prior express written permission from Texas Instruments:

- (i) implantable cardiac rhythm management systems, including without limitation pacemakers, defibrillators and cardiac resynchronization devices,
- (ii) external cardiac rhythm management systems that communicate directly with one or more implantable medical devices: or
- (iii) other devices used to monitor or treat cardiac function, including without limitation pressure sensors, biochemical sensors and neurostimulators.

Please contact lpw-medical-approval@list.ti.com if your application might fall within the category described above.



SWRS082 Page 1 of 92

Key Features

RF Performance

- High sensitivity (-112 dBm at 1.2 kBaud, 480 MHz, 1% packet error rate)
- Low current consumption (15.5 mA in RX, 1.2 kBaud, 480 MHz)
- Programmable output power up to +10 dBm for all supported frequencies
- Excellent receiver selectivity and blocking performance
- Programmable data rate from 1.2 to 500 kBaud
- Frequency bands: 470-510 MHz and 950-960 MHz

Analog Features

- 2-FSK, GFSK, and MSK supported as well as OOK and flexible ASK shaping
- Suitable for frequency hopping systems due to a fast settling frequency synthesizer; 90 µs settling time
- Automatic Frequency Compensation (AFC) can be used to align the frequency synthesizer to the actual received signal center frequency
- Integrated analog temperature sensor

Digital Features

- Flexible support for packet oriented systems; On-chip support for sync word detection, address check, flexible packet length, and automatic CRC handling
- Efficient SPI interface; All registers can be programmed with one "burst" transfer
- Digital RSSI output
- Programmable channel filter bandwidth
- Programmable Carrier Sense (CS) indicator

- Programmable Preamble Quality Indicator (PQI) for improved protection against false sync word detection in random noise
- Support for automatic Clear Channel Assessment (CCA) before transmitting (for listen-before-talk systems)
- Support for per-package Link Quality Indication (LQI)
- Optional automatic whitening and dewhitening of data

Low-Power Features

- 400 nA sleep mode current consumption
- Fast start-up time; 240 µs from sleep to RX or TX mode (measured on EM reference design [3] and [4])
- Wake-on-radio functionality for automatic low-power RX polling
- Separate 64-byte RX and TX data FIFOs (enables burst mode data transmission)

General

- Few external components; Completely onchip frequency synthesizer, no external filters or RF switch needed
- Green package: RoHS compliant and no antimony or bromine
- Small size (QFN 4x4 mm package, 20 pins)
- Suited for systems targeting compliance with ARIB STD-T96
- Suited for systems targeting compliance with the Chinese Short Range Device Regulations at 470-510 MHz
- Support for asynchronous and synchronous serial receive/transmit mode for backwards compatibility with existing radio communication protocols





Abbreviations

Abbreviations used in this data sheet are described below.

ACP	Adjacent Channel Power	MSK	Minimum Shift Keying
ADC	Analog to Digital Converter	N/A	Not Applicable
AFC	Automatic Frequency Compensation	NRZ	Non Return to Zero (Coding)
AGC	Automatic Gain Control	OOK	On-Off Keying
AMR	Automatic Meter Reading	PA	Power Amplifier
ARIB	Association of Radio Industries and Businesses	PCB	Printed Circuit Board
ASK	Amplitude Shift Keying	PD	Power Down
BER	Bit Error Rate	PER	Packet Error Rate
BT	Bandwidth-Time product	PLL	Phase Locked Loop
CCA	Clear Channel Assessment	POR	Power-On Reset
CFR	Code of Federal Regulations	PQI	Preamble Quality Indicator
CRC	Cyclic Redundancy Check	PQT	Preamble Quality Threshold
CS	Carrier Sense	PTAT	Proportional To Absolute Temperature
CW	Continuous Wave (Unmodulated Carrier)	QFN	Quad Leadless Package
DC	Direct Current	QPSK	Quadrature Phase Shift Keying
DVGA	Digital Variable Gain Amplifier	RC	Resistor-Capacitor
ESR	Equivalent Series Resistance	RF	Radio Frequency
FEC	Forward Error Correction	RSSI	Received Signal Strength Indicator
FIFO	First-In-First-Out	RX	Receive, Receive Mode
FHSS	Frequency Hopping Spread Spectrum	SAW	Surface Acoustic Wave
2-FSK	Binary Frequency Shift Keying	SMD	Surface Mount Device
GFSK	Gaussian shaped Frequency Shift Keying	SNR	Signal to Noise Ratio
IF	Intermediate Frequency	SPI	Serial Peripheral Interface
I/Q	In-Phase/Quadrature	SRD	Short Range Devices
ISM	Industrial, Scientific, Medical	TBD	To Be Defined
LC	Inductor-Capacitor	T/R	Transmit/Receive
LNA	Low Noise Amplifier	TX	Transmit, Transmit Mode
LO	Local Oscillator	UHF	Ultra High frequency
LSB	Least Significant Bit	VCO	Voltage Controlled Oscillator
LQI	Link Quality Indicator	WOR	Wake on Radio, Low power polling
MCU	Microcontroller Unit	XOSC	Crystal Oscillator
MSB	Most Significant Bit	XTAL	Crystal

Table of Contents

APPL	LICATIONS	1
PROI	DUCT DESCRIPTION	
KEY	FEATURES	1
	FEATURES	
	ERFORMANCE	
	LOG FEATURES	
	TAL FEATURES	
	/-POWER FEATURES	
	ERAL	
ABBI	REVIATIONS	3
TABI	LE OF CONTENTS	4
1	ABSOLUTE MAXIMUM RATINGS	7
2	OPERATING CONDITIONS	7
3	GENERAL CHARACTERISTICS	7
4	ELECTRICAL SPECIFICATIONS	
4 .1	CURRENT CONSUMPTION	
4.2	RF RECEIVE SECTION	
4.3	RF Transmit Section	
4.4	CRYSTAL OSCILLATOR	
4.5	Low Power RC Oscillator	
4.6	FREQUENCY SYNTHESIZER CHARACTERISTICS.	
4.7 4.8	ANALOG TEMPERATURE SENSOR	
4.6 4.9	POWER-ON RESET	
5	PIN CONFIGURATION	
6	CIRCUIT DESCRIPTION	
7	APPLICATION CIRCUIT	
7.1	BIAS RESISTOR	
7.2	BALUN AND RF MATCHING	
7.3	CRYSTAL	19
7.4	REFERENCE SIGNAL	
7.5	Additional Filtering	
7.6	POWER SUPPLY DECOUPLING	
7.7 7.8	Antenna Considerations	
8	CONFIGURATION OVERVIEW	
9	CONFIGURATION SOFTWARE	
10	4-WIRE SERIAL CONFIGURATION AND DATA INTERFACE	
10.1 10.2	CHIP STATUS BYTE	
10.2	SPI READ	
10.3	COMMAND STROBES	
10.5	FIFO Access	
10.6	PATABLE Access	29
11	MICROCONTROLLER INTERFACE AND PIN CONFIGURATION	30
11.1	CONFIGURATION INTERFACE	
11.2	GENERAL CONTROL AND STATUS PINS	
11.3	OPTIONAL RADIO CONTROL FEATURE	
12	DATA RATE PROGRAMMING	
13	RECEIVER CHANNEL FILTER BANDWIDTH	31



14	DEMODULATOR, SYMBOL SYNCHRONIZER, AND DATA DECISION	32
14.1	Frequency Offset Compensation	
14.2	BIT SYNCHRONIZATION	
14.3	BYTE SYNCHRONIZATION	
15	PACKET HANDLING HARDWARE SUPPORT	
15.1	Data Whitening	
15.2	PACKET FORMAT	
15.3	PACKET FILTERING IN RECEIVE MODE	
15.4	PACKET HANDLING IN TRANSMIT MODE	
15.5	PACKET HANDLING IN RECEIVE MODE	
15.6	PACKET HANDLING IN FIRMWARE	
16	MODULATION FORMATS	
16.1	FREQUENCY SHIFT KEYING	
16.2	MINIMUM SHIFT KEYING	
16.3	AMPLITUDE MODULATION	
17	RECEIVED SIGNAL QUALIFIERS AND LINK QUALITY INFORMATION	
17.1	SYNC WORD QUALIFIER	
17.2 17.3	PREAMBLE QUALITY THRESHOLD (PQT)RSSI	
17.3	CARRIER SENSE (CS)	
17.4	CLEAR CHANNEL ASSESSMENT (CCA)	
17.6	LINK QUALITY INDICATOR (LQI)	
18	FORWARD ERROR CORRECTION WITH INTERLEAVING	
18.1	FORWARD ERROR CORRECTION WITH INTERLEAVING	
18.2	INTERLEAVING	
19 19.1	RADIO CONTROL	
19.1	CRYSTAL CONTROL	
19.2	VOLTAGE REGULATOR CONTROL	
19.3	ACTIVE MODES	
19.5	Wake On Radio (WOR)	
19.6	TIMING	
19.7	RX TERMINATION TIMER	
20	DATA FIFO	50
21	FREQUENCY PROGRAMMING	
22	VCO	
22.1	VCO AND PLL SELF-CALIBRATION	
23	VOLTAGE REGULATORS	
24	OUTPUT POWER PROGRAMMING	52
25	SHAPING AND PA RAMPING	53
26	GENERAL PURPOSE / TEST OUTPUT CONTROL PINS	54
27	ASYNCHRONOUS AND SYNCHRONOUS SERIAL OPERATION	56
27.1	ASYNCHRONOUS SERIAL OPERATION	
27.2	SYNCHRONOUS SERIAL OPERATION	56
28	SYSTEM CONSIDERATIONS AND GUIDELINES	57
28.1	SRD REGULATIONS.	
28.2	Frequency Hopping and Multi-Channel Systems	
28.3	DATA BURST TRANSMISSIONS	58
28.4	CONTINUOUS TRANSMISSIONS	58
28.5	LOW COST SYSTEMS	
28.6	BATTERY OPERATED SYSTEMS	
28.7	INCREASING OUTPUT POWER	59
29	CONFIGURATION REGISTERS	
29.1	CONFIGURATION REGISTER DETAILS – REGISTERS WITH PRESERVED VALUES IN SLEEP STATE	
29.2	CONFIGURATION REGISTER DETAILS – REGISTERS THAT LOOSE PROGRAMMING IN SLEEP STATE	84



29.3	STATUS REGISTER DETAILS	85
30	PACKAGE DESCRIPTION (QFN 20)	89
30.1	RECOMMENDED PCB LAYOUT FOR PACKAGE (QFN 20)	89
	SOLDERING INFORMATION	
30.3	ORDERING INFORMATION	90
REFI	ERENCES	90
REFI	ERENCES	91
31	GENERAL INFORMATION	92
31.1	DOCUMENT HISTORY	92

1 Absolute Maximum Ratings

Under no circumstances must the absolute maximum ratings given in Table 1 be violated. Stress exceeding one or more of the limiting values may cause permanent damage to the device.

Parameter	Min	Max	Units	Condition
Supply voltage	-0.3	3.9	V	All supply pins must have the same voltage
Voltage on any digital pin	-0.3	VDD + 0.3		
		max 3.9	V	
Voltage on the pins RF_P, RF_N, and DCOUPL	-0.3	2.0	V	
Voltage ramp-up rate		120	kV/µs	
Input RF level		+10	dBm	
Storage temperature range	-50	150	°C	
Solder reflow temperature		260	°C	According to IPC/JEDEC J-STD-020
ESD		2000	V	According to JEDEC STD 22, method A114, Human Body Model (HBM)
ESD		750	V	According to JEDEC STD 22, C101C, Charged Device Model (CDM)

Table 1: Absolute Maximum Ratings



Caution! ESD sensitive device. Precaution should be used when handling the device in order to prevent permanent damage.

2 Operating Conditions

The operating conditions for the *CC1100E* are listed Table 2 in below.

Parameter	Min	Max	Unit	Condition
Operating temperature	-40	85	°C	
Operating supply voltage	1.8	3.6	V	All supply pins must have the same voltage

Table 2: Operating Conditions

3 General Characteristics

Parameter	Min	Тур	Max	Unit	Condition/Note
Frequency range	470		510	MHz	
	950		960	MHz	
Data rate	1.2		500	kBaud	2-FSK
	1.2		250	kBaud	GFSK, OOK, and ASK
	26		500	kBaud	(Shaped) MSK (also known as differential offset QPSK)
					Optional Manchester encoding (the data rate in kbps will be half the baud rate)

Table 3: General Characteristics





4 Electrical Specifications

4.1 Current Consumption

 $T_A = 25^{\circ}\text{C}$, VDD = 3.0 V if nothing else stated. All measurement results are obtained using the CC1100E EM reference designs ([3] and[4]). Reduced current settings (MDMCFG2.DEM_DCFILT_OFF=1) gives a slightly lower current consumption at the cost of a reduction in sensitivity. See Table 6: RF Receive Section for additional details on current consumption and sensitivity.

Parameter	Min	Тур	Max	Unit	Condition
Current consumption in power down modes		0.3		μΑ	Voltage regulator to digital part off, register values retained (SLEEP state). All GDO pins programmed to 0x2F (HW to 0)
		0.7		μА	Voltage regulator to digital part off, register values retained, low-power RC oscillator running (SLEEP state with WOR enabled)
		100		μА	Voltage regulator to digital part off, register values retained, XOSC running (SLEEP state with MCSM0 . OSC_FORCE_ON set)
		165		μΑ	Voltage regulator to digital part on, all other modules in power down (XOFF state)
Current consumption		10.0		μА	Automatic RX polling once each second, using low-power RC oscillator, with 460 kHz filter bandwidth and 250 kBaud data rate, PLL calibration every 4 th wakeup. Average current with signal in channel <i>below</i> carrier sense level (MCSM2.RX_TIME_RSSI=1)
		35		μА	Same as above, but with signal in channel <i>above</i> carrier sense level, 1.95 ms RX timeout, and no preamble/sync word found
		1.3		μА	Automatic RX polling every 15 th second, using low-power RC oscillator, with 460 kHz filter bandwidth and 250 kBaud data rate, PLL calibration every 4 th wakeup. Average current with signal in channel below carrier sense level (MCSM2.RX_TIME_RSSI=1)
		32		μА	Same as above, but with signal in channel <i>above</i> carrier sense level, 29.3 ms RX timeout, and no preamble/sync word found
		1.7		mA	Only voltage regulator to digital part and crystal oscillator running (IDLE state)
		9		mA	Only the frequency synthesizer is running (FSTXON state). This currents consumption is also representative for the other intermediate states when going from IDLE to RX or TX, including the calibration state
Current consumption, 480 MHz		16.5		mA	Receive mode, 1.2 kBaud, reduced current, input at sensitivity limit
		15.4		mA	Receive mode, 1.2 kBaud, reduced current, input well above sensitivity limit
		16.6		mA	Receive mode, 38.4 kBaud , reduced current, input at sensitivity limit
		15.5		mA	Receive mode, 38.4 kBaud , reduced current, input well above sensitivity limit
		17.5		mA	Receive mode, 250 kBaud, reduced current, input at sensitivity limit
		16.1		mA	Receive mode, 250 kBaud, reduced current, input well above sensitivity limit
		20		mA	Receive mode, 500 kBaud, input at sensitivity limit
		18.7		mA	Receive mode, 500 kBaud, input well above sensitivity limit
		29.6		mA	Transmit mode, +10 dBm output power
		16.6		mA	Transmit mode, 0 dBm output power
		16.5		mA	Transmit mode, -6 dBm output power



Parameter	Min	Тур	Max	Unit	Condition
Current consumption, 955 MHz		16.3		mA	Receive mode, 1.2 kBaud , reduced current, input at sensitivity limit
955 IVIPIZ		15.2		mA	Receive mode, 1.2 kBaud , reduced current, input well above sensitivity limit
		17.7		mA	Receive mode, 38.4 kBaud , reduced current, input at sensitivity limit
		17.0		mA	Receive mode, 38.4 kBaud , reduced current, input well above sensitivity limit
		16.8		mA	Receive mode, 76.8 kBaud , reduced current, input at sensitivity limit
		15.1		mA	Receive mode, 76.8 kBaud , reduced current, input well above sensitivity limit
		30.9		mA	Transmit mode, +10 dBm output power
		16.5		mA	Transmit mode, 0 dBm output power
		15.8		mA	Transmit mode, -6 dBm output power

Table 4: Electrical Specifications

		upply Vol VDD = 1.8	_	Supply Voltage VDD = 3.0 V			Supply Voltage VDD = 3.6 V		
Temperature [°C]	-40	25	85	-40	25	85	-40	25	85
Current [mA]	29.3	28.7	28.1	31.6	30.9	30.3	31.9	31.2	30.6

Table 5: Typical Variation in TX Current Consumption over Temperature and Supply Voltage, 955 MHz and +10 dBm Output Power Setting

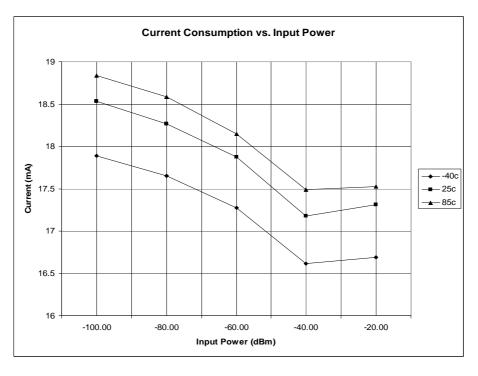


Figure 1: Typical Variation in RX Current Consumption overt Temperature and Input Power Level, 955 MHz, 76.8 kBaud GFSK, Sensitivity Optimized Setting





4.2 RF Receive Section

 $T_A = 25$ °C, VDD = 3.0 V if nothing else stated. All measurement results are obtained using the CC1100E EM reference designs ([3] and[4]).

Parameter	Min	Тур	Max	Unit	Condition/Note
Digital channel filter bandwidth	58		812	kHz	User programmable. The bandwidth limits are proportional to crystal frequency (given values assume a 26.0 MHz crystal)
400 1411 4 0 1 0		*** **	4		
480 MHz, 1.2 kBau		•	•		i_DCFILT_OFF=0 Iz deviation, 58 kHz digital channel filter bandwidth)
` '	1 70 packet ei		l	T .	, , , , , , , , , , , , , , , , , , ,
Receiver sensitivity		-112		dBm	Sensitivity can be traded for current consumption by setting MDMCFG2.DEM_DCFILT_OFF=1. The typical current consumption is then reduced from 17.9 mA to 16.5 mA at sensitivity limit. The sensitivity is typically reduced to -110 dBm
					M_DCFILT_OFF=0
(GFSK with BT=1,	1% packet er	ror rate, 20 b	ytes packet l	length, 20 kH	z deviation, 100 kHz digital channel filter bandwidth)
Receiver sensitivity		-104		dBm	Sensitivity can be traded for current consumption by setting MDMCFG2.DEM_DCFILT_OFF=1. The typical current consumption is then reduced from 18mA to 16.6 mA at sensitivity limit.
480 MHz, 250 kBa (GFSK with BT=1,		•	•		M_DCFILT_OFF=0 Hz deviation, 540 kHz digital channel filter bandwidth)
Receiver sensitivity		-95		dBm	Sensitivity can be traded for current consumption by setting MDMCFG2.DEM_DCFILT_OFF=1. The typical current consumption is then reduced from 19.2mA to 17.5 mA at sensitivity limit.
480 MHz, 500 kBa (MSK, 1% packet e		•	•		M_DCFILT_OFF=0 annel filter bandwidth)
Receiver sensitivity		-88		dBm	Setting MDMCFG2.DEM_DCFILT_OFF=1 is not an valid option at 500 kBaud dara rate
955 MHz, 1.2 kBau (GFSK with BT=1,		•	•		I_DCFILT_OFF=0 Hz deviation, 58 kHz digital channel filter bandwidth)
Receiver sensitivity		-111		dBm	Sensitivity can be traded for current consumption by setting MDMCFG2.DEM_DCFILT_OFF=1. The typical current consumption is then reduced from 18.2 mA to 16.3 mA at sensitivity limit. The sensitivity is typically reduced to -109 dBm
Saturation		-15		dBm	FIFOTHR.CLOSE_IN_RX=0. See more in DN010 [11]
Adjacent channel rejection		28		dB	Desired channel 3 dB above the sensitivity limit. 200 kHz channel spacing
Alternate channel rejection		37		dB	Desired channel 3 dB above the sensitivity limit. 200 kHz channel spacing
					See Figure 2 for plot of selectivity versus frequency offset
Image channel		32		dB	IF frequency 152 kHz
rejection, 955 MHz					Desired channel 3 dB above the sensitivity limit



 $T_A = 25$ °C, VDD = 3.0 V if nothing else stated. All measurement results are obtained using the CC1100E EM reference designs ([3] and[4])

Receiver sensitivity	-104	dBm	Sensitivity can be traded for current consumption by setting MDMCFG2.DEM_DCFILT_OFF=1. The typical current consumption is then reduced from 18.3mA to 17.7 mA at sensitivity limit.
Saturation	-18	dBm	FIFOTHR.CLOSE_IN_RX=0. See more in DN010 [11]
Adjacent channel rejection	12	dB	Desired channel 3 dB above the sensitivity limit. 200 kHz channel spacing
Alternate channel rejection	27	dB	Desired channel 3 dB above the sensitivity limit. 200 kHz channel spacing
			See Figure 3 for plot of selectivity versus frequency offset
Image channel rejection, 955 MHz	23	dB	IF frequency 152 kHz Desired channel 3 dB above the sensitivity limit

Parameter	Min	Тур	Max	Unit	Condition/Note
955 MHz, 76.8 kBaud data (GFSK with BT=1, 1% pack					CFG2.DEM_DCFILT_OFF=0 th, 32 kHz deviation, 232 kHz digital channel filter bandwidth)
Receiver sensitivity		-100		dBm	Sensitivity can be traded for current consumption by setting MDMCFG2.DEM_DCFILT_OFF=1. The typical current consumption is then reduced from 18.6mA to 16.8 mA at sensitivity limit.
Blocking					
Blocking at ±2 MHz offset, 1.2 kBaud, 955 MHz		-49		dBm	Desired channel 3 dB above the sensitivity limit
Blocking at ±2 MHz offset, 38.4 kBaud, 955 MHz		-49		dBm	Desired channel 3 dB above the sensitivity limit
Blocking at ±10 MHz offset, 1.2 kBaud, 955 MHz		-39		dBm	Desired channel 3 dB above the sensitivity limit
Blocking at ±10 MHz offset, 38.4 kBaud, 955 MHz		-40		dBm	Desired channel 3 dB above the sensitivity limit
General	1		ı	ı	
Spurious Emmissions			-38	dBm	25 MHz – 1 GHz
					Excluding the 470-510 MHz band, signal at 960 MHz, 2 nd harmonicAbove 1 GHz
			-32	dBm	Typical radiated spurious emission is -49 dBm measured at the VCO frequency
					Data above is for the 470-510 MHz band, for spurious emmisions at 950-960 MHz, look at section 28.
RX latency		9		Bit	Serial operation. Time from start of reception until data is available on the receiver data output pin is equal to 9 bits.

Table 6: RF Receive Section



SWRS082 Page 11 of 92



	Supply VDD = 1.8 V		Voltage	Supply VDD = 3.0 V		Voltage	Voltage Supply VDD = 3.6 V		Voltage
Temperature [°C]	-40	25	85	-40	25	85	-40	25	85
Sensitivity [dBm]	-101	-100	-96	-102	-100	-98	-102	-100	-98

Table 7: Typical Variation in Sensitivity over Temperature and Supply Voltage, 955 MHz, 76.8 kBaud GFSK, Sensitivity Optimized Setting, 770 MHz notch filter Used

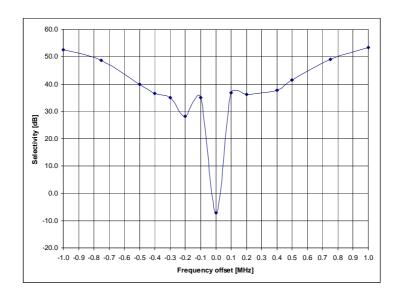


Figure 2: Typical Selectivity at 1.2 kBaud Data Rate, 955 MHz, GFSK, 5.2 kHz Deviation. IF Frequency is 152.3 kHz and the Digital Channel Filter Bandwidth is 58 kHz

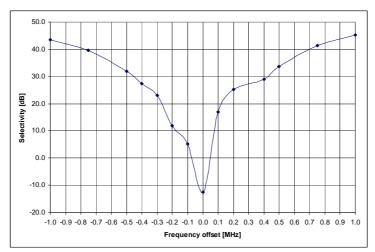


Figure 3: Typical Selectivity at 38.4 kBaud Data Rate, 955 MHz, GFSK, 20 kHz Deviation. IF Frequency is 152.3 kHz and the Digital Channel Filter Bandwidth is 100 kHz



4.3 RF Transmit Section

 $T_A = 25$ °C, VDD = 3.0 V, +10dBm if nothing else stated. All measurement results are obtained using the CC1100E EM reference designs ([3] and[4]).

Parameter	Min	Тур	Max	Unit	Condition/Note
Differential load impedance					Differential impedance as seen from the RF-port (RF_P and RF_N) towards the antenna. Follow the CC1100E EM reference designs ([3] and 0) available from the TI website
480 MHz		132 – j2		Ω	reference designs ([3] and 0) available from the 11 website
955 MHz		59 – j67		Ω	
Output power, highest setting					Output power is programmable, and full range is available in all frequency bands. Output power may be restricted by regulatory limits.
480 MHz		+10		dBm	Delivered to a 50 Ω single-ended load via the CC1100E EM
955 MHz		+9		dBm	reference designs ([3] and 0) RF matching network
Output power, lowest setting		-30		dBm	Output power is programmable, and full range is available in all frequency bands
					Delivered to a 50Ω single-ended load via the CC1100E EM reference designs ([3] and 0) RF matching network
Harmonics, conducted 480 MHz 2 nd Harm, 480 MHz 3 rd Harm, 480 MHz 955 MHz		-40 -48		dBm dBm	Measured with 10 dBm CW, TX frequency at 480 / 955 MHz Frequencies below 960 MHz Frequencies above 960 MHz
2 nd Harm, 955 MHz 3 rd Harm, 955 MHz		-34 -50		dBm dBm	
Spurious emissions, conducted, harmonics not included					Measured with +10 dBm CW, TX frequency at 480 / 955 MHz
480 MHz 955MHz		-39 -50		dBm dBm	Frequencies below 1 GHz, outside 470-510 MHz band Frequencies above 1 GHz
					Refer to section 28.1 for information on Spurious Emissions
General			1	1	_
TX latency		8		bit	Serial operation. Time from sampling the data on the transmitter data input pin until it is observed on the RF output ports

Table 8: RF Transmit Section

		Supply Voltage VDD = 1.8 V			/oltage .0 V		Supply Voltage VDD = 3.6 V		
Temperature [°C]	-40	25	85	-40	25	85	-40	25	85
Output Power [dBm]	10.1	10.8	10.8	10.2	10.4	10.5	9.2	9.9	9.9

Table 9: Typical Variation in Output Power over Temperature and Supply Voltage, 480 MHz, +10 dBm Output Power Setting

		Supply Voltage VDD = 1.8 V			/oltage .0 V		Supply Voltage VDD = 3.6 V		
Temperature [°C]	-40	25	85	-40	25	85	-40	25	85
Output Power [dBm]	8.8	8.4	7.9	9.6	9.2	8.8	9.6	9.2	8.8

Table 10: Typical Variation in Output Power over Temperature and Supply Voltage, 955 MHz, +10 dBm Output Power Setting

4.4 Crystal Oscillator

 $T_A = 25^{\circ}C$, VDD = 3.0 V if nothing else is stated. All measurement results obtained using the CC1100E EM reference designs ([3] and[4]).

Parameter	Min	Тур	Max	Unit	Condition/Note
Crystal frequency	26	26	27	MHz	
Tolerance		±40		ppm	This is the total tolerance including a) initial tolerance, b) crystal loading, c) aging, and d) temperature dependence. The acceptable crystal tolerance depends on RF frequency and channel spacing / bandwidth.
Load capacitance	10	13	20	pF	Simulated over operating conditions
ESR			100	Ω	
Start-up time		150		μs	This parameter is to a large degree crystal dependent. Measured on the CC1100E EM reference designs ([3] and[4]) using crystal AT-41CD2 from NDK

Table 11: Crystal Oscillator Parameters

4.5 Low Power RC Oscillator

 $T_A = 25^{\circ}C$, VDD = 3.0 V if nothing else is stated. All measurement results obtained using the CC1100E EM reference designs ([3] and[4]).

Parameter	Min	Тур	Max	Unit	Condition/Note
Calibrated frequency	34.7	34.7	36	kHz	Calibrated RC Oscillator frequency is XTAL frequency divided by 750
Frequency accuracy after calibration			±1	%	
Temperature coefficient		+0.5		% / °C	Frequency drift when temperature changes after calibration
Supply voltage coefficient		+3		% / V	Frequency drift when supply voltage changes after calibration
Initial calibration time		2		ms	When the RC Oscillator is enabled, calibration is continuously done in the background as long as the crystal oscillator is running

Table 12: RC Oscillator Parameters





4.6 Frequency Synthesizer Characteristics

T_A = 25°C, VDD = 3.0 V if nothing else is stated. All measurement results are obtained using the CC1100E EM reference designs ([3] and[4]). Min figures are given using a 27 MHz crystal. Typ and max figures are given using a 26 MHz crystal.

Parameter	Min	Тур	Max	Unit	Condition/Note
Programmed frequency resolution	397	F _{XOSC} / 2 ¹⁶	412	Hz	26-27 MHz crystal. The resolution (in Hz) is equal for all frequency bands
Synthesizer frequency tolerance		±40		ppm	Given by crystal used. Required accuracy (including temperature and aging) depends on frequency band and channel bandwidth / spacing
RF carrier phase noise		-92		dBc/Hz	@ 50 kHz offset from carrier
RF carrier phase noise		-92		dBc/Hz	@ 100 kHz offset from carrier
RF carrier phase noise		-92		dBc/Hz	@ 200 kHz offset from carrier
RF carrier phase noise		-98		dBc/Hz	@ 500 kHz offset from carrier
RF carrier phase noise		-107		dBc/Hz	@ 1 MHz offset from carrier
RF carrier phase noise		-113		dBc/Hz	@ 2 MHz offset from carrier
RF carrier phase noise		-119		dBc/Hz	@ 5 MHz offset from carrier
RF carrier phase noise		-129		dBc/Hz	@ 10 MHz offset from carrier
PLL turn-on / hop time	85.1	88.4	88.4	μs	Time from leaving the IDLE state until arriving in the RX, FSTXON or TX state, when not performing calibration. Crystal oscillator running
PLL RX/TX settling time	9.3	9.6	9.6	μS	Settling time for the 1-IF frequency step from RX to TX
PLL TX/RX settling time	20.7	21.5	21.5	μS	Settling time for the 1-IF frequency step from TX to RX
PLL calibration time	694	721	721	μ\$	Calibration can be initiated manually or automatically before entering or after leaving RX/TX

Table 13: Frequency Synthesizer Parameters

4.7 Analog Temperature Sensor

 $T_A = 25^{\circ}\text{C}$, VDD = 3.0 V if nothing else is stated. All measurement results obtained using the CC1100E EM reference designs ([3] and[4]). Note that it is necessary to write 0xBF to the PTEST register to use the analog temperature sensor in the IDLE state.

Parameter	Min	Тур	Max	Unit	Condition/Note
Output voltage at -40°C		0.651		V	
Output voltage at 0°C		0.747		V	
Output voltage at +40°C		0.847		V	
Output voltage at +80°C		0.945		V	
Temperature coefficient		2.47		mV/°C	Fitted from -20 °C to +80 °C
Error in calculated temperature, calibrated	-2 *	0	2 *	°C	From –20 °C to +80 °C when using 2.47 mV / °C, after 1-point calibration at room temperature
					[*] The indicated minimum and maximum error with 1- point calibration is based on simulated values for typical process parameters
Current consumption increase when enabled		0.3		mA	

Table 14: Analog Temperature Sensor Parameters



4.8 DC Characteristics

 $T_A = 25^{\circ}C$ if nothing else stated.

Digital Inputs/Outputs	Min	Max	Unit	Condition
Logic "0" input voltage	0	0.7	V	
Logic "1" input voltage	VDD-0.7	VDD	V	
Logic "0" output voltage	0	0.5	V	For up to 4 mA output current
Logic "1" output voltage	VDD-0.3	VDD	V	For up to 4 mA output current
Logic "0" input current	N/A	-50	nA	Input equals 0V
Logic "1" input current	N/A	50	nA	Input equals VDD

Table 15: DC Characteristics

4.9 Power-On Reset

When the power supply complies with the requirements in Table 16 below, proper Power-On-Reset functionality is guaranteed. Otherwise, the chip should be assumed to have unknown state until transmitting an SRES strobe over the SPI interface. See Section 19.1 on page 45 for further details.

Parameter	Min	Тур	Max	Unit Condition/Note	
Power-up ramp-up time			5	ms	From 0V until reaching 1.8V
Power off time	1			ms	Minimum time between power-on and power-off

Table 16: Power-On Reset Requirements

5 Pin Configuration

The **CC1100E** pin-out is shown in Figure 4 and Table 17. See Section 26 for details on the I/O configuration.

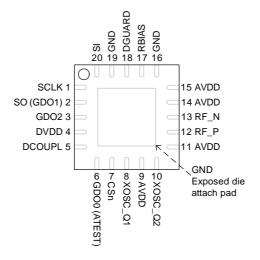


Figure 4: Pin out Top View

Note: The exposed die attach pad **must** be connected to a solid ground plane as this is the main ground connection for the chip





Pin#	Pin Name	Pin type	Description
1	SCLK	Digital Input	Serial configuration interface, clock input
2	SO (GDO1)	Digital Output	Serial configuration interface, data output
			Optional general output pin when CSn is high
3	GDO2	Digital Output	Digital output pin for general use:
			Test signals
			FIFO status signals
			Clear channel indicator
			Clock output, down-divided from XOSC
			Serial output RX data
4	DVDD	Power (Digital)	1.8 - 3.6 V digital power supply for digital I/O's and for the digital core voltage regulator
5	DCOUPL	Power (Digital)	1.6 - 2.0 V digital power supply output for decoupling
			NOTE: This pin is intended for use only by the CC1100E . It can not be used to provide supply voltage to other devices
6	GDO0	Digital I/O	Digital output pin for general use:
	(ATEST)		Test signals
			FIFO status signals
			Clear channel indicator
			Clock output, down-divided from XOSC
			Serial output RX data
			Serial input TX data
			Also used as analog test I/O for prototype/production testing
7	CSn	Digital Input	Serial configuration interface, chip select
8	XOSC_Q1	Analog I/O	Crystal oscillator pin 1, or external clock input
9	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
10	XOSC_Q2	Analog I/O	Crystal oscillator pin 2
11	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
12	RF_P	RF I/O	Positive RF input signal to LNA in receive mode
			Positive RF output signal from PA in transmit mode
13	RF_N	RF I/O	Negative RF input signal to LNA in receive mode
			Negative RF output signal from PA in transmit mode
14	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
15	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
16	GND	Ground (Analog)	Analog ground connection
17	RBIAS	Analog I/O	External bias resistor for reference current
18	DGUARD	Power (Digital)	Power supply connection for digital noise isolation
19	GND	Ground (Digital)	Ground connection for digital noise isolation
20	SI	Digital Input	Serial configuration interface, data input

Table 17: Pin out Overview



SWRS082 Page 17 of 92

6 Circuit Description

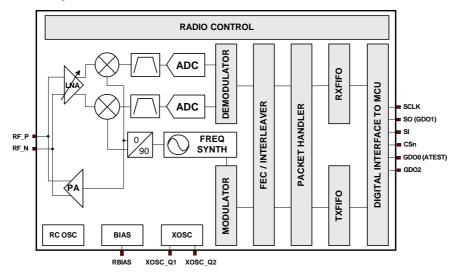


Figure 5: **CC1100E** Simplified Block Diagram

A simplified block diagram of the **CC1100E** is shown in Figure 5.

The **CC1100E** features a low-IF receiver. The received RF signal is amplified by the low-noise amplifier (LNA) and down-converted in quadrature (I and Q) to the intermediate frequency (IF). At IF, the I/Q signals are digitized by the ADCs. Automatic gain control (AGC), fine channel filtering and demodulation bit/packet synchronization are performed digitally.

The transmitter part of the **CC1100E** is based on direct synthesis of the RF frequency. The

7 Application Circuit

Only a few external components are required for using the **CC1100E**. The recommended application circuits for the **CC1100E** are shown in Figure 6 and Figure 7. The external components

7.1 Bias Resistor

The bias resistor R171 is used to set an

7.2 Balun and RF Matching

The balanced RF input and output of the **CC1100E** share two common pins and are designed for a simple, low-cost matching and balun network on the printed circuit board. The receive and transmit switching at the **CC1100E** front-end is controlled by a dedicated on-chip

frequency synthesizer includes a completely on-chip LC VCO and a 90 degree phase shifter for generating the I and Q LO signals to the down-conversion mixers in receive mode.

A crystal is to be connected to XOSC_Q1 and XOSC_Q2. The crystal oscillator generates the reference frequency for the synthesizer, as well as clocks for the ADC and the digital part.

A 4-wire SPI serial interface is used for configuration and data buffer access.

The digital baseband includes support for channel configuration, packet handling, and data buffering.

are described in Table 18, and typical values are given in Table 19.

accurate bias current.

function, eliminating the need for an external RX/TX-switch.

A few external passive components combined with the internal RX/TX switch/termination circuitry ensures match in both RX and TX mode. The components between the RF_N/RF_P pins and the point where the two



SWRS082 Page 18 of 92

signals are joined together (C131, C121, L121 and L131 for the 470 MHz reference design [3], and L121, L131, C121, L122, C131, C122 and L132 for the 950 MHz reference design [4]) form a balun that converts the differential RF signal on the **CC1100E** to a single-ended RF signal. C124 is needed for DC blocking. Together with an appropriate LC network, the balun components also transform the impedance to match a 50 Ω load. C125 provides DC blocking and is only needed if there is a DC path in the antenna. For the 950

MHz reference design, this component may also be used for additional filtering, see section 7.5 below. Suggested values for 470 MHz, and 950 MHz are listed in Table 19.

The balun and LC filter component values and their placement are important to keep the performance optimized. It is highly recommended to follow the CC1100E EM reference design ([3] and 0). Gerber files and schematics for the reference designs are available for download from the TI website.

7.3 Crystal

A crystal in the frequency range 26-27 MHz must be connected between the XOSC_Q1 and XOSC_Q2 pins. The oscillator is designed for parallel mode operation of the crystal. In addition, loading capacitors (C81 and C101) for the crystal are required. The loading capacitor values depend on the total load capacitance, C_L , specified for the crystal. The total load capacitance seen between the crystal terminals should equal C_L for the crystal to oscillate at the specified frequency.

$$C_L = \frac{1}{\frac{1}{C_{81}} + \frac{1}{C_{101}}} + C_{parasitic}$$

The parasitic capacitance is constituted by pin input capacitance and PCB stray capacitance. Total parasitic capacitance is typically 2.5 pF.

The crystal oscillator is amplitude regulated. This means that a high current is used to start up the oscillations. When the amplitude builds up, the current is reduced to what is necessary to maintain approximately 0.4 Vpp signal swing. This ensures a fast start-up, and keeps the drive level to a minimum. The ESR of the crystal should be within the specification in order to ensure a reliable start-up (see Section 4.4 on page 14).

The initial tolerance, temperature drift, aging and load pulling should be carefully specified in order to meet the required frequency accuracy in a certain application.

7.4 Reference Signal

The chip can alternatively be operated with a reference signal from 26 to 27 MHz instead of a crystal. This input clock can either be a full-swing digital signal (0 V to VDD) or a sine wave of maximum 1 V peak-peak amplitude. The reference signal must be connected to the

XOSC_Q1 input. The sine wave must be connected to XOSC_Q1 using a serial capacitor. This capacitor can be omitted when using a full-swing digital signal. The XOSC_Q2 line must be left un-connected. C81 and C101 can be omitted when using a reference signal.

7.5 Additional Filtering

In the 950 MHz reference design, C126 and L125 together with C125 build an optional filter to reduce emission at 770 MHz. This filter is necessary for applications with an external antenna connector that target compliance with ARIB STD-T96. If this filtering is not necessary, C125 will work as a DC block (only

necessary if there is a DC path in the antenna). C126 and L125 should in that case be left unmounted.

Additional external components (e.g. an RF SAW filter) may be used in order to improve the performance in specific applications.

7.6 Power Supply Decoupling

The power supply must be properly decoupled close to the supply pins. Note that decoupling capacitors are not shown in the application circuit. The placement and the size of the

decoupling capacitors are very important to achieve the optimum performance. The CC1100E EM reference designs ([3] and 0) should be followed closely.





7.7 Antenna Considerations

The reference designs ([3] and 0) contain an SMA connector and are matched for a 50 Ω load. The SMA connector makes it easy to connect evaluation modules and prototypes to different test equipment for example a

spectrum analyzer. The SMA connector can also be replaced by an antenna suitable for the desired application. Please refer to the antenna selection guide [14] for further details regarding antenna solutions provided by TI.

Component	Description	
C51	Decoupling capacitor for on-chip voltage regulator to digital part	
C81/C101	Crystal loading capacitors	
C121/C131	RF balun/matching capacitors	
C122	RF LC filter/matching filter capacitor (470 MHz). RF balun/matching capacitor (950 MHz).	
C123	RF LC filter/matching capacitor	
C124	RF balun DC blocking capacitor	
C125	RF LC filter DC blocking capacitor and part of optional RF LC filter (950 MHz)	
C126	Part of optional RF LC filter and DC-block (950 MHz)	
L121/L131	RF balun/matching inductors (wire wound or multi-layer type)	
L122 RF LC filter/matching filter inductor (470 MHz). RF balun/matching inductor (950 MHz). or multi-layer type)		
L123	RF LC filter/matching filter inductor (wire wound or multi-layer type)	
L124 RF LC filter/matching filter inductor (wire wound or multi-layer type)		
L125 Optional RF LC filter/matching filter inductor (950 MHz) (wire wound or multi-layer type)		
L132 RF balun/matching inductor. (wire wound or multi-layer type)		
R171	Resistor for internal bias current reference	
XTAL	26MHz - 27MHz crystal	

Table 18: Overview of External Components (excluding supply decoupling capacitors)



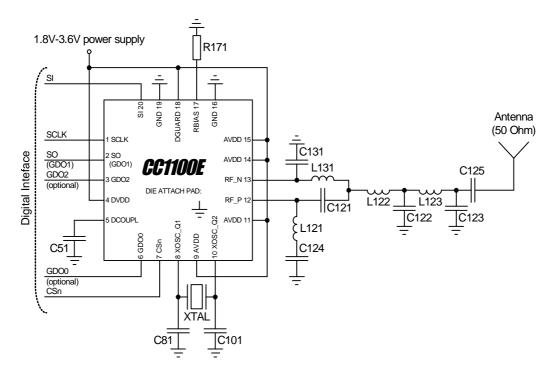


Figure 6: Typical Application and Evaluation Circuit 470 MHz (excluding supply decoupling capacitors)

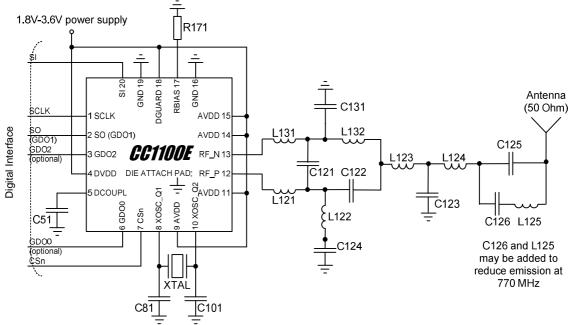


Figure 7: Typical Application and Evaluation Circuit 950 MHz (excluding supply decoupling capacitors)



Component	Value at 470MHz	Value at 950MHz	Manufacturer
C51	100 nF ± 10%, 0402 X5R		Murata GRM1555C series
C81	27 pF ± 5%	6, 0402 NP0	Murata GRM1555C series
C101	27 pF ± 5%	6, 0402 NP0	Murata GRM1555C series
C121	3.9 pF ± 0.25 pF, 0402 NP0	1.0 pF ± 0.25 pF, 0402 NP0	Murata GRM1555C series
C122	6.8 pF ± 5% pF, 0402 NP0	1.5 pF ± 0.25 pF, 0402 NP0	Murata GRM1555C series
C123	5.6 pF ± 0.5 pF, 0402 NP0	2.7 pF ± 0.25 pF, 0402 NP0	Murata GRM1555C series
C124	.220 pF pF ± 5%, 0402 NP0	100 pF ± 5%, 0402 NP0	Murata GRM1555C series
C125	220 pF ± 5%, 0402 NP0	100 pF ± 5%, 0402 NP0 or 11 pF ± 5%, 0402 NP0 when part of optional filter	Murata GRM1555C series
C126		47 pF ± 5%, 0402 NP0	Murata GRM1555C series
C131	3.9 pF ± 0.25 pF, 0402 NP0	1.5 pF ± 0.25 pF, 0402 NP0	Murata GRM1555C series
L121	27 nH ± 5%, 0402 wire wound	12 nH ± 5%, 0402 wire wound	Murata LQW15 series
L122	22 nH ± 5%, 0402 wire wound	18 nH ± 5%, 0402 wire wound	Murata LQW15 series
L123	27 nH ± 5%, 0402 wire wound	12 nH ± 5%, 0402 wire wound	Murata LQW15 series
L124		12 nH ± 5%, 0402 wire wound	Murata LQW15 series
L125		2.7 nH ± 0.2nH, 0402 wire wound	Murata LQW15 series
L131	27 nH ± 5%, 0402 wire wound	12 nH ± 5%, 0402 wire wound	Murata LQW15 series
L132		18 nH ± 5%, 0402 wire wound	Murata LQW15 series
R171	56k Ω, 0	0402, 1%	Koa RK73 series
XTAL	26.0 MHz surfa	ce mount crystal	NDK, AT-41CD2

Table 19: Bill Of Materials for the Application Circuit

7.8 PCB Layout Recommendations

The top layer should be used for signal routing, and the open areas should be filled with metallization connected to ground using several vias.

The area under the chip is used for grounding and shall be connected to the bottom ground plane with several vias for good thermal performance and sufficiently low inductance to ground.

In the CC1100E EM reference designs ([3] and 0), 5 vias are placed inside the exposed

die attached pad. These vias should be "tented" (covered with solder mask) on the component side of the PCB to avoid migration of solder through the vias during the solder reflow process.

The solder paste coverage should not be 100%. If it is, out gassing may occur during the reflow process, which may cause defects (splattering, solder balling). Using "tented" vias reduces the solder paste coverage below



100%. See Figure 8 for top solder resist and top paste masks.

Each decoupling capacitor should be placed as close as possible to the supply pin it decouples. Each decoupling capacitor should be connected to the power line (or power plane) by separate vias. The best routing is from the power line (or power plane) to the decoupling capacitor and then to the **CC1100E** supply pin. Supply power filtering is very important.

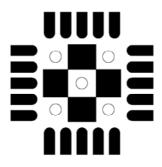
Each decoupling capacitor ground pad should be connected to the ground plane by separate vias. Direct connections between neighboring power pins will increase noise coupling and should be avoided unless absolutely necessary. Routing in the ground plane underneath the chip or the balun/RF matching circuit, or between the chip's ground vias and the decoupling capacitor's ground vias should

be avoided. This improves the grounding and ensures the shortest possible current return path.

The external components should ideally be as small as possible (0402 is recommended) and surface mount devices are highly recommended. Please note that components with different sizes than those specified may have differing characteristics.

Precaution should be used when placing the microcontroller in order to avoid noise interfering with the RF circuitry.

A **CC1100E** DK Development Kit with a fully assembled **CC1100E** EM Evaluation Module is available. It is strongly advised that this reference layout is followed very closely in order to get the best performance. The schematic, BOM and layout Gerber files are all available from the TI website ([3] and 0).



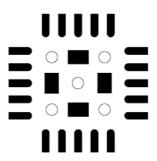


Figure 8: Left: Top Solder Resist Mask (Negative). Right: Top Paste Mask. Circles are Vias

8 Configuration Overview

The **CC1100E** can be configured to achieve optimum performance for many different applications. Configuration is done using the SPI interface. See Section 10 below for more description of the SPI interface. The following key parameters can be programmed:

- Power-down / power up mode
- Crystal oscillator power-up / power-down
- Receive / transmit mode
- RF channel selection
- Data rate
- Modulation format
- RX channel filter bandwidth
- RF output power
- Data buffering with separate 64-byte receive and transmit FIFOs

- Packet radio hardware support
- Forward Error Correction (FEC) with interleaving
- Data whitening
- Wake-On-Radio (WOR)

Details of each configuration register can be found in Section 29, starting on page 59.

Figure 9 shows a simplified state diagram that explains the main **CC1100E** states together with typical usage and current consumption. For detailed information on controlling the **CC1100E** state machine, and a complete state diagram, see Section 19, starting on page 45.

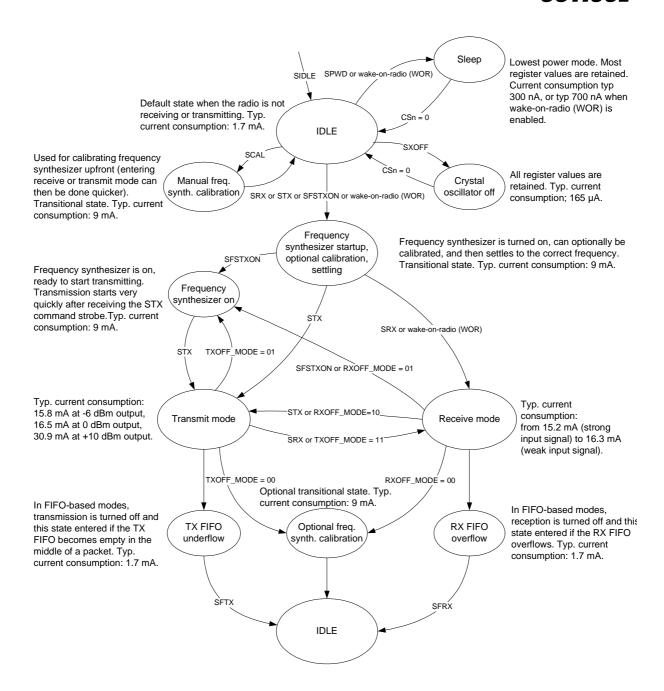


Figure 9: Simplified State Diagram, with Typical Current Consumption at 1.2 kBaud Data Rate and MDMCFG2.DEM_DCFILT_OFF=1 (current optimized). Frequency Band = 955 MHz

9 Configuration Software

The **CC1100E** can be configured using the SmartRF® Studio software [8]. The SmartRF® Studio software is highly recommended for obtaining optimum register settings, and for evaluating performance and functionality. A screenshot of the SmartRF® Studio user interface for the **CC1100E** is shown in Figure 10.

After chip reset, all the registers have default values as shown in the tables in Section 29. The optimum register setting might differ from the default value. After a reset all registers that shall be different from the default value therefore needs to be programmed through the SPI interface.

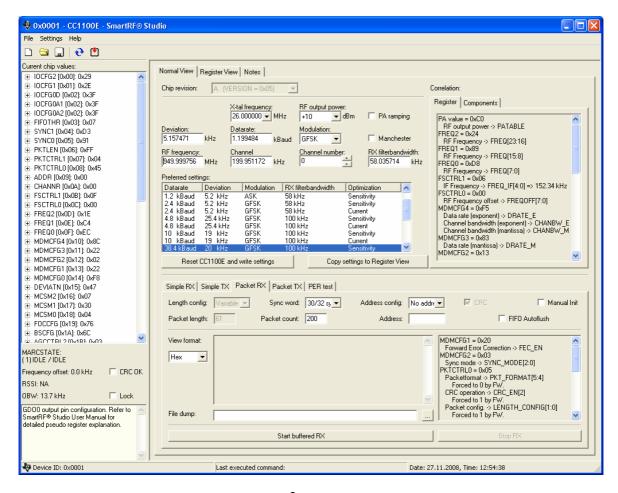


Figure 10: SmartRF® Studio [8] User Interface

10 4-wire Serial Configuration and Data Interface

The **CC1100E** is configured via a simple 4-wire SPI-compatible interface (SI, SO, SCLK and CSn) where the **CC1100E** is the slave. This interface is also used to read and write buffered data. All transfers on the SPI interface are done most significant bit first.

All transactions on the SPI interface start with a header byte containing an R/W; bit, a burst access bit (B), and a 6-bit address ($A_5 - A_0$).

The CSn pin must be kept low during transfers on the SPI bus. If CSn goes high during the

transfer of a header byte or during read/write from/to a register, the transfer will be cancelled. The timing for the address and data transfer on the SPI interface is shown in Figure 11 with reference to Table 20.

When CSn is pulled low, the MCU must wait until the **CC1100E** SO pin goes low before starting to transfer the header byte. This indicates that the crystal is running. Unless the chip was in the SLEEP or XOFF states, the SO pin will always go low immediately after taking CSn low.



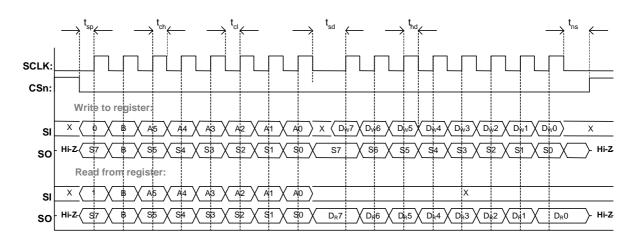


Figure 11: Configuration Registers Write and Read Operations

Parameter	Description	Min	Max	Units	
f _{SCLK}	SCLK frequency 100 ns delay inserted between address byte and data byte (s between address and data, and between each data byte (but	-	10	MHz	
	SCLK frequency, single access No delay between address and data byte		-	9	
	SCLK frequency, burst access No delay between address and data byte, or between data by	-	6.5		
t _{sp,pd}	CSn low to positive edge on SCLK, in power-or	down mode	150	-	μS
t _{sp}	CSn low to positive edge on SCLK, in active r	20	-	ns	
t _{ch}	Clock high	50	-	ns	
t _{cl}	Clock low	50	-	ns	
t _{rise}	Clock rise time		-	5	ns
t _{fall}	Clock fall time		-	5	ns
t _{sd}	Setup data (negative SCLK edge) to	Single access	55	-	ns
	positive edge on SCLK (t _{sd} applies between address and data bytes, and between data bytes)		76	-	
t _{hd}	Hold data after positive edge on SCLK		20	-	ns
t _{ns}	Negative edge on SCLK to CSn high.	20	-	ns	

Table 20: SPI Interface Timing Requirements

Note: The minimum $t_{sp,pd}$ figure in Table 20 can be used in cases where the user does not read the CHIP_RDYn signal. CSn low to positive edge on SCLK when the chip is woken from power-down depends on the start-up time of the crystal being used. The 150 μ s in Table 20 is the crystal oscillator start-up time measured on CC1100E EM reference designs (0 and 0) using crystal AT-41CD2 from NDK.



SWRS082 Page 26 of 92

10.1 Chip Status Byte

When the header byte, data byte, or command strobe is sent on the SPI interface, the chip status byte is sent by the *GC1100E* on the SO pin. The status byte contains key status signals, useful for the MCU. The first bit, s7, is the CHIP_RDYn signal; this signal must go low before the first positive edge of SCLK. The CHIP_RDYn signal indicates that the crystal is running.

Bits 6, 5, and 4 comprise the STATE value. This value reflects the state of the chip. The XOSC and power to the digital core are on in the IDLE state, but all other modules are in power down. The frequency and channel configuration should only be updated when the chip is in this state. The RX state will be active when the chip is in the receive mode. Likewise, TX is active when the chip is transmitting.

The last four bits (3:0) in the status byte contains FIFO_BYTES_AVAILABLE. For read operations (the R/W; bit in the header byte is set to 1), the FIFO_BYTES_AVAILABLE field contains the number of bytes available for reading from the RX FIFO. For write operations (the R/W; bit in the header byte is set to 0), the FIFO_BYTES_AVAILABLE field contains the number of bytes that can be ΤX FIFO. When written to the FIFO BYTES AVAILABLE=15, 15 or more bytes are available/free.

Table 21 gives a status byte summary.

Bits	Name	Description			
7	CHIP_RDYn	Stays high until power and crystal have stabilized. Should always be low when using the SPI interface.			
6:4	STATE[2:0]	Indicates	the current main state made	chine mode	
		Value	State	Description	
			IDLE	IDLE state (Also reported for some transitional states instead of SETTLING or CALIBRATE)	
			RX	Receive mode	
		010	TX	Transmit mode	
		011	FSTXON	Fast TX ready	
		100	CALIBRATE	Frequency synthesizer calibration is running	
			SETTLING	PLL is settling	
			RXFIFO_OVERFLOW	RX FIFO has overflowed. Read out any useful data, then flush the FIFO with SFRX	
		111	TXFIFO_UNDERFLOW	TX FIFO has underflowed. Acknowledge with SFTX	
3:0	FIFO_BYTES_AVAILABLE[3:0]	The number of bytes available in the RX FIFO or free bytes in the TX FIFO			

Table 21: Status Byte Summary

10.2 Register Access

The configuration registers on the **CC1100E** are located on SPI addresses from 0x00 to 0x2E. Table 39 on page 61 lists all configuration registers. It is highly recommended to use SmartRF® Studio [8] to generate optimum register settings. The detailed description of each register is found in Section 29.1 and 29.2, starting on page 64. All configuration registers can be both written to and read. The

R/W; bit controls if the register should be written to or read. When writing to registers, the status byte is sent on the SO pin each time a header byte or data byte is transmitted on the SI pin. When reading from registers, the status byte is sent on the SO pin each time a header byte is transmitted on the SI pin.

Registers with consecutive addresses can be accessed in an efficient way by setting the



burst bit (B) in the header byte. The address bits $(A_5 - A_0)$ set the start address in an internal address counter. This counter is incremented by one each new byte (every 8 clock pulses). The burst access is either a read or a write access and must be terminated by setting CSn high.

For register addresses in the range 0x30-0x3D, the burst bit is used to select between

status registers when burst bit is one, and between command strobes when burst bit is zero. See more in Section 10.3 below. Because of this, burst access is not available for status registers and they must be accessed one at a time. The status registers can only be read.

10.3 SPI Read

When reading register fields over the SPI interface while the register fields are updated by the radio hardware (e.g. MARCSTATE or TXBYTES), there is a small, but finite, probability that a single read from the register

is corrupt. As an example, the probability of any single read from TXBYTES being corrupt, assuming the maximum data rate is used, is approximately 80 ppm. Refer to the **CC1100E** Errata Note [5] for more details.

10.4 Command Strobes

Command Strobes may be viewed as single byte instructions to the **CC1100E**. By addressing a command strobe register, internal sequences will be started. These commands are used to disable the crystal oscillator, enable receive mode, enable wake-on-radio etc. The 13 command strobes are listed in Table 38 on page 60.

Note: An SIDLE strobe will clear all pending command strobes until IDLE state is reached. This means that if for example an SIDLE strobe is issued while the radio is in RX state, any other command strobes issued before the radio reaches IDLE state will be ignored.

The command strobe registers are accessed by transferring a single header byte (no data is being transferred). That is, only the R/W; bit, the burst access bit (set to 0), and the six

address bits (in the range 0x30 through 0x3D) are written. The R/W; bit can be either one or zero and will determine how the FIFO_BYTES_AVAILABLE field in the status byte should be interpreted.

When writing command strobes, the status byte is sent on the SO pin.

A command strobe may be followed by any other SPI access without pulling CSn high. However, if an SRES strobe is being issued, one will have to wait for SO to go low again before the next header byte can be issued as shown in Figure 12. The command strobes are executed immediately, with the exception of the SPWD and the SXOFF strobes that are executed when CSn goes high.

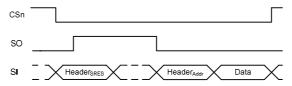


Figure 12: SRES Command Strobe

10.5 FIFO Access

The 64-byte TX FIFO and the 64-byte RX FIFO are accessed through the 0x3F address. When the R/W; bit is zero, the TX FIFO is accessed, and the RX FIFO is accessed when the R/W; bit is one.

The TX FIFO is write-only, while the RX FIFO is read-only.

The burst bit is used to determine if the FIFO access is a single byte access or a burst access. The single byte access method



SWRS082 Page 28 of 92

expects a header byte with the burst bit set to zero and one data byte. After the data byte, a new header byte is expected; hence, CSn can remain low. The burst access method expects one header byte and then consecutive data bytes until terminating the access by setting CSn high.

The following header bytes access the FIFOs:

0x3F: Single byte access to TX FIFO

0x7F: Burst access to TX FIFO

0xBF: Single byte access to RX FIFO

0xFF: Burst access to RX FIFO

When writing to the TX FIFO, the status byte (see Section 10.1) is output on SO for each new data byte as shown in Figure 11. This status byte can be used to detect TX FIFO underflow while writing data to the TX FIFO.

Note that the status byte contains the number of bytes free before writing the byte in progress to the TX FIFO. When the last byte that fits in the TX FIFO is transmitted on SI, the status byte received concurrently on SO will indicate that one byte is free in the TX FIFO.

The TX FIFO may be flushed by issuing a SFTX command strobe. Similarly, a SFRX command strobe will flush the RX FIFO. A SFTX or SFRX command strobe can only be issued in the IDLE, TXFIFO_UNDERFLOW, or RXFIFO_OVERFLOW states. Both FIFOs are flushed when going to the SLEEP state.

Figure 13 gives a brief overview of different register access types possible.

10.6 PATABLE Access

The 0x3E address is used to access the PATABLE, which is used for selecting PA power control settings. The SPI expects up to eight data bytes after receiving the address. By programming the PATABLE, controlled PA power ramp-up and ramp-down can be achieved, as well as ASK modulation shaping for reduced bandwidth. See SmartRF® Studio [8] for recommended shaping / PA ramping sequences. See also Section 24 on page 52 for details on output power programming.

The PATABLE is an 8-byte table that defines the PA control settings to use for each of the eight PA power values (selected by the 3-bit value FRENDO.PA_POWER). The table is written and read from the lowest setting (0) to the highest (7), one byte at a time. An index counter is used to control the access to the table. This counter is incremented each time a byte is read or written to the table, and set to the lowest index when CSn is high. When the

highest value is reached the counter restarts at zero.

The access to the PATABLE is either single byte or burst access depending on the burst bit. When using burst access the index counter will count up; when reaching 7 the counter will restart at 0. The R/W; bit controls whether the access is a read or a write access.

If one byte is written to the PATABLE and this value is to be read out, CSn must be set high before the read access in order to set the index counter back to zero.

Note that the content of the PATABLE is lost when entering the SLEEP state, except for the first byte (index 0).

Please referr to Design Note DN501 [17] for more information

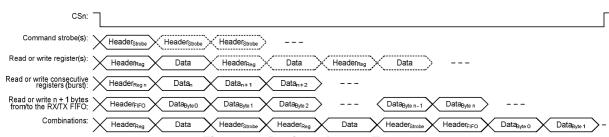


Figure 13: Register Access Types



SWRS082 Page 29 of 92



11 Microcontroller Interface and Pin Configuration

In a typical system, the **CC1100E** will interface to a microcontroller. This microcontroller must be able to:

• Program the **CC1100E** into different modes

Read and write buffered data

 Read back status information via the 4-wire SPI-bus configuration interface (SI, SO, SCLK and CSn)

11.1 Configuration Interface

The microcontroller uses four I/O pins for the SPI configuration interface (SI, SO, SCLK and

CSn). The SPI is described in Section 10 on page 25.

11.2 General Control and Status Pins

The **CC1100E** has two dedicated configurable pins (GDO0 and GDO2) and one shared pin (GDO1) that can output internal status information useful for control software. These pins can be used to generate interrupts on the MCU. See Section 26 page 54 for more details on the signals that can be programmed.

GDO1 is shared with the SO pin in the SPI interface. The default setting for GDO1/SO is 3-state output. By selecting any other of the programming options, the GDO1/SO pin will become a generic pin. When CSn is low, the pin will always function as a normal SO pin.

In the synchronous and asynchronous serial modes, the GDO0 pin is used as a serial TX data input pin while in transmit mode.

The GDO0 pin can also be used for an on-chip analog temperature sensor. By measuring the voltage on the GDO0 pin with an external ADC, the temperature can be calculated. Specifications for the temperature sensor are found in Section 4.7 on page 15. With default PTEST register setting (0x7F), the temperature sensor output is only available if the frequency synthesizer is enabled (e.g. the MANCAL, FSTXON, RX, and TX states). It is necessary to write 0xBF to the PTEST register to use the analog temperature sensor in the IDLE state. Before leaving the IDLE state, the PTEST register should be restored to its default value (0x7F).

11.3 Optional Radio Control Feature

The **CC1100E** has an optional way of controlling the radio by reusing SI, SCLK, and CSn from the SPI interface. This feature allows for a simple three-pin control of the major states of the radio: SLEEP, IDLE, RX, and TX. This optional functionality is enabled with the MCSMO.PIN_CTRL_EN configuration bit.

State changes are commanded as follows:

- If CSn is high, the SI and SCLK are set to the desired state according to Table 22.
- If CSn goes low, the state of SI and SCLK is latched and a command strobe is generated internally according to the pin configuration.

It is only possible to change state with the latter functionality. That means that for instance RX will not be restarted if SI and

SCLK are set to RX and CSn toggles. When CSn is low the SI and SCLK has normal SPI functionality.

All pin control command strobes are executed immediately except the SPWD strobe. The SPWD strobe is delayed until CSn goes high.

CSn	SCLK	SI	Function
1	Χ	Χ	Chip unaffected by SCLK/SI
\downarrow	0	0	Generates SPWD strobe
\downarrow	0	1	Generates STX strobe
\downarrow	1	0	Generates SIDLE strobe
\downarrow	1	1	Generates SRX strobe
0	SPI mode	SPI mode	SPI mode (wakes up into IDLE if in SLEEP/XOFF)

Table 22: Optional Pin Control Coding



12 Data Rate Programming

The data rate used when transmitting, or the data rate expected in receive is programmed by the MDMCFG3.DRATE_M and the MDMCFG4.DRATE_E configuration registers. The data rate is given by the formula below. As the formula shows, the programmed data rate depends on the crystal frequency.

$$R_{DATA} = \frac{\left(256 + DRATE_M\right) \cdot 2^{DRATE_E}}{2^{28}} \cdot f_{XOSC}$$

The following approach can be used to find suitable values for a given data rate:

$$DRATE_E = \left[log_2 \left(\frac{R_{DATA} \cdot 2^{20}}{f_{XOSC}} \right) \right]$$

$$DRATE_M = \frac{R_{DATA} \cdot 2^{28}}{f_{XOSC} \cdot 2^{DRATE_E}} - 256$$

If DRATE_M is rounded to the nearest integer and becomes 256, increment DRATE_E and use DRATE_M = 0.

The data rate can be set from 0.8 kBaud to 500 kBaud with the minimum step size according to Table 23 below.

Min Data Rate [kBaud]	Typical Data Rate [kBaud]	Max Data Rate [kBaud]	Data rate Step Size [kBaud]
0.8	1.2 / 2.4	3.17	0.0062
3.17	4.8	6.35	0.0124
6.35	9.6	12.7	0.0248
12.7	19.6	25.4	0.0496
25.4	38.4	50.8	0.0992
50.8	76.8	101.6	0.1984
101.6	153.6	203.1	0.3967
203.1	250	406.3	0.7935
406.3	500	500	1.5869

Table 23: Data Rate Step Size

13 Receiver Channel Filter Bandwidth

In order to meet different channel width requirements, the receiver channel filter is programmable. The MDMCFG4.CHANBW_E and MDMCFG4.CHANBW_M configuration registers control the receiver channel filter bandwidth, which scales with the crystal oscillator frequency.

The following formula gives the relation between the register settings and the channel filter bandwidth:

$$BW_{channel} = \frac{f_{XOSC}}{8 \cdot (4 + CHANBW_{M}) \cdot 2^{CHANBW_{E}}}$$

Table 24 lists the channel filter bandwidths supported by the **CC1100E**.

For best performance, the channel filter bandwidth should be selected so that the signal bandwidth occupies at most 80% of the channel filter bandwidth. The channel centre tolerance due to crystal inaccuracy should also be subtracted from the channel filter bandwidth. The following example illustrates this:

With the channel filter bandwidth set to 500 kHz, the signal should stay within 80% of

500 kHz, which is 400 kHz. Assuming 955 MHz frequency and ±20 ppm frequency uncertainty for both the transmitting device and the receiving device, the total frequency uncertainty is ±40 ppm of 955 MHz, which is ±38.2 kHz. If the whole transmitted signal bandwidth is to be received within 400 kHz, the transmitted signal bandwidth should be maximum 400 kHz – 2·38.2 kHz, which is 323.6 kHz.

By compensating for a frequency offset between the transmitter and the receiver, the filter bandwidth can be reduced and the sensitivity can be improved, see more in DN005 [16] and in Section 14.1.

MDMCFG4.	MDMCFG4.CHANBW_E			
CHANBW_M	00	01	10	11
00	812	406	203	102
01	650	325	162	81
10	541	270	135	68
11	464	232	116	58

Table 24: Channel Filter Bandwidths [kHz] (assuming a 26 MHz crystal)



14 Demodulator, Symbol Synchronizer, and Data Decision

The **CC1100E** contains an advanced and highly configurable demodulator. Channel filtering and frequency offset compensation is performed digitally. To generate the RSSI level

(see Section 17.3 for more information), the signal level in the channel is estimated. Data filtering is also included for enhanced performance.

14.1 Frequency Offset Compensation

The **CC1100E** has a very fine frequency resolution (see Table 13). This feature can be used to compensate for frequency offset and drift.

When using 2-FSK, GFSK, or MSK modulation, the demodulator will compensate for the offset between the transmitter and receiver frequency within certain limits, by estimating the centre of the received data. The frequency offset compensation configuration is controlled from the FOCCFG register. By compensating for a large frequency offset between the transmitter and the receiver, the sensitivity can be improved, see DN005 [16].

The tracking range of the algorithm is selectable as fractions of the channel bandwidth with the FOCCFG.FOC_LIMIT configuration register.

If the FOCCFG.FOC_BS_CS_GATE bit is set, the offset compensator will freeze until carrier sense asserts. This may be useful when the radio is in RX for long periods with no traffic,

14.2 Bit Synchronization

The bit synchronization algorithm extracts the clock from the incoming symbols. The algorithm requires that the expected data rate is programmed as described in Section 12 on

14.3 Byte Synchronization

Byte synchronization is achieved by a continuous sync word search. The sync word is a 16 bit configurable field (can be repeated to get a 32 bit) that is automatically inserted at the start of the packet by the modulator in transmit mode. The MSB in the sync word is sent first. The demodulator uses this field to find the byte boundaries in the stream of bits. The sync word will also function as a system identifier; since only packets with the correct predefined sync word will be received if the sync word detection in RX is enabled in register MDMCFG2 (see Section 17.1). The sync word detector correlates against the user-configured 16 or 32 bit sync word. The

since the algorithm may drift to the boundaries when trying to track noise.

The tracking loop has two gain factors, which affects the settling time and noise sensitivity of the algorithm. FOCCFG.FOC_PRE_K sets the gain before the sync word is detected, and FOCCFG.FOC_POST_K selects the gain after the sync word has been found.

Note: Frequency offset compensation is not supported for ASK or OOK modulation.

The estimated frequency offset value is available in the FREQEST status register. This can be used for permanent frequency offset compensation. By writing the value from FREQEST into FSCTRLO.FREQOFF, the frequency synthesizer will automatically be adjusted according to the estimated frequency offset. More details regarding this permanent frequency compensation algorithm can be found in DN015 [12].

page 31. Re-synchronization is performed continuously to adjust for error in the incoming symbol rate.

correlation threshold can be set to 15/16, 16/16, or 30/32 bits match. The sync word can be further qualified using the preamble quality indicator mechanism described below and/or a carrier sense condition. The sync word is configured through the SYNC1 and SYNC0 registers.

In order to make false detections of sync words less likely, a mechanism called preamble quality indication (PQI) can be used to qualify the sync word. A threshold value for the preamble quality must be exceeded in order for a detected sync word to be accepted. See Section 17.2 on page 39 for more details.

15 Packet Handling Hardware Support

The **CC1100E** has built-in hardware support for packet oriented radio protocols.

In transmit mode, the packet handler can be configured to add the following elements to the packet stored in the TX FIFO:

- A programmable number of preamble bytes
- A two byte synchronization (sync) word. Can be duplicated to give a 4-byte sync word (recommended). It is not possible to only insert preamble or only insert a sync word
- A CRC checksum computed over the data field.

The recommended setting is 4-byte preamble and 4-byte sync word, except for 500 kBaud data rate where the recommended preamble length is 8 bytes. In addition, the following can be implemented on the data field and the optional 2-byte CRC checksum:

- Whitening of the data with a PN9 sequence
- Forward Error Correction (FEC) by the use of interleaving and coding of the data (convolutional coding)

In receive mode, the packet handling support will de-construct the data packet by implementing the following (if enabled):

15.1 Data Whitening

From a radio perspective, the ideal over the air data are random and DC free. This results in the smoothest power distribution over the occupied bandwidth. This also gives the regulation loops in the receiver uniform operation conditions (no data dependencies).

Real data often contain long sequences of zeros and ones. In these cases, performance can be improved by whitening the data before transmitting, and de-whitening the data in the receiver.

- Preamble detection
- Sync word detection
- CRC computation and CRC check
- One byte address check
- Packet length check (length byte checked against a programmable maximum length)
- De-whitening
- · De-interleaving and decoding

Optionally, two status bytes (see Table 25 and Table 26) with RSSI value, Link Quality Indication, and CRC status can be appended in the RX FIFO.

Bit	Field Name	Description
7:0	RSSI	RSSI value

Table 25: Received Packet Status Byte 1 (first byte appended after the data)

Bit	Field Name	Description
7	CRC_OK	1: CRC for received data OK (or CRC disabled)
		0: CRC error in received data
6:0	LQI	Indicating the link quality

Table 26: Received Packet Status Byte 2 (second byte appended after the data)

Note: Register fields that control the packet handling features should only be altered when **CC1100E** is in the IDLE state.

With the CC1100E. this can done automatically. By settina PKTCTRL0.WHITE_DATA=1, all data, except the preamble and the sync word will be XORed with a 9-bit pseudo-random (PN9) sequence before being transmitted. This is shown in Figure 14. At the receiver end, the data are XOR-ed with the same pseudorandom sequence. In this way, the whitening is reversed, and the original data appear in the receiver. The PN9 sequence is initialized to all

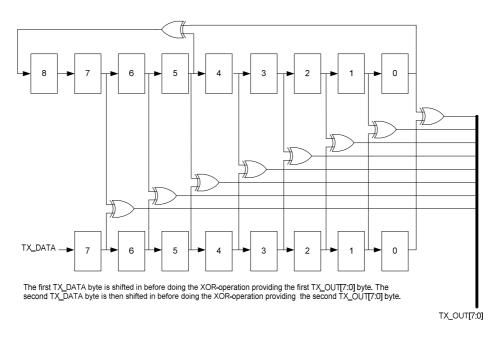


Figure 14: Data Whitening in TX Mode

15.2 Packet Format

The format of the data packet can be configured and consists of the following items (see Figure 15):

- Preamble
- Synchronization word

- Optional length byte
- Optional address byte
- Payload
- Optional 2 byte CRC

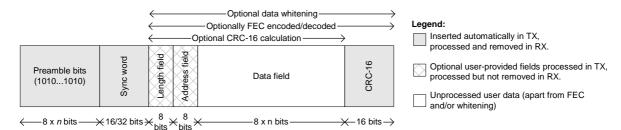


Figure 15: Packet Format

The preamble pattern is an alternating sequence of ones and zeros (10101010...). The minimum length of the preamble is programmable through the value MDMCFG1.NUM PREAMBLE. When enabling TX, the modulator will start transmitting the preamble. When the programmed number of preamble bytes has been transmitted, the modulator will send the sync word and then data from the TX FIFO if data is available. If the TX FIFO is empty, the modulator will continue to send preamble bytes until the first byte is written to the TX FIFO. The modulator will then send the sync word and then the data bytes.

The synchronization word is a two-byte value set in the SYNC1 and SYNC0 registers. The sync word provides byte synchronization of the incoming packet. A one-byte sync word can be emulated by setting the SYNC1 value to the preamble pattern. It is also possible to emulate a 32 bit sync word by setting MDMCFG2.SYNC_MODE to 3 or 7. The sync word will then be repeated twice.

The **CC1100E** supports both constant packet length protocols and variable length protocols. Variable or fixed packet length mode can be used for packets up to 255 bytes. For longer





packets, infinite packet length mode must be used.

Fixed packet length mode is selected by setting PKTCTRL0.LENGTH_CONFIG=0. The desired packet length is set by the PKTLEN register.

In variable packet length mode, PKTCTRL0.LENGTH_CONFIG=1, the packet length is configured by the first byte after the sync word. The packet length is defined as the payload data, excluding the length byte and the optional CRC. The PKTLEN register is used to set the maximum packet length allowed in RX. Any packet received with a length byte with a value greater than PKTLEN will be discarded.

With PKTCTRLO.LENGTH_CONFIG=2, the packet length is set to infinite and transmission and reception will continue until turned off manually. As described in the next section, this can be used to support packet formats with different length configuration than natively supported by the **CC1100E**. One should make sure that TX mode is not turned off during the transmission of the first half of any byte. Refer to the **CC1100E** Errata Note [5] for more details.

Note: The minimum packet length supported (excluding the optional length byte and CRC) is one byte of payload data.

15.2.1 Arbitrary Length Field Configuration

The packet length register, PKTLEN, can be reprogrammed during receive and transmit. In combination with fixed packet length mode (PKTCTRLO.LENGTH_CONFIG=0), this opens the possibility to have a different length field configuration than supported for variable length packets (in variable packet length mode the length byte is the first byte after the sync word). At the start of reception, the packet length is set to a large value. The MCU reads out enough bytes to interpret the length field in the packet. Then the PKTLEN value is set according to this value. The end of packet will occur when the byte counter in the packet

handler is equal to the PKTLEN register. Thus, the MCU must be able to program the correct length, before the internal counter reaches the packet length.

15.2.2 Packet Length > 255

The packet automation control register, PKTCTRL0, can be reprogrammed during TX and RX. This opens the possibility to transmit and receive packets that are longer than 256 bytes and still be able to use the packet handling hardware support. At the start of the packet, the infinite packet length mode (PKTCTRL0.LENGTH_CONFIG=2) must be active. On the TX side, the PKTLEN register is set to mod (length, 256). On the RX side the MCU reads out enough bytes to interpret the length field in the packet and sets the PKTLEN register to mod (length, 256). When less than 256 bytes remains of the packet, the MCU disables infinite packet length mode and activates fixed packet length mode. When the internal byte counter reaches the PKTLEN value, the transmission or reception ends (the radio enters the state determined TXOFF MODE or RXOFF MODE). Automatic CRC appending/checking can also be used (by setting PKTCTRL0.CRC EN=1).

When for example a 600-byte packet is to be transmitted, the MCU should do the following (see also Figure 16)

- Set PKTCTRL0.LENGTH_CONFIG=2.
- Pre-program the PKTLEN register to mod (600, 256) = 88.
- Transmit at least 345 bytes (600 255), for example by filling the 64-byte TX FIFO six times (384 bytes transmitted).
- Set PKTCTRL0.LENGTH CONFIG=0.
- The transmission ends when the packet counter reaches 88. A total of 600 bytes are transmitted.



Internal byte counter in packet handler counts from 0 to 255 and then starts at 0 again

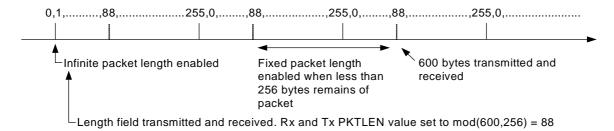


Figure 16: Packet Length > 255

15.3 Packet Filtering in Receive Mode

The **CC1100E** supports three different types of packet-filtering; address filtering, maximum length filtering, and CRC filtering.

15.3.1 Address Filtering

Setting PKTCTRL1.ADR_CHK to any other value than zero enables the packet address filter. The packet handler engine will compare the destination address byte in the packet with the programmed node address in the ADDR register and the 0x00 broadcast address when PKTCTRL1.ADR_CHK=10 or both the 0x00 and 0xFF broadcast addresses when PKTCTRL1.ADR_CHK=11. If the received address matches a valid address, the packet is received and written into the RX FIFO. If the address match fails, the packet is discarded and receive mode restarted (regardless of the MCSM1.RXOFF_MODE setting).

If the received address matches a valid address when using infinite packet length mode and address filtering is enabled, 0xFF will be written into the RX FIFO followed by the address byte and then the payload data.

15.3.2 Maximum Length Filtering

In variable packet length mode, PKTCTRLO.LENGTH_CONFIG=1, the PKTLEN.PACKET_LENGTH register value is used to set the maximum allowed packet

15.4 Packet Handling in Transmit Mode

The payload that is to be transmitted must be written into the TX FIFO. The first byte written must be the length byte when variable packet length is enabled. The length byte has a value equal to the payload of the packet (including the optional address byte). If address recognition is enabled on the receiver, the

length. If the received length byte has a larger value than this, the packet is discarded and receive mode restarted (regardless of the MCSM1.RXOFF_MODE setting).

15.3.3 CRC Filtering

The filtering of a packet when CRC check fails is enabled by setting PKTCTRL1.CRC_AUTOFLUSH=1. The CRC auto flush function will flush the entire RX FIFO if the CRC check fails. After auto flushing the RX FIFO, the next state depends on the MCSM1.RXOFF MODE setting.

When using the auto flush function, the maximum packet length is 63 bytes in variable packet length mode and 64 bytes in fixed packet length mode. Note that when PKTCTRL1.APPEND_STATUS is enabled, the maximum allowed packet length is reduced by two bytes in order to make room in the RX FIFO for the two status bytes appended at the end of the packet. Since the entire RX FIFO is flushed when the CRC check fails, the previously received packet must be read out of the FIFO before receiving the current packet. The MCU must not read from the current packet until the CRC has been checked as OK.

second byte written to the TX FIFO must be the address byte.

If fixed packet length is enabled, the first byte written to the TX FIFO should be the address (assuming the receiver uses address recognition).



The modulator will first send the programmed number of preamble bytes. If data is available in the TX FIFO, the modulator will send the two-byte (optionally 4-byte) sync word followed by the payload in the TX FIFO. If CRC is enabled, the checksum is calculated over all the data pulled from the TX FIFO, and the result is sent as two extra bytes following the payload data. If the TX FIFO runs empty before the complete packet has been transmitted. radio will the enter TXFIFO UNDERFLOW state. The only way to exit this state is by issuing an SFTX strobe.

15.5 Packet Handling in Receive Mode

In receive mode, the demodulator and packet handler will search for a valid preamble and the sync word. When found, the demodulator has obtained both bit and byte synchronism and will receive the first payload byte.

If FEC/Interleaving is enabled, the FEC decoder will start to decode the first payload byte. The interleaver will de-scramble the bits before any other processing is done to the data

If whitening is enabled, the data will be dewhitened at this stage.

When variable packet length mode is enabled, the first byte is the length byte. The packet handler stores this value as the packet length and receives the number of bytes indicated by

15.6 Packet Handling in Firmware

When implementing a packet oriented radio protocol in firmware, the MCU needs to know when a packet has been received/transmitted. Additionally, for packets longer than 64 bytes, the RX FIFO needs to be read while in RX and the TX FIFO needs to be refilled while in TX. This means that the MCU needs to know the number of bytes that can be read from or written to the RX FIFO and TX FIFO respectively. There are two possible solutions to get the necessary status information:

a) Interrupt Driven Solution

The GDO pins can be used in both RX and TX to give an interrupt when a sync word has been received/transmitted or when a complete packet has been received/transmitted by setting IOCFGx.GDOx_CFG=0x06. In addition, there are two configurations for the IOCFGx.GDOx_CFG register that can be used as an interrupt source to provide information on how many bytes are in the RX FIFO and

Writing to the TX FIFO after it has underflowed will not restart TX mode.

If whitening is enabled, everything following the sync words will be whitened. This is done before the optional FEC/Interleave stage. Whitening is enabled by setting PKTCTRL0.WHITE_DATA=1.

If FEC/Interleaving is enabled, everything following the sync words will be scrambled by the interleave and FEC encoded before being modulated. FEC is enabled by setting MDMCFG1.FEC_EN=1.

the length byte. If fixed packet length mode is used, the packet handler will accept the programmed number of bytes.

Next, the packet handler optionally checks the address and only continues the reception if the address matches. If automatic CRC check is enabled, the packet handler computes CRC and matches it with the appended CRC checksum.

At the end of the payload, the packet handler will optionally write two extra packet status bytes (see Table 25 and Table 26) that contain CRC status, link quality indication, and RSSI value.

The TΧ FIFO respectively. IOCFGx.GDOx_CFG=0x00 and the IOCFGx.GDOx_CFG=0x01 configurations are associated with the RX FIFO while the the $IOCFGx.GDOx_CFG=0x02$ and IOCFGx.GDOx CFG=0x03 configurations are associated with the TX FIFO. See Table 36 for more information.

b) SPI Polling

The PKTSTATUS register can be polled at a given rate to get information about the current GDO2 and GDO0 values respectively. The RXBYTES and TXBYTES registers can be polled at a given rate to get information about the number of bytes in the RX FIFO and TX FIFO respectively. Alternatively, the number of bytes in the RX FIFO and TX FIFO can be read from the chip status byte returned on the MISO line each time a header byte, data byte, or command strobe is sent on the SPI bus.





It is recommended to employ an interrupt driven solution since high rate SPI polling reduces the RX sensitivity. Furthermore, as explained in Section 10.3 and the **CC1100E** Errata Note [5], when using SPI polling, there is a small, but finite, probability that a single

read from registers PKTSTATUS, RXBYTES and TXBYTES is being corrupt. The same is the case when reading the chip status byte.

Refer to the TI website for SW examples ([9] and [10]).

16 Modulation Formats

The **CC1100E** supports amplitude, frequency, and phase shift modulation formats. The desired modulation format is set in the MDMCFG2.MOD_FORMAT register.

Optionally, the data stream can be Manchester coded by the modulator and decoded by the demodulator. This option is enabled by setting MDMCFG2.MANCHESTER EN=1.

Note: Manchester encoding is not supported at the same time as using the FEC/Interleaver option or when using MSK modulation.

16.1 Frequency Shift Keying

The **CC1100E** has the possibility to use Gaussian shaped 2-FSK (GFSK). The 2-FSK signal is then shaped by a Gaussian filter with BT = 1, producing a GFSK modulated signal. This spectrum-shaping feature improves adjacent channel power (ACP) and occupied bandwidth.

In 'true' 2-FSK systems with abrupt frequency shifting, the spectrum is inherently broad. By making the frequency shift 'softer', the spectrum can be made significantly narrower. Thus, higher data rates can be transmitted in the same bandwidth using GFSK.

When 2-FSK/GFSK modulation is used, the DEVIATN register specifies the expected frequency deviation of incoming signals in RX and should be the same as the TX deviation for demodulation to be performed reliably and robustly.

The frequency deviation is programmed with the DEVIATION_M and DEVIATION_E values in the DEVIATN register. The value has an exponent/mantissa form, and the resultant deviation is given by:

$$f_{dev} = \frac{f_{xosc}}{2^{17}} \cdot (8 + DEVIATION _M) \cdot 2^{DEVIATION_E}$$

The symbol encoding is shown in Table 27.

Format	Symbol	Coding
2-FSK/GFSK	'0'	Deviation
	'1'	+ Deviation

Table 27: Symbol Encoding for 2-FSK/GFSK Modulation

16.2 Minimum Shift Keying

When using MSK¹, the complete transmission (preamble, sync word, and payload) will be MSK modulated.

Phase shifts are performed with a constant transition time. The fraction of a symbol period used to change the phase can be modified with the DEVIATN.DEVIATION_M setting.

When using MSK, Manchester encoding/decoding should be disabled by setting MDMCFG2 MANCHESTER_EN = 0

The MSK modulation format implemented in the **CC1100E** inverts the sync word and data compared to e.g. signal generators.

TEXAS INSTRUMENTS

SWRS082 Page 38 of 92

This is equivalent to changing the shaping of the symbol. The DEVIATN register setting has no effect in RX when using MSK.

¹ Identical to offset QPSK with half-sine shaping (data coding may differ).

16.3 Amplitude Modulation

The **CC1100E** supports two different forms of amplitude modulation: On-Off Keying (OOK) and Amplitude Shift Keying (ASK).

OOK modulation simply turns the PA on or off to modulate ones and zeros respectively.

The ASK variant supported by the **CC1100E** allows programming of the modulation depth (the difference between 1 and 0), and shaping of the pulse amplitude. Pulse shaping

produces a more bandwidth constrained output spectrum.

When using OOK/ASK, the AGC settings from the SmartRF® Studio [8] preferred FSK/MSK settings are not optimum. DN022 [15] give guidelines on how to find optimum OOK/ASK settings from the preferred settings in SmartRF® Studio [8]. The DEVIATN register setting has no effect in either TX or RX when using OOK/ASK.

17 Received Signal Qualifiers and Link Quality Information

The **CC1100E** has several qualifiers that can be used to increase the likelihood that a valid sync word is detected:

- Sync Word Qualifier
- · Preamble Quality Threshold

- RSSI
- Carrier Sense
- Clear Channel Assessment
- Link Quality Indicator

17.1 Sync Word Qualifier

If sync word detection in RX is enabled in the MDMCFG2 register, the **CC1100F** will not start filling the RX FIFO and perform the packet filtering described in Section 15.3 before a valid sync word has been detected. The sync word qualifier mode is set by MDMCFG2.SYNC_MODE and is summarized in Table 28. Carrier sense in Table 28 is described in Section 17.4.

MDMCFG2.	Some Word Qualifier Made
SYNC_MODE	Sync Word Qualifier Mode
000	No preamble/sync
001	15/16 sync word bits detected
010	16/16 sync word bits detected
011	30/32 sync word bits detected
100	No preamble/sync + carrier sense above threshold
101	15/16 + carrier sense above threshold
110	16/16 + carrier sense above threshold
111	30/32 + carrier sense above threshold

Table 28: Sync Word Qualifier Mode

17.2 Preamble Quality Threshold (PQT)

The Preamble Quality Threshold (PQT) sync word qualifier adds the requirement that the received sync word must be preceded with a preamble with a quality above the programmed threshold.

Another use of the preamble quality threshold is as a qualifier for the optional RX termination timer. See Section 19.7 on page 49 for details.

The preamble quality estimator increases an internal counter by one each time a bit is received that is different from the previous bit, and decreases the counter by eight each time a bit is received that is the same as the last bit.

The threshold is configured with the register field PKTCTRL1.PQT. A threshold of 4·PQT for this counter is used to gate sync word detection. By setting the value to zero, the preamble quality qualifier of the sync word is disabled.

A "Preamble Quality Reached" signal can be observed on one of the GDO pins by setting IOCFGx.GDOx_CFG=8. It is also possible to determine if preamble quality is reached by checking the PQT_REACHED bit in the PKTSTATUS register. This signal / bit asserts when the received signal exceeds the PQT.



17.3 RSSI

The RSSI value is an estimate of the signal power level in the chosen channel. This value is based on the current gain setting in the RX chain and the measured signal level in the channel.

In RX mode, the RSSI value can be read continuously from the RSSI status register until the demodulator detects a sync word (when sync word detection is enabled). At that point the RSSI readout value is frozen until the next time the chip enters the RX state.

Note: It takes some time from the radio enters RX mode until a valid RSSI value is present in the RSSI register. Please see DN505 [13] for details on how the RSSI response time can be estimated.

The RSSI value is given in dBm with a $\frac{1}{2}$ dB resolution. The RSSI update rate, f_{RSSI} , depends on the receiver filter bandwidth (BW_{channel} is defined in Section 13) and AGCCTRL0.FILTER LENGTH.

$$f_{RSSI} = \frac{2 \cdot BW_{channel}}{8 \cdot 2^{FILTER} - LENGTH}$$

If PKTCTRL1.APPEND_STATUS is enabled, the last RSSI value of the packet is automatically added to the first byte appended after the payload.

The RSSI value read from the RSSI status register is a 2's complement number. The following procedure can be used to convert the RSSI reading to an absolute power level (RSSI_dBm)

- 1) Read the RSSI status register
- 2) Convert the reading from a hexadecimal number to a decimal number (RSSI_dec)
- 3) If RSSI_dec ≥ 128 then RSSI_dBm = (RSSI_dec 256)/2 RSSI_offset
- 4) Else if RSSI_dec < 128 then RSSI_dBm = (RSSI_dec)/2 - RSSI_offset

Table 29 gives typical values for the RSSI_offset. Figure 17 and Figure 18 show typical plots of RSSI readings as a function of input power level for different data rates.

Data rate [kBaud]	RSSI_offset [dB], 490 MHz	RSSI_offset [dB], 955 MHz
1.2	75	75
38.4	75	75
76.8	N/A	79
250	79	N/A

Table 29: Typical RSSI_offset Values



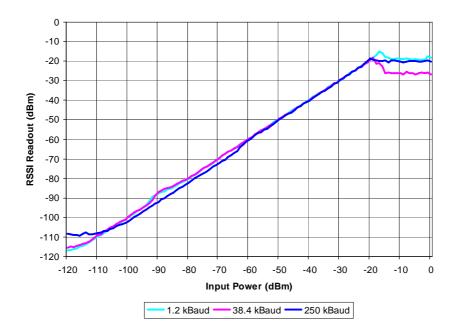


Figure 17: Typical RSSI Value vs. Input Power Level for Different Data Rates at 480 MHz

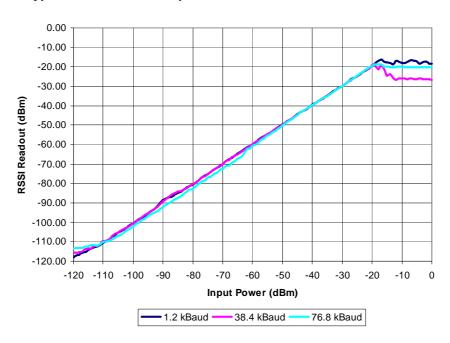


Figure 18: Typical RSSI Value vs. Input Power Level for Different Data Rates at 955 MHz

17.4 Carrier Sense (CS)

Carrier sense (CS) is used as a sync word qualifier and for Clear Channel Assessment (see Section 17.5). CS can be asserted based on two conditions which can be individually adjusted:

 CS is asserted when the RSSI is above a programmable absolute threshold, and deasserted when RSSI is below the same

- threshold (with hysteresis). See more in Section 17.4.1.
- CS is asserted when the RSSI has increased with a programmable number of dB from one RSSI sample to the next, and de-asserted when RSSI has decreased with the same number of dB. This setting is not dependent on the absolute signal



SWRS082 Page 41 of 92

level and is thus useful to detect signals in environments with time varying noise floor. See more in Section 17.4.2.

Carrier sense can be used as a sync word qualifier that requires the signal level to be higher than the threshold for a sync word search to be performed and is set by setting MDMCFG2 The carrier sense signal can be observed on one of the GDO pins by setting IOCFGx.GDOx_CFG=14 and in the status register bit PKTSTATUS.CS.

Other uses of Carrier sense include the TX-if-CCA function (see Section 17.5 on page 43) and the optional fast RX termination (see Section 19.7 on page 49).

CS can be used to avoid interference from other RF sources in the ISM bands.

17.4.1 CS Absolute Threshold

The absolute threshold related to the RSSI value depends on the following register fields:

- AGCCTRL2.MAX LNA GAIN
- AGCCTRL2.MAX_DVGA_GAIN
- AGCCTRL1.CARRIER_SENSE_ABS_THR
- AGCCTRL2.MAGN_TARGET

For given AGCCTRL2.MAX_LNA_GAIN and AGCCTRL2.MAX_DVGA_GAIN settings, the absolute threshold can be adjusted ±7 dB in steps of 1 dB using CARRIER SENSE ABS THR.

The MAGN_TARGET setting is a compromise between blocker tolerance/selectivity and sensitivity. The value sets the desired signal level in the channel into the demodulator. Increasing this value reduces the headroom for blockers, and therefore close-in selectivity. It is strongly recommended to use SmartRF® [8] to generate the MAGN TARGET setting. Table 30 and Table 31 show the typical RSSI readout values at the CS threshold at 2.4 kBaud and 250 kBaud respectively. The CARRIER_SENSE_ABS_THR=0 (0 dB) and MAGN_TARGET=3 (33 dB) have been used. For other data rates, the user must generate similar tables to find the CS absolute threshold.

		N	MAX_DVGA_GAIN[1:0]		
		00	01	10	11
	000	-97.5	-91.5	-85.5	-79.5
[0	001	-94	-88	-82.5	-76
N[2:	010	-90.5	-84.5	-78.5	-72.5
GAI	011	-88	-82.5	-76.5	-70.5
MAX_LNA_GAIN[2:0]	100	-85.5	-80	-73.5	-68
4X_I	101	-84	-78	-72	-66
Ŋ.	110	-82	-76	-70	-64
	111	-79	-73.5	-67	-61

Table 30: Typical RSSI Value in dBm at CS Threshold with Default MAGN_TARGET at 2.4 kBaud, 955 MHz

		MAX_DVGA_GAIN[1:0]			
		00	01	10	11
	000	-90.5	-84.5	-78.5	-72.5
[0	001	-88	-82	-76	-70
IN[2:	010	-84.5	-78.5	-72	-66
GA	011	-82.5	-76.5	-70	-64
MAX_LNA_GAIN[2:0]	100	-80.5	-74.5	-68	-62
ΔX_I	101	-78	-72	-66	-60
/W	110	-76.5	-70	-64	-58
	111	-74.5	-68	-62	-56

Table 31: Typical RSSI Value in dBm at CS
Threshold with Default MAGN_TARGET at 250
kBaud, 955 MHz

If the threshold is set high, i.e. only strong signals are wanted; the threshold should be adjusted upwards by first reducing the MAX_LNA_GAIN value and then the MAX_DVGA_GAIN value. This will reduce power consumption in the receiver front end, since the highest gain settings are avoided.

17.4.2 CS Relative Threshold

The relative threshold detects sudden changes in the measured signal level. This setting does not depend on the absolute signal level and is thus useful to detect signals in environments with a time varying noise floor. The register field AGCCTRL1.CARRIER_SENSE_REL_THR is used to enable/disable relative CS, and to select threshold of 6 dB, 10 dB, or 14 dB RSSI change.



17.5 Clear Channel Assessment (CCA)

The Clear Channel Assessment (CCA) is used to indicate if the current channel is free or busy. The current CCA state is viewable on any of the GDO pins by setting IOCFGx.GDOx_CFG=0x09.

 ${\tt MCSM1.CCA_MODE}$ selects the mode to use when determining CCA.

When the STX or SFSTXON command strobe is given while the **CC1100F** is in the RX state, the TX or FSTXON state is only entered if the clear channel requirements are fulfilled. Otherwise, the chip will remain in RX. If the channel then becomes available, the radio will

not enter TX or FSTXON state before a new strobe command is sent on the SPI interface. This feature is called TX-if-CCA. Four CCA requirements can be programmed:

- Always (CCA disabled, always goes to TX)
- If RSSI is below threshold
- Unless currently receiving a packet
- Both the above (RSSI below threshold and not currently receiving a packet)

17.6 Link Quality Indicator (LQI)

The Link Quality Indicator is a metric of the current quality of the received signal. If PKTCTRL1.APPEND_STATUS is enabled, the value is automatically added to the last byte appended after the payload. The value can also be read from the LQI status register. The LQI gives an estimate of how easily a received signal can be demodulated by accumulating

the magnitude of the error between ideal constellations and the received signal over the 64 symbols immediately following the sync word. LQI is best used as a relative measurement of the link quality (a high value indicates a better link than what a low value does), since the value is dependent on the modulation format.

18 Forward Error Correction with Interleaving

18.1 Forward Error Correction (FEC)

The **CC1100E** has built in support for Forward Error Correction (FEC). To enable this option, set MDMCFG1.FEC_EN to 1. FEC is only supported in fixed packet length mode, i.e. when PKTCTRL0.LENGTH_CONFIG=0. FEC is employed on the data field and CRC word in order to reduce the gross bit error rate when operating near the sensitivity limit. Redundancy is added to the transmitted data in such a way that the receiver can restore the original data in the presence of some bit errors.

The use of FEC allows correct reception at a lower Signal-to-Noise Ratio (SNR), thus extending communication range if the receiver bandwidth remains constant. Alternatively, for a given SNR, using FEC decreases the bit error rate (BER). The packet error rate (PER) is related to BER by

$$PER = 1 - (1 - BER)^{packet_length}$$

A lower BER can therefore be used to allow longer packets, or a higher percentage of packets of a given length, to be transmitted successfully. Finally, in realistic ISM radio environments, transient and time-varying

phenomena will produce occasional errors even in otherwise good reception conditions. FEC will mask such errors and, combined with interleaving of the coded data, even correct relatively long periods of faulty reception (burst errors).

The FEC scheme adopted for the **CC1100E** is convolutional coding, in which n bits are generated based on k input bits and the m most recent input bits, forming a code stream able to withstand a certain number of bit errors between each coding state (the m-bit window).

The convolutional coder is a rate ½ code with a constraint length of m = 4. The coder codes one input bit and produces two output bits; hence, the effective data rate is halved. This means that in order to transmit at the same effective data rate when using FEC, it is necessary to use twice as high over-the-air data rate. This will require a higher receiver bandwidth, and thus reduce sensitivity. In other words the improved reception by using FEC and the degraded sensitivity from a receiver bandwidth higher will counteracting factors. Please see Design Note DN504 [18] for more information



18.2 Interleaving

Data received through radio channels will often experience burst errors due to interference and time-varying signal strengths. In order to increase the robustness to errors spanning multiple bits, interleaving is used when FEC is enabled. After de-interleaving, a continuous span of errors in the received stream will become single errors spread apart.

The **GC1100E** employs matrix interleaving, which is illustrated in Figure 19. The on-chip interleaving and de-interleaving buffers are 4 x 4 matrices. In the transmitter, the data bits from the rate ½ convolutional coder are written into the rows of the matrix, whereas the bit sequence to be transmitted is read from the columns of the matrix. Conversely, in the receiver, the received symbols are written into the rows of the matrix, whereas the data

passed onto the convolutional decoder is read from the columns of the matrix.

When FEC and interleaving is used, at least one extra byte is required for trellis termination. In addition, the amount of data transmitted over the air must be a multiple of the size of the interleaver buffer (two bytes). The packet control hardware therefore automatically inserts one or two extra bytes at the end of the packet, so that the total length of the data to be interleaved is an even number. Note that these extra bytes are invisible to the user, as they are removed before the received packet enters the RX FIFO.

When FEC and interleaving is used the minimum data payload is 2 bytes.

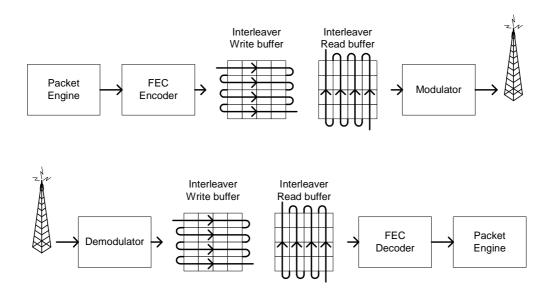


Figure 19: General Principle of Matrix Interleaving

19 Radio Control

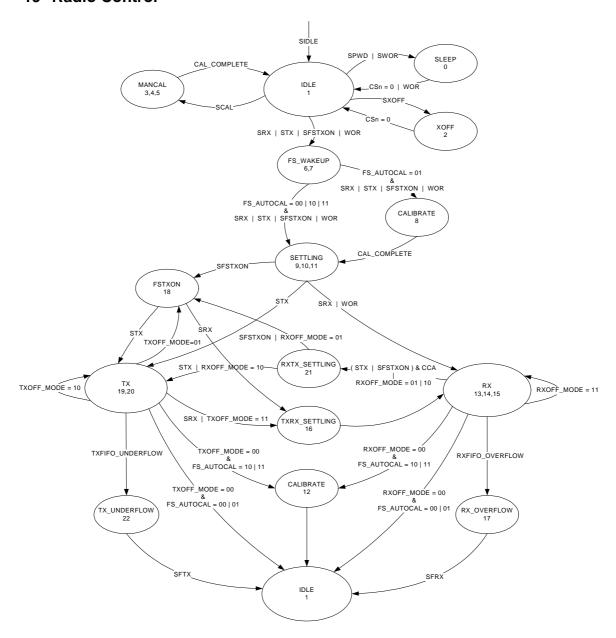


Figure 20: Complete Radio Control State Diagram

The **CC1100E** has a built-in state machine that is used to switch between different operational states (modes). The change of state is done either by using command strobes or by internal events such as TX FIFO underflow.

A simplified state diagram, together with typical usage and current consumption, is

shown in Figure 9 on page 24. The complete radio control state diagram is shown in Figure 20. The numbers refer to the state number readable in the MARCSTATE status register. This register is primarily for test purposes.

19.1 Power-On Start-Up Sequence

When the power supply is turned on, the system must be reset. This is achieved by one of the two sequences described below, i.e. Automatic power-on reset (POR) or manual

reset. After the automatic power-on reset or manual reset, it is also recommended to change the signal that is output on the GDO0 pin. The default setting is to output a clock



signal with a frequency of CLK_XOSC/192. However, to optimize performance in TX and RX, an alternative GDO setting from the settings found in Table 36 on page 55 should be selected.

19.1.1 Automatic POR

A power-on reset circuit is included in the **CC1100E**. The minimum requirements stated in Table 16 must be followed for the power-on reset to function properly. The internal power-up sequence is completed when CHIP_RDYn goes low. CHIP_RDYn is observed on the SO pin after CSn is pulled low. See Section 10.1 for more details on CHIP_RDYn.

When the **CC1100E** reset is completed, the chip will be in the IDLE state and the crystal oscillator will be running. If the chip has had sufficient time for the crystal oscillator to stabilize after the power-on-reset, the SO pin will go low immediately after taking CSn low. If CSn is taken low before reset is completed, the SO pin will first go high, indicating that the crystal oscillator is not stabilized, before going low as shown in Figure 21.

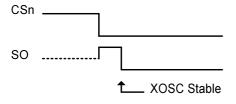


Figure 21: Power-On Reset

19.1.2 Manual Reset

The other global reset possibility on the **CC1100E** uses the SRES command strobe. By issuing this strobe, all internal registers and states are set to the default, IDLE state. The

19.2 Crystal Control

The crystal oscillator (XOSC) is either automatically controlled or always on, if MCSM0.XOSC_FORCE_ON is set.

In the automatic mode, the XOSC will be turned off if the SXOFF or SPWD command strobes are issued; the state machine then goes to XOFF or SLEEP respectively. This can only be done from the IDLE state. The XOSC will be turned off when CSn is released (goes high). The XOSC will be automatically turned on again when CSn goes low. The

manual power-up sequence is as follows (see Figure 22):

- Set SCLK = 1 and SI = 0, to avoid potential problems with pin control mode (see Section 11.3 on page 30).
- Strobe CSn low / high.
- Hold CSn low and then high for at least 40
 µs relative to pulling CSn low
- Pull CSn low and wait for SO to go low (CHIP_RDYn).
- Issue the SRES strobe on the SI line.
- When SO goes low again, reset is complete and the chip is in the IDLE state.

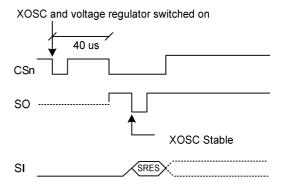


Figure 22: Power-On Reset with SRES

Note that the above reset procedure is only required just after the power supply is first turned on. If the user wants to reset the **CC1100E** after this, it is only necessary to issue an SRES command strobe.

state machine will then go to the IDLE state. The SO pin on the SPI interface must be pulled low before the SPI interface is ready to be used as described in Section 10.1 on page 27.

If the XOSC is forced on, the crystal will always stay on even in the SLEEP state.

Crystal oscillator start-up time depends on crystal ESR and load capacitances. The electrical specification for the crystal oscillator can be found in Section 4.4 on page 14.



19.3 Voltage Regulator Control

The voltage regulator to the digital core is controlled by the radio controller. When the chip enters the SLEEP state which is the state with the lowest current consumption, the voltage regulator is disabled. This occurs after CSn is released when a SPWD command strobe has been sent on the SPI interface. The

19.4 Active Modes

The **CC1100E** has two active modes: receive and transmit. These modes are activated directly by the MCU by using the SRX and STX command strobes, or automatically by Wake on Radio.

The frequency synthesizer must be calibrated regularly. The **CC1100E** has one manual calibration option (using the SCAL strobe), and three automatic calibration options that are controlled by the MCSMO.FS_AUTOCAL setting:

- Calibrate when going from IDLE to either RX or TX (or FSTXON)
- Calibrate when going from either RX or TX to IDLE automatically
- Calibrate every fourth time when going from either RX or TX to IDLE automatically

If the radio goes from TX or RX to IDLE by issuing an SIDLE strobe, calibration will not be performed. The calibration takes a constant number of XOSC cycles; see Table 32 for timing details regarding calibration.

When RX is activated, the chip will remain in receive mode until a packet is successfully received or the RX termination timer expires (see Section 19.7). The probability that a false sync word is detected can be reduced by using PQT, CS, maximum sync word length, and sync word qualifier mode as described in Section 17. After a packet is successfully received, the radio controller goes to the state indicated by the MCSM1.RXOFF_MODE setting. The possible destinations are:

- IDLE
- FSTXON: Frequency synthesizer on and ready at the TX frequency. Activate TX with STX
- TX: Start sending preamble

chip is then in the SLEEP state. Setting CSn low again will turn on the regulator and crystal oscillator and make the chip enter the IDLE state.

When Wake on Radio is enabled, the WOR module will control the voltage regulator as described in Section19.5.

RX: Start search for a new packet

Note: When MCSM1.RXOFF_MODE=11 and a packet has been received, it will take some time before a valid RSSI value is present in the RSSI register again even if the radio has never exited RX mode. This time is the same as the RSSI response time discussed in DN505 [13].

Similarly, when TX is active the chip will remain in the TX state until the current packet has been successfully transmitted. Then the state will change as indicated by the MCSM1.TXOFF_MODE setting. The possible destinations are the same as for RX.

The MCU can manually change the state from RX to TX and vice versa by using the command strobes. If the radio controller is currently in transmit and the SRX strobe is used, the current transmission will be ended and the transition to RX will be done.

If the radio controller is in RX when the STX or SFSTXON command strobes are used, the TX-if-CCA function will be used. If the channel is not clear, the chip will remain in RX. The MCSM1.CCA_MODE setting controls the conditions for clear channel assessment. See Section 17.5 on page 43 for details.

The SIDLE command strobe can always be used to force the radio controller to go to the IDLE state.



19.5 Wake On Radio (WOR)

The optional Wake on Radio (WOR) functionality enables the **CC1100E** to periodically wake up from SLEEP and listen for incoming packets without MCU interaction.

When the SWOR strobe command is sent on the SPI interface, the **CC1100E** will go to the SLEEP state when CSn is released. The RC oscillator must be enabled before the SWOR strobe can be used, as it is the clock source for the WOR timer. The on-chip timer will set the **CC1100E** into IDLE state and then RX state. After a programmable time in RX, the chip will go back to the SLEEP state, unless a packet is received. See Figure 23 and Section 19.7 for details on how the timeout works.

To exit WOR mode, set the **CC1100E** into the IDLE state

The **CC1100E** can be set up to signal the MCU that a packet has been received by using the GDO pins. If a packet is received, the MCSM1.RXOFF_MODE will determine the behaviour at the end of the received packet. When the MCU has read the packet, it can put the chip back into SLEEP with the SWOR strobe from the IDLE state.

Note: The FIFO looses its content in the SLEEP state.

The WOR timer has two events, Event 0 and Event 1. In the SLEEP state with WOR activated, reaching Event 0 will turn on the digital regulator and start the crystal oscillator. Event 1 follows Event 0 after a programmed timeout.

The time between two consecutive Event 0 is programmed with a mantissa value given by WOREVT1.EVENTO and WOREVTO.EVENTO, and an exponent value set by WORCTRL.WOR_RES. The equation is:

$$t_{Event0} = \frac{750}{f_{xOSC}} \cdot EVENT0 \cdot 2^{5 \cdot WOR_RES}$$

The Event 1 timeout is programmed with WORCTRL.EVENT1. Figure 23 shows the timing relationship between Event 0 timeout and Event 1 timeout.

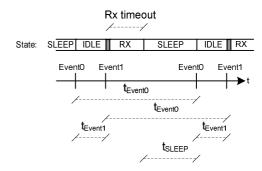


Figure 23: Event 0 and Event 1 Relationship

The time from the **CC1100E** enters SLEEP state until the next Event0 is programmed to appear, t_{SLEEP} in Figure 23, should be larger than 11.08 ms when using a 26 MHz crystal and 10.67 ms when a 27 MHz crystal is used. If t_{SLEEP} is less than 11.08 (10.67) ms, there is a chance that the consecutive Event 0 will occur

$$\frac{750}{f_{xosc}}$$
.128 seconds

too early. Application Note AN047 [7] explains in detail the theory of operation and the different registers involved when using WOR, as well as highlighting important aspects when using WOR mode.

19.5.1 RC Oscillator and Timing

The frequency of the low-power RC oscillator used for the WOR functionality varies with temperature and supply voltage. In order to keep the frequency as accurate as possible, the RC oscillator will be calibrated whenever possible, which is when the XOSC is running and the chip is not in the SLEEP state. When the power and XOSC are enabled, the clock used by the WOR timer is a divided XOSC clock. When the chip goes to the sleep state, the RC oscillator will use the last valid calibration result. The frequency of the RC oscillator is locked to the main crystal frequency divided by 750.

In applications where the radio wakes up very often, typically several times every second, it is possible to do the RC oscillator calibration once and then turn off calibration to reduce the current consumption. This is done by setting WORCTRL.RC_CAL=0 and requires that RC oscillator calibration values are read from registers RCCTRL0_STATUS and RCCTRL1_STATUS and written back to RCCTRL0 and RCCTRL1 respectively. If the





RC oscillator calibration is turned off, it will have to be manually turned on again if the temperature and/or the supply voltage

changes. Refer to Application Note AN047 [7] for further details.

19.6 Timing

The radio controller controls most of the timing in the *CC1100E*, such as synthesizer calibration, PLL lock time, and RX/TX turnaround times. Timing from IDLE to RX and IDLE to TX is constant, dependent on the auto calibration setting. RX/TX and TX/RX turnaround times are constant. The calibration time is constant 18739 clock periods. Table 32 shows timing in crystal clock cycles for key state transitions.

Power on time and XOSC start-up times are variable, but within the limits stated in Table 11.

Note that in a frequency hopping spread spectrum or a multi-channel protocol the calibration time can be reduced from 721 μ s to approximately 150 μ s. This is explained in Section 28.2.

19.7 RX Termination Timer

The **CC1100E** has optional functions for RXautomatic termination of after programmable time. The main use for this functionality is Wake on Radio, but it may also useful for other applications. termination timer starts when in RX state. The programmable timeout is with the MCSM2.RX_TIME setting. When the timer expires, the radio controller will check the condition for staying in RX; if the condition is not met, RX will terminate.

The programmable conditions are:

- MCSM2.RX_TIME_QUAL=0: Continue receive if sync word has been found
- MCSM2.RX_TIME_QUAL=1: Continue receive if sync word has been found, or if the preamble quality is above threshold (PQT)

If the system expects the transmission to have started when enabling the receiver, the MCSM2.RX_TIME_RSSI function can be used. The radio controller will then terminate RX if the first valid carrier sense sample indicates no carrier (RSSI below threshold). See Section 17.4 on page 41 for details on Carrier Sense.

Description	XOSC Periods	26 MHz Crystal
IDLE to RX, no calibration	2298	88.4µs
IDLE to RX, with calibration	~21037	809µs
IDLE to TX/FSTXON, no calibration	2298	88.4µs
IDLE to TX/FSTXON, with calibration	~21037	809µs
TX to RX switch	560	21.5µs
RX to TX switch	250	9.6µs
RX or TX to IDLE, no calibration	2	0.1µs
RX or TX to IDLE, with calibration	~18739	721µs
Manual calibration	~18739	721µs

Table 32: State Transition Timing

For ASK/OOK modulation, lack of carrier sense is only considered valid after eight symbol periods. Thus, the MCSM2.RX_TIME_RSSI function can be used in ASK/OOK mode when the distance between "1" symbols is eight or less.

If RX terminates due to no carrier sense when the MCSM2.RX TIME RSSI function is used, or if no sync word was found when using the MCSM2.RX_TIME timeout function, the chip will always go back to IDLE if WOR is disabled and back to SLEEP if WOR is enabled. Otherwise, the MCSM1.RXOFF MODE setting determines the state to go to when RX ends. This means that the chip will not automatically go back to SLEEP once a sync word has been received. It is therefore recommended to always wake up the microcontroller on sync word detection when using WOR mode. This can be done by selecting output signal 6 (see Table 36 on page 55) on one of the GDO output programmable pins, programming the microcontroller to wake up on an edge-triggered interrupt from this GDO pin.

20 Data FIFO

The **CC1100E** contains two 64 byte FIFOs, one for received data and one for data to be transmitted. The SPI interface is used to read from the RX FIFO and write to the TX FIFO. Section 10.5 contains details on the SPI FIFO access. The FIFO controller will detect overflow in the RX FIFO and underflow in the TX FIFO.

When writing to the TX FIFO it is the responsibility of the MCU to avoid TX FIFO overflow. A TX FIFO overflow will result in an error in the TX FIFO content.

Likewise, when reading the RX FIFO the MCU must avoid reading the RX FIFO past its empty value since a RX FIFO underflow will result in an error in the data read out of the RX FIFO.

The chip status byte that is available on the SO pin while transferring the SPI header and contains the fill grade of the RX FIFO if the access is a read operation and the fill grade of the TX FIFO if the access is a write operation. Section 10.1 on page 27 contains more details on this.

The number of bytes in the RX FIFO and TX FIFO can be read from the status registers RXBYTES.NUM_RXBYTES and TXBYTES.NUM_TXBYTES respectively. If a received data byte is written to the RX FIFO at the exact same time as the last byte in the RX FIFO is read over the SPI interface, the RX FIFO pointer is not properly updated and the last read byte will be duplicated. To avoid this problem, the RX FIFO should never be emptied before the last byte of the packet is received.

For packet lengths less than 64 bytes it is recommended to wait until the complete packet has been received before reading it out of the RX FIFO.

If the packet length is larger than 64 bytes, the MCU must determine how many bytes can be read from the RX FIFO (RXBYTES.NUM_RXBYTES-1). The following software routine can be used:

- Read RXBYTES.NUM_RXBYTES
 repeatedly at a rate guaranteed to be at
 least twice that of which RF bytes are
 received until the same value is returned
 twice; store value in n.
- 2. If *n* < # of bytes remaining in packet, read *n*-1 bytes from the RX FIFO.

- 3. Repeat steps 1 and 2 until *n* = # of bytes remaining in packet.
- 4. Read the remaining bytes from the RX FIFO.

The 4-bit FIFOTHR.FIFO_THR setting is used to program threshold points in the FIFOs.

Table 33 lists the 16 FIFO_THR settings and the corresponding thresholds for the RX and TX FIFOs. The threshold value is coded in opposite directions for the RX FIFO and TX FIFO. This gives equal margin to the overflow and underflow conditions when the threshold is reached.

FIFO_THR	Bytes in TX FIFO	Bytes in RX FIFO
0 (0000)	61	4
1 (0001)	57	8
2 (0010)	53	12
3 (0011)	49	16
4 (0100)	45	20
5 (0101)	41	24
6 (0110)	37	28
7 (0111)	33	32
8 (1000)	29	36
9 (1001)	25	40
10 (1010)	21	44
11 (1011)	17	48
12 (1100)	13	52
13 (1100E)	9	56
14 (1110)	5	60
15 (1111)	1	64

Table 33: FIFO_THR Settings and the Corresponding FIFO Thresholds

A signal will assert when the number of bytes in the FIFO is equal to or higher than the programmed threshold. This signal can be viewed on the GDO pins (see Table 36 on page 55).

Figure 24 shows the number of bytes in both the RX FIFO and TX FIFO when the threshold signal toggles in the case of FIFO_THR=13. Figure 25 shows the signal on the GDO pin as the respective FIFO is filled above the threshold, and then drained below in the case of FIFO_THR=13.



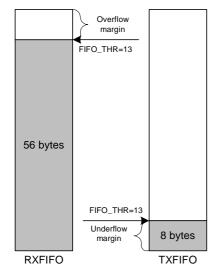


Figure 24 Example of FIFOs at Threshold

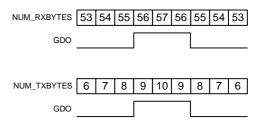


Figure 25: Number of Bytes in FIFO vs. the GDO Signal (GDOx_CFG=0x00 in RX and GDOx_CFG=0x02 in TX, FIFO_THR=13)

21 Frequency Programming

The frequency programming in the **CC1100E** is designed to minimize the programming needed in a channel-oriented system.

To set up a system with channel numbers, the desired channel spacing is programmed with the MDMCFGO.CHANSPC_M and MDMCFGI.CHANSPC_E registers. The channel spacing registers are mantissa and exponent respectively. The base or start frequency is set

by the 24 bit frequency word located in the FREQ2, FREQ1, and FREQ0 registers. This word will typically be set to the centre of the lowest channel frequency that is to be used.

The desired channel number is programmed with the 8-bit channel number register, CHANNR.CHAN, which is multiplied by the channel offset. The resultant carrier frequency is given by:

$$f_{carrier} = \frac{f_{XOSC}}{2^{16}} \cdot \left(FREQ + CHAN \cdot \left(\left(256 + CHANSPC \ _M \right) \cdot 2^{CHANSPC \ _E - 2} \right) \right)$$

With a 26 MHz crystal the maximum channel spacing is 405 kHz. To get e.g. 1 MHz channel spacing, one solution is to use 333 kHz channel spacing and select each third channel in CHANNR. CHAN.

The preferred IF frequency is programmed with the FSCTRL1.FREQ_IF register. The IF frequency is given by:

$$f_{IF} = \frac{f_{XOSC}}{2^{10}} \cdot FREQ_IF$$

Note that the SmartRF[®] Studio software [8] automatically calculates the optimum FSCTRL1.FREQ_IF register setting based on channel spacing and channel filter bandwidth.

If any frequency programming register is altered when the frequency synthesizer is running, the synthesizer may give an undesired response. Hence, the frequency programming should only be updated when the radio is in the IDLE state.

22 VCO

The VCO is completely integrated on-chip.

22.1 VCO and PLL Self-Calibration

The VCO characteristics vary with temperature and supply voltage changes as well as the desired operating frequency. In order to ensure reliable operation, the **CC1100E** includes frequency synthesizer self-calibration circuitry. This calibration should be done regularly, and must be performed after turning on power and before using a new frequency (or channel). The number of XOSC cycles for completing the PLL calibration is given in Table 32 on page 49.

The calibration can be initiated automatically or manually. The synthesizer can be automatically calibrated each time the synthesizer is turned on, or each time the synthesizer is turned off automatically. This is configured with the MCSMO.FS_AUTOCAL register setting. In manual mode, the calibration is initiated when the SCAL command strobe is activated in the IDLE mode.

23 Voltage Regulators

The **CC1100E** contains several on-chip linear voltage regulators that generate the supply voltages needed by low-voltage modules. These voltage regulators are invisible to the user, and can be viewed as integral parts of the various modules. The user must however make sure that the absolute maximum ratings and required pin voltages in Table 1 and Table 17 are not exceeded.

By setting the CSn pin low, the voltage regulator to the digital core turns on and the crystal oscillator starts. The SO pin on the SPI interface must go low before the first positive edge of SCLK (setup time is given in Table 20).

24 Output Power Programming

The RF output power level from the device has two levels of programmability as illustrated in Figure 26. The special PATABLE register can hold up to eight user selected output power settings. The 3-bit FRENDO.PA_POWER value selects the PATABLE entry to use. This two-level functionality provides flexible PA power ramp up and ramp down at the start and end of transmission as well as ASK modulation

Note: The calibration values are maintained in SLEEP mode, so the calibration is still valid after waking up from SLEEP mode unless supply voltage or temperature has changed significantly.

To check that the PLL is in lock, the user can program register <code>IOCFGx.GDOx_CFG</code> to 0x0A, and use the lock detector output available on the GDOx pin as an interrupt for the MCU (x = 0,1, or 2). A positive transition on the GDOx pin means that the PLL is in lock. As an alternative the user can read register <code>FSCAL1</code>. The PLL is in lock if the register content is different from 0x3F. Refer also to the **CC1100E** Errata Note [5].

For more robust operation, the source code could include a check so that the PLL is recalibrated until PLL lock is achieved if the PLL does not lock the first time.

If the chip is programmed to enter power-down mode (SPWD strobe issued), the power will be turned off after CSn goes high. The power and crystal oscillator will be turned on again when CSn goes low.

The voltage regulator for the digital core requires one external decoupling capacitor.

The voltage regulator output should only be used for driving the **CC1100E**.

shaping. All the PA power settings in the PATABLE from index 0 up to the FRENDO.PA POWER value are used.

The power ramping at the start and at the end of a packet can be turned off by setting FRENDO.PA_POWER=0 and then program the desired output power to index 0 in the PATABLE.





If OOK modulation is used, the logic 0 and logic 1 power levels shall be programmed to index 0 and 1 respectively.

Table 33 contains recommended PATABLE settings for various output levels and frequency bands. DN013 Error! Reference source not found. gives the complete tables for the different frequency bands. Using PA settings from 0x61 to 0x6F is not recommended.

Table 34 contains output power and current consumption for default PATABLE setting (0xC6).

See Section 10.6 on page 29 for PATABLE programming details. PATABLE must be programmed in burst mode if you want to write to other entries than PATABLE[0].

Note: All content of the PATABLE except for the first byte (index 0) is lost when entering the SLEEP state.

	480 MHz		9	55 MHz
Output Power [dBm]	Setting	Current Consumption, Typ. [mA]	Setting	Current Consumption, Typ. [mA]
-30	0x04	12.5	0x30	13.0
-20	0x0E	13.0	0x14	12.9
-15	0x1C	13.5	0x18	13.6
-10	0x26	14.9	0x24	14.6
-5	0x2B	16.9	0x28	16.2
0	0x60	16.6	0x60	16.5
5	0x86	19.8	0x86	19.1
7	0xCB	24.6	0xC7	26.3
10 (9)	0xC2	29.6	0xC0	30.9

Table 34: Optimum PATABLE Settings for Various Output Power Levels and Frequency Bands

	480 MHz			955 MHz
Default Power Setting	Output Power [dBm]	Current Consumption, Typ. [mA]	Output Power [dBm]	Current Consumption, Typ. [mA]
0xC6	8.8	26.9	7.3	26.7

Table 35: Output Power and Current Consumption for Default PATABLE Setting

25 Shaping and PA Ramping

With ASK modulation, up to eight power settings are used for shaping. The modulator contains a counter that counts up when transmitting a one and down when transmitting a zero. The counter counts at a rate equal to 8 times the symbol rate. The counter saturates

at FRENDO.PA_POWER and 0 respectively. This counter value is used as an index for a lookup in the power table. Thus, in order to utilize the whole table, FRENDO.PA_POWER should be 7 when ASK is active. The shaping of the ASK signal is dependent on the



SWRS082 Page 53 of 92

configuration of the PATABLE. Figure 27

shows some examples of ASK shaping.

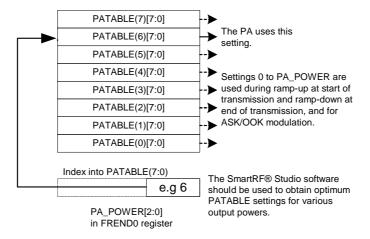


Figure 26: PA_POWER and PATABLE

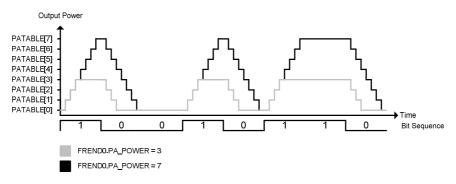


Figure 27: Shaping of ASK Signal

26 General Purpose / Test Output Control Pins

The three digital output pins GDO0, GDO1, and GDO2 are general control pins configured with IOCFG0.GDO0_CFG, IOCFG1.GDO1_CFG, and IOCFG2.GDO2_CFG respectively. Table 36 shows the different signals that can be monitored on the GDO pins. These signals can be used as inputs to the MCU.

GDO1 is the same pin as the SO pin on the SPI interface, thus the output programmed on this pin will only be valid when CSn is high. The default value for GDO1 is 3-stated which is useful when the SPI interface is shared with other devices.

The default value for GDO0 is a 135-141 kHz clock output (XOSC frequency divided by 192). Since the XOSC is turned on at power-on-reset, this can be used to clock the MCU in systems with only one crystal. When the MCU is up and running, it can change the clock frequency by writing to IOCFG0.GDO0_CFG.

An on-chip analog temperature sensor is enabled by writing the value 128 (0x80) to the IOCFG0 register. The voltage on the GDO0 pin is then proportional to temperature. See Section 4.7 on page 15 for temperature sensor specifications.

If the IOCFGx.GDOx_CFG setting is less than 0x20 and IOCFGx_GDOx_INV is 0 (1), the GDO0 and GDO2 pins will be hardwired to 0 (1), and the GDO1 pin will be hardwired to 1 (0) in the SLEEP state. These signals will be hardwired until the CHIP_RDYn signal goes low.

If the IOCFGx.GDOx_CFG setting is 0x20 or higher, the GDO pins will work as programmed also in SLEEP state. As an example, GDO1 is high impedance in all states if IOCFG1.GDO1 CFG=0x2E.



SWRS082 Page 54 of 92



GDOx CFG	[5:0] Description
0 (0x00)	Associated to the RX FIFO: Asserts when RX FIFO is filled at or above the RX FIFO threshold. De-asserts when RX FIFO is drained below the same threshold.
1 (0x01)	Associated to the RX FIFO: Asserts when RX FIFO is filled at or above the RX FIFO threshold or the end of packet is reached. De-asserts when the RX FIFO is empty.
2 (0x02)	Associated to the TX FIFO: Asserts when the TX FIFO is filled at or above the TX FIFO threshold. De-asserts when the TX FIFO is below the same threshold.
3 (0x03)	Associated to the TX FIFO: Asserts when TX FIFO is full. De-asserts when the TX FIFO is drained below the TX FIFO threshold.
4 (0x04)	Asserts when the RX FIFO has overflowed. De-asserts when the FIFO has been flushed.
5 (0x05) 6 (0x06)	Asserts when the TX FIFO has underflowed. De-asserts when the FIFO is flushed. Asserts when sync word has been sent / received, and de-asserts at the end of the packet. In RX, the pin will de-assert when the packet is the TX FIFO underflower.
7 (0x07)	when the optional address check fails or the RX FIFO overflows. In TX the pin will de-assert if the TX FIFO underflows. Asserts when a packet has been received with CRC OK. De-asserts when the first byte is read from the RX FIFO.
8 (0x08)	Preamble Quality Reached. Asserts when the PQI is above the programmed PQT value.
9 (0x09) 10 (0x0A)	Clear channel assessment. High when RSSI level is below threshold (dependent on the current CCA_MODE setting). Lock detector output. The PLL is in lock if the lock detector output has a positive transition or is constantly logic high. To
11 (0x0B)	check for PLL lock the lock detector output should be used as an interrupt for the MCU. Serial Clock. Synchronous to the data in synchronous serial mode. In RX mode, data is set up on the falling edge by the CC1100E when GDOX_TNV=0.
` ,	In RX mode, data is set up on the falling edge by the CC1100E when GDOx_INV=0. In TX mode, data is sampled by the CC1100E on the rising edge of the serial clock when GDOx_INV=0.
12 (0x0C)	Serial Synchronous Data Output. Used for synchronous serial mode.
13 (0x0D) 14 (0x0E)	Serial Data Output. Used for asynchronous serial mode. Carrier sense. High if RSSI level is above threshold.
15 (0x0F)	CRC_OK. The last CRC comparison matched. Cleared when entering/restarting RX mode.
16 (0x10)	Reserved – used for test.
17 (0x11)	Reserved – used for test.
18 (0x12)	Reserved – used for test.
19 (0x13)	Reserved – used for test.
20 (0x14) 21 (0x15)	Reserved – used for test. Reserved – used for test.
22 (0x16)	RX_HARD_DATA [1]. Can be used together with RX_SYMBOL_TICK for alternative serial RX output.
23 (0x17)	RX_HARD_DATA [0]. Can be used together with RX_SYMBOL_TICK for alternative serial RX output.
24 (0x18)	Reserved – used for test.
25 (0x19)	Reserved – used for test.
26 (0x1A)	Reserved – used for test.
27 (0x1B)	Reserved – used for test.
28 (0x1C) 29 (0x1D)	Reserved – used for test. RX SYMBOL TICK. Can be used together with RX HARD DATA for alternative serial RX output.
30 (0x1E)	Reserved – used for test.
31 (0x1F)	Reserved – used for test.
32 (0x20)	Reserved – used for test.
33 (0x21)	Reserved – used for test.
34 (0x22)	Reserved – used for test.
35 (0x23)	Reserved – used for test. WOR EVNTO.
36 (0x24) 37 (0x25)	WOR_EVNTO. WOR EVNT1.
38 (0x26)	Reserved – used for test.
39 (0x27)	CLK 32k.
40 (0x28)	Reserved – used for test.
41 (0x29)	CHIP_RDYn.
42 (0x2A)	Reserved – used for test.
43 (0x2B)	XOSC_STABLE.
44 (0x2C) 45 (0x2D)	Reserved – used for test. GD00_Z_EN_N. When this output is 0, GD00 is configured as input (for serial TX data).
46 (0x2E)	High impedance (3-state).
47 (0x2F)	HW to 0 (HW1 achieved by setting GD0x_INV=1). Can be used to control an external LNA/PA or RX/TX switch.
48 (0x30)	CLK_XOSC/1
49 (0x31)	CLK_XOSC/1.5
50 (0x32)	CLK_XOSC/2 CLK_XOSC/3
51 (0x33) 52 (0x34)	
53 (0x35)	CLK_XOSC/4 Note: There are 3 GDO pins, but only one CLK_XOSC/n can be selected as an output at any time. If CLK_XOSC/n is to be monitored on one of the GDO pins, the other two GDO pins must
54 (0x36)	CLK_XOSC/8 be configured to values less than 0x30. The GDO default value is CLK XOSC/192.
55 (0x37)	CLK_XOSC/12
56 (0x38)	CLK_XOSC/16 To optimize RF performance, these signals should not be used while the radio is in RX or TX
57 (0x39)	CLK_XOSC/24 mode.
58 (0x3A)	CLK_XOSC/32
59 (0x3B)	CLK_XOSC/48
60 (0x3C)	CLK_XOSC/64
61 (0×3D)	CLK XOSC/96
61 (0x3D) 62 (0x3E)	CLK_XOSC/96 CLK_XOSC/128

Table 36: GDOx Signal Selection (x = 0, 1, or 2)



SWRS082 Page 55 of 92

27 Asynchronous and Synchronous Serial Operation

Several features and modes of operation have been included in the **CC1100E** to provide backward compatibility with previous Chipcon products and other existing RF communication systems. For new systems, it is recommended

to use the built-in packet handling features, as they can give more robust communication, significantly offload the microcontroller, and simplify software development.

27.1 Asynchronous Serial Operation

Asynchronous transfer is included in the **CC1100E** for backward compatibility with systems that are already using the asynchronous data transfer.

When asynchronous transfer is enabled, several of the support mechanisms for the MCU that are included in the **CC1100E** will be disabled, such as packet handling hardware, buffering in the FIFO, and so on. The asynchronous transfer mode does not allow for the use of the data whitener, interleaver, and FEC, and it is not possible to use Manchester encoding. MSK is not supported for asynchronous transfer.

PKTCTRL0.PKT_FORMAT Settina to 3 enables asynchronous serial mode. In TX, the GDO0 pin is used for data input (TX data). Data output can be on GDO0, GDO1, or GDO2. This is set by the IOCFG0.GDO0_CFG, IOCFG1.GDO1_CFG and IOCFG2.GDO2 CFG fields.

The **CC1100E** modulator samples the level of the asynchronous input 8 times faster than the programmed data rate. The timing requirement for the asynchronous stream is that the error in the bit period must be less than one eighth of the programmed data rate.

27.2 Synchronous Serial Operation

PKTCTRL0.PKT FORMAT Settina to enables synchronous serial mode. In the synchronous serial mode, data is transferred on a two-wire serial interface. The CC1100E provides a clock that is used to set up new data on the data input line or sample data on the data output line. Data input (TX data) is on the GDO0 pin. This pin will automatically be configured as an input when TX is active. The TX latency is 8 bits. The data output pin can be any of the GDO pins. This is set by the IOCFG0.GDO0_CFG, IOCFG1.GDO1_CFG, and IOCFG2.GDO2 CFG fields. Time from start of reception until data is available on the receiver data output pin is equal to 9 bit.

Preamble and sync word insertion/detection may or may not be active, dependent on the sync mode set by the MDMCFG2.SYNC MODE.

If preamble and sync word is disabled, all other packet handler features and FEC should also be disabled. The MCU must then handle preamble and sync word insertion and detection in software.

If preamble and sync word insertion/detection is left on, all packet handling features and FEC can be used. One exception is that the address filtering feature is unavailable in synchronous serial mode.

When using the packet handling features in synchronous serial mode, the **CC1100E** will insert and detect the preamble and sync word and the MCU will only provide/get the data payload. This is equivalent to the recommended FIFO operation mode.

An alternative serial RX output option is to configure any of the GD0 pins for RX_SYMBOL_TICK and RX_HARD_[1:0], see Table 36. RX_HARD_[1:0] is the hard decision symbol. RX_HARD_[1:0] contain data for 4-ary modulation formats while RX_HARD_DATA [1] contain data for 2-ary modulation formats. The RX_SYMBOL_TICK signal is the symbol clock and is high for one half symbol period whenever a new symbol is presented on the hard and soft data outputs. This option may be used for both synchronous and asynchronous interfaces.



28 System Considerations and Guidelines

28.1 SRD Regulations

International regulations and national laws regulate the use of radio receivers and transmitters. The **CC1100E** is specifically designed for use in the license free 470-510 MHz and 950-960 MHz frequency bands in China and Japan, respectively.

28.1.1 ARIB STD-T96

The applicable regulatory requirements for using the **CC1100E** at the 950-956 MHz frequency band in Japan are specified by the ARIB STD-T96 [6].

For applications targeting ARIB STD-T96, FSCAL3 [7:4] needs to be set to 0xA and FSCAL0 needs to be set to 0x07 for optimum performance.

The **CC1100E** can support operation with one (200 kHz), two (400 kHz) and three (600 kHz) unit channels as defined by the ARIB STD-T96 but will typically be used in wireless systems

with two and three unit channels. For data rates higher than 100 kbps, the frequency deviation may have to be reduced compared to the default settings in order to comply with the ARIB STD-T96 transmit specifications.

Typical margins to the transmit spectrum mask measured according to the ARIB STD-T96 using the CC1100E reference design at 0 dBm output power are shown in Table 37. Higher margins can be achieved by reducing the output power accordingly.

Please note that compliance with regulations is dependent on the complete system performance. It is the customer's responsibility to ensure that the system complies with regulations.

Data	Deviation	Typical	Typical N	largin [dB]
Rate [kbps]	[kHz]	Sensitivity [dBm]	400 kHz	600 kHz
1.2	5.2	-111	3	4
4.8	25.4	-110	1.5	5.5
10	19	-106	3	4.5
38.4	20	-103	1.5	6.5
76.8	32	-100	3	6
100	47	-100	1	5.5
175	41	-91	2.5	5.5
200	100	-96	N/A	2
200	38	-89	1.5	4.5
250	70	-93	N/A	2.5

Table 37: CC1100E typical performance values for ARIB STD-T96 using the CC1100E reference design, 25°C and 3V (FSCAL3 [7:4] set to 0xA and FSCAL0 set to 0x07)

28.2 Frequency Hopping and Multi-Channel Systems

The 470 MHz and 950 MHz bands are shared by many systems both in industrial, office, and home environments. It is therefore recommended to use frequency hopping spread spectrum (FHSS) or a multi-channel

protocol because the frequency diversity makes the system more robust with respect to interference from other systems operating in the same frequency band. FHSS also combats multipath fading.



The **CC1100E** is highly suited for FHSS or multichannel systems due to its agile frequency synthesizer and effective communication interface. Using the packet handling support and data buffering is also beneficial in such systems as these features will significantly offload the host controller.

Charge pump current, VCO current, and VCO capacitance array calibration data is required for each frequency when implementing frequency hopping for the **CC1100E**. There are 3 ways of obtaining the calibration data from the chip:

- 1) Frequency hopping with calibration for each hop. The PLL calibration time is approximately 720 µs. The blanking interval between each frequency hop is then approximately 810 us.
- 2) Fast frequency hopping without calibration for each hop can be done by performing the necessary calibrating at startup and saving the resulting FSCAL3, FSCAL2, and FSCAL1 register values in MCU memory. The VCO capacitance array calibration FSCAL1 register value must be found for each RF frequency to be used. The VCO current calibration value and the charge pump current calibration value available in FSCAL2 and FSCAL3 respectively are not dependent on the RF frequency, so the same value can therefore be used for all RF frequencies for these two registers. Between each frequency hop, the calibration process can then be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values that corresponds to the next RF frequency. The PLL turn on time is approximately 90 µs. The blanking interval between each frequency hop is then approximately 90 µs.

3) Run calibration on a single frequency at startup. Next write 0 to FSCAL3 [5:4] to disable the charge pump calibration. After writing to FSCAL3 [5:4], strobe SRX (or STX) with MCSM0.FS_AUTOCAL=1 for each new frequency hop. That is, VCO current and VCO capacitance calibration is done, but not charge pump current calibration. When charge pump current calibration is disabled the calibration time is reduced from approximately 720 μ s to approximately 150 μ s. The blanking interval between each frequency hop is then approximately 240 μ s.

There is a trade off between blanking time and memory space needed for storing calibration data in non-volatile memory. Solution 2) above gives the shortest blanking interval, but requires more memory space to store calibration values. This solution also requires that the supply voltage and temperature do not vary much in order to have a robust solution. Solution 3) gives approximately 570 µs smaller blanking interval than solution 1).

The recommended settings for TESTO.VCO_SEL_CAL_EN changes with frequency. This means that one should always use SmartRF® Studio [8] to get the correct settings for a specific frequency before doing a calibration, regardless of which calibration method is being used.

Note: The content in the TESTn registers (n = 0, 1, or 2) are not retained in SLEEP state, thus it is necessary to re-write these registers when returning from the SLEEP state.

28.3 Data Burst Transmissions

The high maximum data rate of the **CC1100E** opens up for burst transmissions. A low average data rate link (e.g. 10 kBaud) can be realized by using a higher over-the-air data rate. Buffering the data and transmitting in bursts at high data rate (e.g. 500 kBaud) will reduce the time in active mode, and hence also reduce the average current consumption

28.4 Continuous Transmissions

In data streaming applications, the **CC1100E** opens up for continuous transmissions at a 500 kBaud effective data rate. As the modulation is done with a closed loop PLL, there is no limitation in the length of a

significantly. Reducing the time in active mode will reduce the likelihood of collisions with other systems in the same frequency range.

Note: The sensitivity and thus transmission range is reduced for high data rate bursts compared to lower data rates.

transmission (open loop modulation used in some transceivers often prevents this kind of continuous data streaming and reduces the effective data rate).



SWRS082 Page 58 of 92

28.5 Low Cost Systems

As the **CC1100E** provides 1.2 - 500 kBaud multichannel performance without any external SAW or loop filters, a very low cost system can be made.

A HC-49 type SMD crystal is used in the CC1100E EM reference designs ([3] and 0).

The crystal package strongly influences the price. In a size constrained PCB design, a smaller, but more expensive, crystal may be used.

28.6 Battery Operated Systems

In low power applications, the SLEEP state with the crystal oscillator core switched off should be used when the **CC1100E** is not active. It is possible to leave the crystal

oscillator core running in the SLEEP state if start-up time is critical. The WOR functionality should be used in low power applications.

28.7 Increasing Output Power

In some applications it may be necessary to extend the link range. Adding an external power amplifier is the most effective way of doing this. The power amplifier should be inserted between the antenna and the balun and matching circuit. Two T/R switches are needed to disconnect the PA in RX mode, see details in Figure 28.

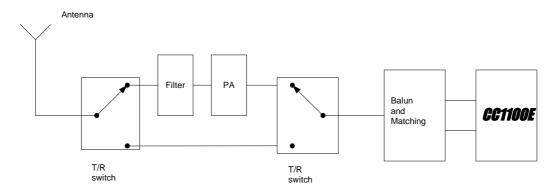


Figure 28: Block Diagram of the **CC1100E** Usage with External Power Amplifier

29 Configuration Registers

The configuration of the **CC1100E** is done by programming 8-bit registers. The optimum configuration data based on selected system parameters are most easily found by using the SmartRF® Studio software [8]. Complete descriptions of the registers are given in the following tables. After chip reset, all the registers have default values as shown in the tables. The optimum register setting might differ from the default value. After a reset, all registers that shall be different from the default value therefore needs to be programmed through the SPI interface.

There are 13 command strobe registers, listed in Table 38. Accessing these registers will initiate the change of an internal state or mode. There are 47 normal 8-bit configuration registers listed in Table 39. Many of these

registers are for test purposes only, and need not be written for normal operation of the **CC1100E**.

There are also 12 status registers that are listed in Table 40. These registers, which are read-only, contain information about the status of the **CC1100E**.

The two FIFOs are accessed through one 8-bit register. Write operations write to the TX FIFO, while read operations read from the RX FIFO.

During the header byte transfer and while writing data to a register or the TX FIFO, a status byte is returned on the SO line. This status byte is described in Table 21 on page 27.





Table 41 summarizes the SPI address space. The address to use is given by adding the base address to the left and the burst and

read/write bits on the top. Note that the burst bit has different meaning for base addresses above and below 0x2F.

Address	Strobe Name	Description
0x30	SRES	Reset chip.
0x31	SFSTXON	Enable and calibrate frequency synthesizer (if MCSM0.FS_AUTOCAL=1). If in RX (with CCA): Go to a wait state where only the synthesizer is running (for quick RX / TX turnaround).
0x32	SXOFF	Turn off crystal oscillator.
0x33	SCAL	Calibrate frequency synthesizer and turn it off. SCAL can be strobed from IDLE mode without setting manual calibration mode (MCSM0.FS_AUTOCAL=0)
0x34	SRX	Enable RX. Perform calibration first if coming from IDLE and MCSM0.FS_AUTOCAL=1.
0x35	STX	In IDLE state: Enable TX. Perform calibration first if MCSM0.FS_AUTOCAL=1. If in RX state and CCA is enabled: Only go to TX if channel is clear.
0x36	SIDLE	Exit RX / TX, turn off frequency synthesizer and exit Wake-On-Radio mode if applicable.
0x38	SWOR	Start automatic RX polling sequence (Wake-on-Radio) as described in Section 19.5 if WORCTRL.RC_PD=0.
0x39	SPWD	Enter power down mode when CSn goes high.
0x3A	SFRX	Flush the RX FIFO buffer. Only issue SFRX in IDLE or RXFIFO_OVERFLOW states.
0x3B	SFTX	Flush the TX FIFO buffer. Only issue SFTX in IDLE or TXFIFO_UNDERFLOW states.
0x3C	SWORRST	Reset real time clock to Event1 value.
0x3D	SNOP	No operation. May be used to get access to the chip status byte.

Table 38: Command Strobes



SWRS082 Page 60 of 92



Address	Register	Description	Preserved in SLEEP State	Details on Page Number
0x00	IOCFG2	GDO2 output pin configuration	Yes	64
0x01	IOCFG1	GDO1 output pin configuration	Yes	64
0x02	IOCFG0	GDO0 output pin configuration	Yes	64
0x03	FIFOTHR	RX FIFO and TX FIFO thresholds	Yes	65
0x04	SYNC1	Sync word, high byte	Yes	66
0x05	SYNC0	Sync word, low byte	Yes	66
0x06	PKTLEN	Packet length	Yes	66
0x07	PKTCTRL1	Packet automation control	Yes	66
0x08	PKTCTRL0	Packet automation control	Yes	67
0x09	ADDR	Device address	Yes	67
0x0A	CHANNR	Channel number	Yes	67
0x0B	FSCTRL1	Frequency synthesizer control	Yes	68
0x0C	FSCTRL0	Frequency synthesizer control	Yes	68
0x0D	FREQ2	Frequency control word, high byte	Yes	68
0x0E	FREQ1	Frequency control word, middle byte	Yes	68
0x0F	FREQ0	Frequency control word, low byte	Yes	68
0x10	MDMCFG4	Modem configuration	Yes	69
0x11	MDMCFG3	Modem configuration	Yes	69
0x12	MDMCFG2	Modem configuration	Yes	70
0x13	MDMCFG1	Modem configuration	Yes	71
0x14	MDMCFG0	Modem configuration	Yes	71
0x15	DEVIATN	Modem deviation setting	Yes	72
0x16	MCSM2	Main Radio Control State Machine configuration	Yes	73
0x17	MCSM1	Main Radio Control State Machine configuration	Yes	74
0x18	MCSM0	Main Radio Control State Machine configuration	Yes	75
0x19	FOCCFG	Frequency Offset Compensation configuration	Yes	76
0x1A	BSCFG	Bit Synchronization configuration	Yes	77
0x1B	AGCTRL2	AGC control	Yes	78
0x1C	AGCTRL1	AGC control	Yes	79
0x1D	AGCTRL0	AGC control	Yes	80
0x1E	WOREVT1	High byte Event 0 timeout	Yes	80
0x1F	WOREVT0	Low byte Event 0 timeout	Yes	81
0x20	WORCTRL	Wake On Radio control	Yes	81
0x21	FREND1	Front end RX configuration	Yes	82
0x22	FREND0	Front end TX configuration	Yes	82
0x23	FSCAL3	Frequency synthesizer calibration	Yes	82
0x24	FSCAL2	Frequency synthesizer calibration	Yes	83
0x25	FSCAL1	Frequency synthesizer calibration	Yes	83
0x26	FSCAL0	Frequency synthesizer calibration	Yes	83
0x27	RCCTRL1	RC oscillator configuration	Yes	83
0x28	RCCTRL0	RC oscillator configuration	Yes	83
0x29	FSTEST	Frequency synthesizer calibration control	No	84
0x2A	PTEST	Production test	No	84
0x2B	AGCTEST	AGC test	No	84
0x2C	TEST2	Various test settings	No	84
0x2D	TEST1	Various test settings	No	84
0x2E	TEST0	Various test settings	No	85

Table 39: Configuration Registers Overview



SWRS082 Page 61 of 92



Address	Register	Description	Details on page number
0x30 (0xF0)	PARTNUM	Part number for the CC1100E	85
0x31 (0xF1)	VERSION	Current version number	85
0x32 (0xF2)	FREQEST	Frequency Offset Estimate	85
0x33 (0xF3)	LQI	Demodulator estimate for Link Quality	85
0x34 (0xF4)	RSSI	Received signal strength indication	85
0x35 (0xF5)	MARCSTATE	Control state machine state	86
0x36 (0xF6)	WORTIME1	High byte of WOR timer	86
0x37 (0xF7)	WORTIME0	Low byte of WOR timer	86
0x38 (0xF8)	PKTSTATUS	Current GDOx status and packet status	87
0x39 (0xF9)	VCO_VC_DAC	Current setting from PLL calibration module	87
0x3A (0xFA)	TXBYTES	Underflow and number of bytes in the TX FIFO	87
0x3B (0xFB)	RXBYTES	Overflow and number of bytes in the RX FIFO	87
0x3C (0xFC)	RCCTRL1_STATUS	Last RC oscillator calibration result	87
0x3D (0xFD)	RCCTRL0_STATUS	Last RC oscillator calibration result	88

Table 40: Status Registers Overview



Single Byte +0x00 0x00 0x01 0x02 0x03 0x04	Burst +0x40	Single Byte +0x80	Burst								
0x00 0x01 0x02 0x03		+0x80	10000								
0x01 0x02 0x03			+0xC0								
0x02 0x03	IOCFG2 IOCFG1										
0x03	IOCFG0										
		FOTHR									
	SYNC1										
0x05	SYNC0										
0x06		KTLEN									
0x07	PK	TCTRL1									
0x08	PK	TCTRL0									
0x09		ADDR									
0x0A		HANNR									
0x0B		SCTRL1									
0x0C		SCTRL0									
0x0D		REQ2									
0x0E 0x0F		REQ1 REQ0		<u>e</u>							
0x10		MCFG4		dis							
0x10		MCFG3		000							
0x12		MCFG2		SS							
0x13	ME	MCFG1		Š							
0x14		MCFG0		R/W configuration registers, burst access possible							
0x15		EVIATN		ırsı							
0x16		ICSM2		, br							
0x17		ICSM1		ers							
0x18		ICSM0		iste							
0x19		OCCFG		reg							
0x1A 0x1B		SCFG CCTRL2		on							
0x1C				ati							
0x1D	AGCCTRL1 AGCCTRL0										
0x1E		DREVT1		Juli							
0x1F	WOREVT1										
0x20	WC	DRCTRL		≶							
0x21		REND1									
0x22		REND0									
0x23		SCAL3									
0x24		SCAL2									
0x25 0x26		SCAL1 SCAL0									
0x27		CCTRL1									
0x28		CCTRL0									
0x29		STEST									
0x2A	F	PTEST									
0x2B		CTEST									
0x2C		EST2									
0x2D		TEST1									
0x2E		TEST0									
0x2F 0x30 SRES	1	SRES	PARTNUM								
0x31 SFSTXON		SFSTXON	VERSION								
0x32 SXOFF		SXOFF	FREQEST	φ							
0x33 SCAL		SCAL	LQI	ster							
0x34 SRX		SRX	RSSI	egi: gist							
0x35 STX		STX	MARCSTATE	S re							
0x36 SIDLE		SIDLE	WORTIME1	Command Strobes, Status registers (read only) and multi byte registers							
0x37	WORTIME0										
0x38 SWOR		SWOR	PKTSTATUS	es, nu							
0x39 SPWD		SPWD	VCO_VC_DAC	g p							
0x3A SFRX 0x3B SFTX		SFRX SFTX	TXBYTES RXBYTES	Sti							
0x3B SFTX 0x3C SWORRST		SWORRST	RCCTRL1_STATUS	bl (Şir							
		SNOP	RCCTRL1_STATUS	ma 1 or							
0x3D SNOP	PATABLE	PATABLE	PATABLE	om 3ad							
0x3D SNOP 0x3E PATABLE			1 / 1 / 1 / 1 / 1 / 1 / 1	ヘスピ							

Table 41: SPI Address Space



SWRS082 Page 63 of 92



29.1 Configuration Register Details – Registers with preserved values in SLEEP state

0x00: IOCFG2 - GDO2 Output Pin Configuration

Bit	Field Name	Reset	R/W	Description
7			R0	Not used
6	GDO2_INV	0	R/W	Invert output, i.e. select active low (1) / high (0)
5:0	GDO2_CFG[5:0]	41 (0x29)	R/W	Default is CHP_RDYn (See Table 36 on page 55).

0x01: IOCFG1 - GDO1 Output Pin Configuration

Bit	Field Name	Reset	R/W	Description
7	GDO_DS	0	R/W	Set high (1) or low (0) output drive strength on the GDO pins.
6	GDO1_INV	0	R/W	Invert output, i.e. select active low (1) / high (0)
5:0	GDO1_CFG[5:0]	46 (0x2E)	R/W	Default is 3-state (See Table 36 on page 55).

0x02: IOCFG0 - GDO0 Output Pin Configuration

Bit	Field Name	Reset	R/W	Description
7	TEMP_SENSOR_ENABLE	0	R/W	Enable analog temperature sensor. Write 0 in all other register bits when using temperature sensor.
6	GDO0_INV	0	R/W	Invert output, i.e. select active low (1) / high (0)
5:0	GDO0_CFG[5:0]	63 (0x3F)	R/W	Default is CLK_XOSC/192 (See Table 36 on page 55).
				It is recommended to disable the clock output in initialization, in order to optimize RF performance.





0x03: FIFOTHR - RX FIFO and TX FIFO Thresholds

Bit	Field Name	Reset	R/W	Description	Description		
7		0	R/W	Reserved,	Reserved , write 0 for compatibility with possible future extension		ensions
6	ADC_RETENTION	0	R/W	0: TEST1 =	0: TEST1 = 0x31 and TEST2= 0x88 when waking up from SL		SLEEP
				1: TEST1 =	= 0x35 and TEST2 = 0x	81 when waking up from	SLEEP
				ADC_RET analog par from SLEE	Note that the changes in the TEST registers due to the ADC_RETENTION bit setting are only seen INTERNALLY in the analog part. The values read from the TEST registers when waking up from SLEEP mode will always be the reset value.		
				mode if set at time of v	ttings with an RX filter b	be set to 1 before going andwidth below 325 kHz	are wanted
5:4	CLOSE_IN_RX [1:0]	0 (00)	R/W	For more of	letails, please see DN0	10 [11]	
				Setting	RX Attenuation, Typic	al Values	
				0 (00)	0dB		
				1 (01)	6dB		
				2 (10)	12dB		
				3 (11)	18dB		
3:0	FIFO_THR[3:0]	7 (0111)	R/W	exceeded	eshold for the TX FIFO and RX FIFO. The threshold is when the number of bytes in the FIFO is equal to or higher reshold value.		
				Setting	Bytes in TX FIFO	Bytes in RX FIFO	
				0 (0000)	61	4	
				1 (0001)	57	8	
				2 (0010)	53	12	
				3 (0011)	49	16	
				4 (0100)	45	20	
				5 (0101)	41	24	
				6 (0110)		28	
				7 (0111)	33	32	
				8 (1000)	29	36	
				9 (1001)	25	40	
				10 (1010		44	
				11 (1011		48	
				12 (1100		52	
				13 (1100E)		56	
				14 (1110		60	
				15 (1111) 1	64	

0x04: SYNC1 - Sync Word, High Byte

	Bit	Field Name	Reset	R/W	Description
I	7:0	SYNC[15:8]	211 (0xD3)	R/W	8 MSB of 16-bit sync word

0x05: SYNC0 - Sync Word, Low Byte

Bit	Field Name	Reset	R/W	Description
7:0	SYNC[7:0]	145 (0x91)	R/W	8 LSB of 16-bit sync word

0x06: PKTLEN - Packet Length

Bit	Field Name	Reset	R/W	Description
7:0	PACKET_LENGTH	255 (0xFF)	R/W	Indicates the packet length when fixed packet length mode is enabled. If variable packet length mode is used, this value indicates the maximum packet length allowed.

0x07: PKTCTRL1 - Packet Automation Control

Bit	Field Name	Reset	R/W	Description	on		
7:5	PQT[2:0]	0 (0x00)	R/W	Preamble quality estimator threshold. The preamble quality estimator increases an internal counter by one each time a bit is received that is different from the previous bit, and decreases the counter by 8 each time a bit is received that is the same as the last bit. A threshold of $4 \cdot \textsc{PQT}$ for this counter is used to gate sync word detection. When $\textsc{PQT=0}$ a sync word is always accepted.			
4		0	R0	Not Used.	Not Used.		
3	CRC_AUTOFLUSH	0	R/W	Enable automatic flush of RX FIFO when CRC is not OK. This requires that only one packet is in the RXIFIFO and that packet length is limited to the RX FIFO size.			
2	APPEND_STATUS	1	R/W		When enabled, two status bytes will be appended to the payload of the packet. The status bytes contain RSSI and LQI values, as well as CRC OK.		
1:0	ADR_CHK[1:0]	0 (00)	R/W	Controls a	ddress check configuration of received packages.		
				Setting	Address check configuration		
				0 (00)	No address check		
				1 (01)	Address check, no broadcast		
				2 (10)	Address check and 0 (0x00) broadcast		
				3 (11)	Address check and 0 (0x00) and 255 (0xFF) broadcast		



0x08: PKTCTRL0 - Packet Automation Control

Bit	Field Name	Reset	R/W	Description	Description	
7			R0	Not used	Not used	
6	WHITE_DATA	1	R/W	Turn data	whitening on / off	
				0: Whiteni 1: Whiteni		
5:4	PKT_FORMAT[1:0]	0 (00)	R/W	Format of	RX and TX data	
				Setting	Packet format	
				0 (00)	Normal mode, use FIFOs for RX and TX	
				1 (01)	Synchronous serial mode, Data in on GDO0 and data out on either of the GDOx pins	
				2 (10)	Random TX mode; sends random data using PN9 generator. Used for test. Works as normal mode, setting 0 (00), in RX	
				3 (11)	Asynchronous serial mode, Data in on GDO0 and data out on either of the GDOx pins	
3		0	R0	Not used		
2	CRC_EN	1	R/W	1: CRC ca	lculation in TX and CRC check in RX enabled	
				0: CRC dis	sabled for TX and RX	
1:0	LENGTH_CONFIG[1:0]	1 (01)	R/W	Configure	the packet length	
				Setting	Packet length configuration	
				0 (00)	Fixed packet length mode. Length configured in PKTLEN register	
				1 (01)	Variable packet length mode. Packet length configured by the first byte after sync word	
				2 (10)	Infinite packet length mode	
				3 (11)	Reserved	

0x09: ADDR - Device Address

Bit	Field Name	Reset	R/W	Description
7:0	DEVICE_ADDR[7:0]	0 (0x00)	R/W	Address used for packet filtration. Optional broadcast addresses are 0 (0x00) and 255 (0xFF).

0x0A: CHANNR - Channel Number

Bit	Field Name	Reset	R/W	Description
7:0	CHAN[7:0]	0 (0x00)	R/W	The 8-bit unsigned channel number, which is multiplied by the channel spacing setting and added to the base frequency.



SWRS082 Page 67 of 92

0x0B: FSCTRL1 - Frequency Synthesizer Control

Bit	Field Name	Reset	R/W	Description	
7:6			R0	Not used	
5		0	R/W	Reserved	
4:0	FREQ_IF[4:0]	15 (0x0F)	R/W	The desired IF frequency to employ in RX. Subtracted from FS base frequency in RX and controls the digital complex mixer in the demodulator. $f_{\mathit{IF}} = \frac{f_{\mathit{XOSC}}}{2^{10}} \cdot \mathit{FREQ} _\mathit{IF}$ The default value gives an IF frequency of 381kHz, assuming a 26.0 MHz crystal.	

0x0C: FSCTRL0 - Frequency Synthesizer Control

Bit	Field Name	Reset	R/W	Description
7:0	FREQOFF[7:0]	0 (0x00)	R/W	Frequency offset added to the base frequency before being used by the frequency synthesizer. (2s-complement).
				Resolution is $F_{XTAL}/2^{14}$ (1.59kHz-1.65kHz); range is ± 202 kHz to ± 210 kHz, dependent of XTAL frequency.

0x0D: FREQ2 - Frequency Control Word, High Byte

Bit	Field Name	Reset	R/W	Description
7:6	FREQ[23:22]	0 (00)	R	FREQ[23:22] is always 0 (the FREQ2 register is less than 36 with 26-27 MHz crystal)
5:0	FREQ[21:16]	30 (0x1E)	R/W	FREQ [23:0] is the base frequency for the frequency synthesiser in increments of $f_{\text{XOSC}}/2^{16}$. $f_{carrier} = \frac{f_{XOSC}}{2^{16}} \cdot FREQ \big[23:0 \big]$

0x0E: FREQ1 - Frequency Control Word, Middle Byte

Bit	Field Name	Reset	R/W	Description
7:0	FREQ[15:8]	196 (0xC4)	R/W	Ref. FREQ2 register

0x0F: FREQ0 - Frequency Control Word, Low Byte

Bit	Field Name	Reset	R/W	Description
7:0	FREQ[7:0]	236 (0xEC)	R/W	Ref. FREQ2 register



0x10: MDMCFG4 – Modem Configuration

Bit	Field Name	Reset	R/W	Description
7:6	CHANBW_E[1:0]	2 (0x02)	R/W	
5:4	CHANBW_M[1:0]	0 (0x00)	R/W	Sets the decimation ratio for the delta-sigma ADC input stream and thus the channel bandwidth. $BW_{channel} = \frac{f_{XOSC}}{8\cdot(4+CHANBW_M)\cdot2^{CHANBW_E}}$ The default values give 203 kHz channel filter bandwidth, assuming a 26.0 MHz crystal.
3:0	DRATE_E[3:0]	12 (0x0C)	R/W	The exponent of the user specified symbol rate

0x11: MDMCFG3 - Modem Configuration

Bit	Field Name	Reset	R/W	Description
7:0	DRATE_M[7:0]	34 (0x22)	R/W	The mantissa of the user specified symbol rate. The symbol rate is configured using an unsigned, floating-point number with 9-bit mantissa and 4-bit exponent. The 9 th bit is a hidden '1'. The resulting data rate is: $R_{DATA} = \frac{\left(256 + DRATE_M\right) \cdot 2^{DRATE_E}}{2^{28}} \cdot f_{XOSC}$ The default values give a data rate of 115.051 kBaud (closest setting to 115.2 kBaud), assuming a 26.0 MHz crystal.





0x12: MDMCFG2 – Modem Configuration

Bit	Field Name	Reset	R/W	Description	n		
7	DEM_DCFILT_OFF	0	R/W	Disable dig	ital DC blocking filter before demodulator.		
				0 = Enable (better sensitivity)			
				1 = Disable (current optimized). Only for data rates ≤ 250 kBaud			
				The recommended IF frequency changes when the DC blocking is disabled. Please use SmartRF® Studio [8] to calculate correct register setting.			
6:4	MOD_FORMAT[2:0]	0 (000)	R/W	The modulation format of the radio signal			
				Setting	Modulation format		
				0 (000)	2-FSK		
				1 (001)	GFSK		
				2 (010)	-		
				3 (011)	ASK/OOK		
				4 (100)	-		
				5 (101)	-		
				6 (110)	-		
				7 (111)	MSK		
				ASK is only	supported for output powers up to -1 dBm		
				MSK is only supported for data rates above 26 kBaud			
3	MANCHESTER_EN	0	R/W	Enables Manchester encoding/decoding.			
				0 = Disable			
				1 = Enable			
2:0	SYNC_MODE[2:0]	2 (010)	R/W	Combined	sync-word qualifier mode.		
					0 (000) and 4 (100) disables preamble and sync word on in TX and preamble and sync word detection in RX.		
				transmissio bits need to 3 (011) and	1 (001), 2 (010), 5 (101) and 6 (110) enables 16-bit sync word in TX and 16-bits sync word detection in RX. Only 15 of 16 match in RX when using setting 1 (001) or 5 (101). The values 17 (111) enables repeated sync word transmission in TX and c word detection in RX (only 30 of 32 bits need to match).		
				Setting	Sync-word qualifier mode		
				0 (000)	No preamble/sync		
				1 (001)	15/16 sync word bits detected		
				2 (010)	16/16 sync word bits detected		
				3 (011)	30/32 sync word bits detected		
				4 (100)	No preamble/sync, carrier-sense above threshold		
				5 (101)	15/16 + carrier-sense above threshold		
				6 (110)	16/16 + carrier-sense above threshold		
				7 (111)	30/32 + carrier-sense above threshold		

0x13: MDMCFG1- Modem Configuration

Bit	Field Name	Reset	R/W	Description		
7	FEC_EN	0	R/W	Enable Forward Enacket payload	rror Correction (FEC) with interle	eaving for
				0 = Disable		
				1 = Enable (Only s	supported for fixed packet length TH_CONFIG=0)	mode, i.e.
6:4	NUM_PREAMBLE[2:0]	2 (010)	R/W	Sets the minimum	number of preamble bytes to be	e transmitted
				Setting	Number of preamble bytes	
				0 (000)	2	
				1 (001)	3	
				2 (010)	4	
				3 (011)	6	
				4 (100)	8	
				5 (101)	12	
				6 (110)	16	
				7 (111)	24	
3:2			R0	Not used		
1:0	CHANSPC_E[1:0]	2 (10)	R/W	2 bit exponent of c	hannel spacing	

0x14: MDMCFG0- Modem Configuration

Bit	Field Name	Reset	R/W	Description
7:0	CHANSPC_M[7:0]	248 (0xF8)	R/W	8-bit mantissa of channel spacing. The channel spacing is multiplied by the channel number CHAN and added to the base frequency. It is unsigned and has the format: $\Delta f_{\it CHANNEL} = \frac{f_{\it XOSC}}{2^{18}} \cdot \left(256 + CHANSPC_M\right) \cdot 2^{\it CHANSPC_E}$ The default values give 199.951 kHz channel spacing (the closest setting to 200 kHz), assuming 26.0 MHz crystal frequency.



CC1100E

0x15: DEVIATN – Modem Deviation Setting

Bit	Field Name	Reset	R/W	Description	
7			R0	Not used.	
6:4	DEVIATION_E[2:0]	4 (100)	R/W	Deviation exponent.	
3			R0	Not used.	
2:0	DEVIATION_M[2:0]	7 (111)	R/W	TX	
	DEVIATION_IN[2.0]			2-FSK/ GFSK MSK	Specifies the nominal frequency deviation from the carrier for a '0' (-DEVIATN) and '1' (+DEVIATN) in a mantissa-exponent format, interpreted as a 4-bit value with MSB implicit 1. The resulting frequency deviation is given by: $f_{dev} = \frac{f_{xosc}}{2^{17}} \cdot (8 + DEVIATION_M) \cdot 2^{DEVIATION_E}$ The default values give ± 47.607 kHz deviation assuming 26.0 MHz crystal frequency. Specifies the fraction of symbol period (1/8-8/8) during which a phase change occurs ('0': +90deg, '1':-90deg). Refer to the SmartRF® Studio software [8] for correct DEVIATN setting
					when using MSK.
				ASK/OOK	This setting has no effect.
				RX	
				2-FSK/	Specifies the expected frequency deviation of incoming signal, must be approximately right for demodulation to be performed
				GFSK	reliably and robustly.
				MSK/ ASK/OOK	This setting has no effect.





0x16: MCSM2 - Main Radio Control State Machine Configuration

Bit	Field Name	Reset	R/W	Description
7:5			R0	Not used
4	RX_TIME_RSSI	0	R/W	Direct RX termination based on RSSI measurement (carrier sense). For ASK/OOK modulation, RX times out if there is no carrier sense in the first 8 symbol periods.
3	RX_TIME_QUAL	0	R/W	When the RX_TIME timer expires, the chip checks if sync word is found when RX_TIME_QUAL=0, or either sync word is found or PQI is set when RX_TIME_QUAL=1.
2:0	RX_TIME[2:0]	7 (111)	R/W	Timeout for sync word search in RX for both WOR mode and normal RX operation. The timeout is relative to the programmed EVENTO timeout.

The RX timeout in μ s is given by EVENTO-C(RX_TIME, WOR_RES) -26/X, where C is given by the table below and X is the crystal oscillator frequency in MHz:

Setting	WOR_RES = 0	WOR_RES = 1	WOR_RES = 2	WOR_RES = 3				
0 (000)	3.6058	18.0288	32.4519	46.8750				
1 (001)	1.8029	9.0144	16.2260	23.4375				
2 (010)	0.9014	4.5072	8.1130	11.7188				
3 (011)	0.4507	2.2536	4.0565	5.8594				
4 (100)	0.2254	1.1268	2.0282	2.9297				
5 (101)	0.1127	0.5634	1.0141	1.4648				
6 (110)	0.0563	0.2817	0.5071	0.7324				
7 (111)	Until end of packet							

As an example, EVENT0=34666, WOR_RES=0 and RX_TIME=6 corresponds to 1.96 ms RX timeout, 1 s polling interval and 0.195% duty cycle. Note that WOR_RES should be 0 or 1 when using WOR because using WOR_RES > 1 will give a very low duty cycle. In applications where WOR is not used all settings of WOR_RES can be used.

The duty cycle using WOR is approximated by:

•	, ,	,		
Setting	WOR_RES=0	WOR_RES=1		
0 (000)	12.50%	1.95%		
1 (001)	6.250%	9765ppm		
2 (010)	3.125%	4883ppm		
3 (011)	1.563%	2441ppm		
4 (100)	0.781%	NA		
5 (101)	0.391%	NA		
6 (110)	0.195%	NA		
7 (111)	NA			

Note that the RC oscillator must be enabled in order to use setting 0-6, because the timeout counts RC oscillator periods. WOR mode does not need to be enabled.

The timeout counter resolution is limited: With RX_TIME=0, the timeout count is given by the 13 MSBs of EVENTO, decreasing to the 7MSBs of EVENTO with RX_TIME=6.





0x17: MCSM1- Main Radio Control State Machine Configuration

Bit	Field Name	Reset	R/W	Description			
7:6			R0	Not used			
5:4	CCA_MODE[1:0]	3 (11)	R/W	Selects CCA_MODE; Reflected in CCA signal			
				Setting	Clear channel indication		
				0 (00)	Always		
				1 (01)	If RSSI below threshold		
				2 (10)	Unless currently receiving a packet		
				3 (11)	If RSSI below threshold unless currently receiving a packet		
3:2	RXOFF_MODE[1:0]	0 (00)	R/W	Select wha	at should happen when a packet has been received		
				Setting	Next state after finishing packet reception		
				0 (00)	IDLE		
				1 (01)	FSTXON		
				2 (10)	TX		
				3 (11)	Stay in RX		
				It is not pos time use C	ssible to set RXOFF_MODE to be TX or FSTXON and at the same CA.		
1:0	TXOFF_MODE[1:0]	0 (00)	R/W	Select wha	at should happen when a packet has been sent (TX)		
				Setting	Next state after finishing packet transmission		
				0 (00)	IDLE		
				1 (01)	FSTXON		
				2 (10)	Stay in TX (start sending preamble)		
				3 (11)	RX		





0x18: MCSM0- Main Radio Control State Machine Configuration

Bit	Field Name	Reset	R/W	Description				
7:6			R0	Not used				
5:4	FS_AUTOCAL[1:0]	0 (00)	R/W	Automatically calibrate when going to RX or TX, or back to IDLE				
				Setting				
				0 (00)	Never (manual	ly calibrate using SCAL strobe)		
				1 (01)	When going fro	om IDLE to RX or TX (or FSTX	ON)	
				2 (10)	When going from automatically	om RX or TX back to IDLE		
				3 (11)	Every 4 th time value	when going from RX or TX to II	DLE	
						n-radio (WOR) applications, us rrent consumption.	ing setting 3 (11)	
3:2	PO_TIMEOUT	1 (01)	R/W	Programs the number of times the six-bit ripple counter must expire after XOSC has stabilized before CHP_RDYn goes low. If XOSC is on (stable) during power-down, PO_TIMEOUT should be set so that the regulated digital supply voltage has time to stabilize before CHP_RDYn goes low (PO_TIMEOUT=2 recommended). Typical start-up time for the voltage regulator is 50 μs.				
				has suffici	ent time to stabili	r-down and the regulated digitatize while waiting for the crystal 0. For robust operation it is re	to be stable,	
				Setting	Expire count	Timeout after XOSC start		
				0 (00)	1	Approx. 2.3 – 2.4 μs		
				1 (01)	16	Approx. 37 – 39 μs		
				2 (10)	64	Approx. 149 – 155 μs		
				3 (11)	256	Approx. 597 – 620 μs		
				Exact timeout depends on crystal frequency.				
1	PIN_CTRL_EN	0	R/W	Enables th	ne pin radio contr	rol option		
0	XOSC_FORCE_ON	0	R/W	Force the	XOSC to stay on	in the SLEEP state.		



0x19: FOCCFG – Frequency Offset Compensation Configuration

Bit	Field Name	Reset	R/W	Description				
7:6			R0	Not used				
5	FOC_BS_CS_GATE	1	R/W		If set, the demodulator freezes the frequency offset compensation and clock recovery feedback loops until the CS signal goes high.			
4:3	FOC_PRE_K[1:0]	2 (10)	R/W	The frequency compensation loop gain to be used before a sync word is detected.				
				Setting	Freq. compensation loop gain before sync word			
				0 (00)	К			
				1 (01)	2K			
				2 (10)	3 <i>K</i>			
				3 (11)	4K			
2	FOC_POST_K	1	R/W	The frequency compensation loop gain to be used after a sync word is detected.				
				Setting	Freq. compensation loop gain after sync word			
				0	Same as FOC_PRE_K			
				1	K/2			
1:0	FOC_LIMIT[1:0]	2 (10)	R/W	The satura	tion point for the frequency offset compensation algorithm:			
				Setting	Saturation point (max compensated offset)			
				0 (00)	±0 (no frequency offset compensation)			
				1 (01)	±BW _{CHAN} /8			
				2 (10)	±BW _{CHAN} /4			
				3 (11)	±BW _{CHAN} /2			
					offset compensation is not supported for ASK/OOK; Always use T=0 with these modulation formats.			



0x1A: BSCFG – Bit Synchronization Configuration

Bit	Field Name	Reset	R/W	Description		
7:6	BS_PRE_KI[1:0]	1 (01)	R/W		recovery feedback loop integral gain to be used before a syndly (used to correct offsets in data rate):	c word
				Setting	Clock recovery loop integral gain before sync word	
				0 (00)	K _i	
				1 (01)	2K _i	
				2 (10)	3 <i>K</i> _i	
				3 (11)	4Kı	
5:4	BS_PRE_KP[1:0]	2 (10)	R/W	The clock word is det	recovery feedback loop proportional gain to be used before a tected.	sync
				Setting	Clock recovery loop proportional gain before sync word	
				0 (00)	K _P	
				1 (01)	2K _P	
				2 (10)	3 <i>K</i> _P	
				3 (11)	4K _P	
3	BS_POST_KI	1	R/W	The clock recovery feedback loop integral gain to be used after a sync word is detected.		
				Setting	Clock recovery loop integral gain after sync word	
				0	Same as BS_PRE_KI	
				1	K ₁ /2	
2	BS_POST_KP	1	R/W	The clock word is det	recovery feedback loop proportional gain to be used after a stected.	ync
				Setting	Clock recovery loop proportional gain after sync word	
				0	Same as BS_PRE_KP	
				1	K _P	
1:0	BS_LIMIT[1:0]	0 (00)	R/W	The satura	tion point for the data rate offset compensation algorithm:	
				Setting	Data rate offset saturation (max data rate difference)	
				0 (00)	±0 (No data rate offset compensation performed)	
				1 (01)	±3.125 % data rate offset	
				2 (10)	±6.25 % data rate offset	
				3 (11)	±12.5 % data rate offset	

Page 77 of 92



0x1B: AGCCTRL2 - AGC Control

Bit	Field Name	Reset	R/W	Description	ı
7:6	MAX_DVGA_GAIN[1:0]	0 (00)	R/W	Reduces the	e maximum allowable DVGA gain.
				Setting	Allowable DVGA settings
				0 (00)	All gain settings can be used
				1 (01)	The highest gain setting can not be used
				2 (10)	The 2 highest gain settings can not be used
				3 (11)	The 3 highest gain settings can not be used
5:3	MAX_LNA_GAIN[2:0]	0 (000)	R/W		ximum allowable LNA + LNA 2 gain relative to the ossible gain.
				Setting	Maximum allowable LNA + LNA 2 gain
				0 (000)	Maximum possible LNA + LNA 2 gain
				1 (001)	Approx. 2.6 dB below maximum possible gain
				2 (010)	Approx. 6.1 dB below maximum possible gain
				3 (011)	Approx. 7.4 dB below maximum possible gain
				4 (100)	Approx. 9.2 dB below maximum possible gain
				5 (101)	Approx. 11.5 dB below maximum possible gain
				6 (110)	Approx. 14.6 dB below maximum possible gain
				7 (111)	Approx. 17.1 dB below maximum possible gain
2:0	MAGN_TARGET[2:0]	3 (011)	R/W		set the target value for the averaged amplitude from the nel filter (1 LSB = 0 dB).
				Setting	Target amplitude from channel filter
				0 (000)	24 dB
				1 (001)	27 dB
				2 (010)	30 dB
				3 (011)	33 dB
				4 (100)	36 dB
				5 (101)	38 dB
				6 (110)	40 dB
				7 (111)	42 dB



0x1C: AGCCTRL1 - AGC Control

Bit	Field Name	Reset	R/W	Description	
7			R0	Not used	
6	AGC_LNA_PRIORITY	1	R/W	Selects between two different strategies for LNA and LNA 2 gain adjustment. When 1, the LNA gain is decreased first. When 0, the LNA 2 gain is decreased to minimum before decreasing LNA gain.	
5:4	CARRIER_SENSE_REL_THR[1:0]	0 (00)	R/W	Sets the relative change threshold for asserting carrier se	ense
				Setting Carrier sense relative threshold	
				0 (00) Relative carrier sense threshold disabled	
				1 (01) 6 dB increase in RSSI value	
				2 (10) 10 dB increase in RSSI value	
				3 (11) 14 dB increase in RSSI value	
3:0	CARRIER_SENSE_ABS_THR[3:0]	0 (0000)	R/W	Sets the absolute RSSI threshold for asserting carrier set. The 2-complement signed threshold is programmed in st. 1 dB and is relative to the MAGN_TARGET setting.	
				Setting Carrier sense absolute threshold	
				(Equal to channel filter amplitude when AG has not decreased gain)	iC
				-8 (1000) Absolute carrier sense threshold disabled	
				-7 (1001) 7 dB below MAGN_TARGET setting	
				-1 (1111) 1 dB below MAGN_TARGET setting	
				0 (0000) At MAGN_TARGET setting	
				1 (0001) 1 dB above MAGN_TARGET setting	
				7 (0111) 7 dB above MAGN_TARGET setting	

0x1D: AGCCTRL0 - AGC Control

Bit	Field Name	Reset	R/W	Description	Description		
7:6	HYST_LEVEL[1:0]	2 (10)	R/W		evel of hysteresis on the determine gain change	magnitude deviation (internal AGC s).	
				Setting	Description		
				0 (00)	No hysteresis, small s	ymmetric dead zone, high gain	
				1 (01)	Low hysteresis, small gain	asymmetric dead zone, medium	
				2 (10)	Medium hysteresis, m medium gain	edium asymmetric dead zone,	
				3 (11)	Large hysteresis, large gain	e asymmetric dead zone, low	
5:4	WAIT_TIME[1:0]	1 (01)	R/W			amples from a gain adjustment prithm starts accumulating new	
				Setting	Channel filter samp	les	
				0 (00)	8		
				1 (01)	16		
				2 (10)	24		
				3 (11)	32		
3:2	AGC_FREEZE[1:0]	0 (00)	R/W	Control wh	hen the AGC gain should be frozen.		
				Setting	Function		
				0 (00)	Normal operation. Alw	ays adjust gain when required.	
				1 (01)	The gain setting is froz found.	ren when a sync word has been	
				2 (10)	Manually freeze the ar continue to adjust the	nalogue gain setting and digital gain.	
				3 (11)		the analogue and the digital manually overriding the gain.	
1:0	FILTER_LENGTH[1:0]	1 (01)	R/W			amplitude from the channel filter. dary for OOK/ASK reception.	
				Setting	Channel filter samples	OOK/ASK decision boundary	
				0 (00)	8	4 dB	
				1 (01)	16	8 dB	
				2 (10)	32	12 dB	
				3 (11)	64	16 dB	

0x1E: WOREVT1 – High Byte Event0 Timeout

Bit	Field Name	Reset	R/W	Description
7:0	EVENT0[15:8]	135 (0x87)	R/W	High byte of EVENT0 timeout register
				$t_{Event0} = \frac{750}{f_{XOSC}} \cdot EVENT0 \cdot 2^{5 \cdot WOR_RES}$





0x1F: WOREVT0 –Low Byte Event0 Timeout

Bit	Field Name	Reset	R/W	Description
7:0	EVENT0[7:0]	107 (0x6B)	R/W	Low byte of EVENT0 timeout register.
				The default EVENT0 value gives 1.0s timeout, assuming a 26.0 MHz crystal.

0x20: WORCTRL - Wake On Radio Control

Bit	Field Name	Reset	R/W	Description	on		
7	RC_PD	1	R/W		vn signal to RC oscillator. When w will be performed	ritten to 0, automatic	initial
6:4	EVENT1[2:0]	7 (111)	R/W	Timeout setting from register block. Decoded to Event 1 time oscillator clock frequency equals $F_{\rm XOSC}/750$, which is 34.7 – depending on crystal frequency. The table below lists the nu periods after Event 0 before Event 1 times out.			lz,
				Setting	t _{Event1}		
				0 (000)	4 (0.111 – 0.115 ms)		
				1 (001)	6 (0.167 – 0.173 ms)		
				2 (010)	8 (0.222 – 0.230 ms)		
				3 (011)	12 (0.333 – 0.346 ms)		
				4 (100)	16 (0.444 – 0.462 ms)		
				5 (101)	24 (0.667 – 0.692 ms)		
				6 (110)	32 (0.889 – 0.923 ms)		
				7 (111)	48 (1.333 – 1.385 ms)		
3	RC_CAL	1	R/W	Enables (1) or disables (0) the RC oscillator	calibration.	
2			R0	Not used			
1:0	WOR_RES	0 (00)	R/W		ne Event 0 resolution as well as mand maximum timeout under normal		e WOR
				Setting	Resolution (1 LSB)	Max timeout	7
				0 (00)	1 period (28 – 29 μs)	1.8 – 1.9 seconds	1
				1 (01)	2 ⁵ periods (0.89 – 0.92 ms)	58 – 61 seconds	
				2 (10)	2 ¹⁰ periods (28 – 30 ms)	31 – 32 minutes	
				3 (11)	2 ¹⁵ periods (0.91 – 0.94 s)	16.5 – 17.2 hours	
					WOR_RES should be 0 or 1 when us > 1 will give a very low duty cycle.	sing WOR because	_
				In normal	RX operation all settings of wor_R	ES can be used.	



0x21: FREND1 – Front End RX Configuration

Bit	Field Name	Reset	R/W	Description
7:6	LNA_CURRENT[1:0]	1 (01)	R/W	Adjusts front-end LNA PTAT current output
5:4	LNA2MIX_CURRENT[1:0]	1 (01)	R/W	Adjusts front-end PTAT outputs
3:2	LODIV_BUF_CURRENT_RX[1:0]	1 (01)	R/W	Adjusts current in RX LO buffer (LO input to mixer)
1:0	MIX_CURRENT[1:0]	2 (10)	R/W	Adjusts current in mixer

0x22: FREND0 – Front End TX Configuration

Bit	Field Name	Reset	R/W	Description
7:6			R0	Not used
5:4	LODIV_BUF_CURRENT_TX[1:0]	1 (0x01)	R/W	Adjusts current TX LO buffer (input to PA). The value to use in this field is given by the SmartRF® Studio software [8].
3			R0	Not used
2:0	PA_POWER[2:0]	0 (0x00)	R/W	Selects PA power setting. This value is an index to the PATABLE, which can be programmed with up to 8 different PA settings. In OOK/ASK mode, this selects the PATABLE index to use when transmitting a '1'. PATABLE index zero is used in OOK/ASK when transmitting a '0'. The PATABLE settings from index '0' to the PA_POWER value are used for ASK TX shaping, and for power ramp-up/ramp-down at the start/end of transmission in all TX modulation formats.

0x23: FSCAL3 - Frequency Synthesizer Calibration

Bit	Field Name	Reset	R/W	Description
7:6	FSCAL3[7:6]	2 (0x02)	R/W	Frequency synthesizer calibration configuration. The value to write in this field before calibration is given by the SmartRF® Studio software.
5:4	CHP_CURR_CAL_EN[1:0]	2 (0x02)	R/W	Disable charge pump calibration stage when 0.
3:0	FSCAL3[3:0]	9 (1001)	R/W	Frequency synthesizer calibration results register. Digital bit vector defining the charge pump output current, on an exponential scale: I_OUT = $I_0 \cdot 2^{\text{FSCAL3}[3:0]/4}$ Fast frequency hopping without calibration for each hop can be done by calibrating upfront for each frequency and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values. Between each frequency hop, calibration can be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency. Please note that for operation at 950-956 MHz targeting ARIB STD-T96 FSCAL3 [7:4] needs to be set to 0xA



0x24: FSCAL2 - Frequency Synthesizer Calibration

Bit	Field Name	Reset	R/W	Description
7:6			R0	Not used
5	VCO_CORE_H_EN	0	R/W	Choose high (1) / low (0) VCO
4:0	FSCAL2[4:0]	10 (0x0A)	R/W	Frequency synthesizer calibration results register. VCO current calibration result and override value. Fast frequency hopping without calibration for each hop can be done by calibrating upfront for each frequency and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values. Between each frequency hop, calibration can be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency.

0x25: FSCAL1 - Frequency Synthesizer Calibration

Bit	Field Name	Reset	R/W	Description
7:6			R0	Not used
5:0	FSCAL1[5:0]	32 (0x20)	R/W	Frequency synthesizer calibration results register. Capacitor array setting for VCO coarse tuning. Fast frequency hopping without calibration for each hop can be done by calibrating upfront for each frequency and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values. Between each frequency hop, calibration can be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency.

0x26: FSCAL0 - Frequency Synthesizer Calibration

Bit	Field Name	Reset	R/W	Description
7			R0	Not used
6:0	FSCAL0[6:0]	13 (0x0D)	R/W	Frequency synthesizer calibration control. The value to use in this register is given by the SmartRF® Studio software [8].
				Please note that for operation at 950-956 MHz targeting ARIB STD-T96, FSCAL0 needs to be set to 0x07

0x27: RCCTRL1 - RC Oscillator Configuration

Bit	Field Name	Reset	R/W	Description
7		0	R0	Not used
6:0	RCCTRL1[6:0]	65 (0x41)	R/W	RC oscillator configuration.

0x28: RCCTRL0 - RC Oscillator Configuration

Bit	Field Name	Reset	R/W	Description
7		0	R0	Not used
6:0	RCCTRL0[6:0]	0 (0x00)	R/W	RC oscillator configuration.





29.2 Configuration Register Details – Registers that Loose Programming in SLEEP State

0x29: FSTEST – Frequency Synthesizer Calibration Control

Bit	Field Name	Reset	R/W	Description
7:0	FSTEST[7:0]	89 (0x59)	R/W	For test only. Do not write to this register.

0x2A: PTEST - Production Test

Bit	Field Name	Reset	R/W	Description
7:0	PTEST[7:0]	127 (0x7F)	R/W	Writing 0xBF to this register makes the on-chip temperature sensor available in the IDLE state. The default 0x7F value should then be written back before leaving the IDLE state. Other use of this register is for test only.

0x2B: AGCTEST - AGC Test

Bit	Field Name	Reset	R/W	Description
7:0	AGCTEST[7:0]	63 (0x3F)	R/W	For test only. Do not write to this register.

0x2C: TEST2 - Various Test Settings

Bit	Field Name	Reset	R/W	Description
7:0	TEST2[7:0]	136 (0x88)	R/W	The value to use in this register is given by the SmartRF® Studio software [8]. This register will be forced to 0x88 or 0x81 when it wakes up from SLEEP mode, depending on the configuration of FIFOTHR. ADC_RETENTION.
				Note that the value read from this register when waking up from SLEEP always is the reset value (0x88) regardless of the ADC_RETENTION setting. The inversion of some of the bits due to the ADC_RETENTION setting is only seen INTERNALLY in the analog part.

0x2D: TEST1 - Various Test Settings

Bit	Field Name	Reset	R/W	Description
7:0	TEST1[7:0]	49 (0x31)	R/W	The value to use in this register is given by the SmartRF® Studio software [8]. This register will be forced to 0x31 or 0x35 when it wakes up from SLEEP mode, depending on the configuration of FIFOTHR. ADC_RETENTION.
				Note that the value read from this register when waking up from SLEEP always is the reset value (0x31) regardless of the ADC_RETENTION setting. The inversion of some of the bits due to the ADC_RETENTION setting is only seen INTERNALLY in the analog part.



SWRS082 Page 84 of 92

0x2E: TEST0 - Various Test Settings

Bit	Field Name	Reset	R/W	Description
7:2	TEST0[7:2]	2 (0x02)	R/W The value to use in this register is given by the SmartRF® Studio software [8].	
1	VCO_SEL_CAL_EN	1	R/W	Enable VCO selection calibration stage when 1
0	TESTO[0]	1	R/W	The value to use in this register is given by the SmartRF® Studio software [8].

29.3 Status Register Details

0x30 (0xF0): PARTNUM - Chip ID

Bit	Field Name	Reset	R/W	Description
7:0	PARTNUM[7:0]	0 (0x00)	R	Chip part number

0x31 (0xF1): VERSION - Chip ID

Bit	Field Name	Reset	R/W	Description	
7:0	VERSION[7:0]	5 (0x05)	R	Chip version number.	

0x32 (0xF2): FREQEST – Frequency Offset Estimate from Demodulator

Bit	Field Name	Reset	R/W	Description
7:0	FREQOFF_EST		R	The estimated frequency offset (2's complement) of the carrier. Resolution is $F_{XTAL}/2^{14}$ (1.59 - 1.65 kHz); range is ±202 kHz to ±210 kHz, depending on XTAL frequency.
				Frequency offset compensation is only supported for 2-FSK, GFSK, and MSK modulation. This register will read 0 when using ASK or OOK modulation.

0x33 (0xF3): LQI - Demodulator Estimate for Link Quality

Bit	Field Name	Reset	R/W	R/W Description	
7	CRC OK		R	The last CRC comparison matched. Cleared when entering/restarting RX mode.	
6:0	LQI_EST[6:0]		R	The Link Quality Indicator estimates how easily a received signal can be demodulated. Calculated over the 64 symbols following the sync word	

0x34 (0xF4): RSSI - Received Signal Strength Indication

Bit	Field Name	Reset	R/W	Description
7:0	RSSI		R	Received signal strength indicator





0x35 (0xF5): MARCSTATE - Main Radio Control State Machine State

Bit	Field Name	Reset	R/W	Description		
7:5			R0	Not used		
4:0	MARC_STATE[4:0]		R	Main Radio C	Control FSM State	
				Value	State name	State (Figure 20, page 45)
				0 (0x00)	SLEEP	SLEEP
				1 (0x01)	IDLE	IDLE
				2 (0x02)	XOFF	XOFF
				3 (0x03)	VCOON_MC	MANCAL
				4 (0x04)	REGON_MC	MANCAL
				5 (0x05)	MANCAL	MANCAL
				6 (0x06)	VCOON	FS_WAKEUP
				7 (0x07)	REGON	FS_WAKEUP
				8 (0x08)	STARTCAL	CALIBRATE
				9 (0x09)	BWBOOST	SETTLING
				10 (0x0A)	FS_LOCK	SETTLING
				11 (0x0B)	IFADCON	SETTLING
				12 (0x0C)	ENDCAL	CALIBRATE
				13 (0x0D)	RX	RX
				14 (0x0E)	RX_END	RX
				15 (0x0F)	RX_RST	RX
				16 (0x10)	TXRX_SWITCH	TXRX_SETTLING
				17 (0x11)	RXFIFO_OVERFLOW	RXFIFO_OVERFLOW
				18 (0x12)	FSTXON	FSTXON
				19 (0x13)	TX	TX
				20 (0x14)	TX_END	TX
				21 (0x15)	RXTX_SWITCH	RXTX_SETTLING
				22 (0x16)	TXFIFO_UNDERFLOW	TXFIFO_UNDERFLOW
					ng CSn low will make the c	SLEEP or XOFF state numbers hip enter the IDLE mode from the

0x36 (0xF6): WORTIME1 – High Byte of WOR Time

Bit	Field Name	Reset	R/W	Description
7:0	TIME[15:8]		R	High byte of timer value in WOR module

0x37 (0xF7): WORTIME0 - Low Byte of WOR Time

Bit	Field Name	Reset	R/W	Description
7:0	TIME[7:0]		R	Low byte of timer value in WOR module





0x38 (0xF8): PKTSTATUS - Current GDOx Status and Packet Status

Bit	Field Name	Reset	R/W	Description
7	CRC_OK		R	The last CRC comparison matched. Cleared when entering/restarting RX mode.
6	CS		R	Carrier sense
5	PQT_REACHED		R	Preamble Quality reached
4	CCA		R	Channel is clear
3	SFD		R	Sync word found. Asserted when sync word has been sent / received, and de-asserted at the end of the packet. In RX, this bit will de-assert when the optional address check fails or the radio enter RX_OVERFLOW state. In TX this bit will de-assert if the radio enters TX_UNDERFLOW state.
2	GDO2		R Current GDO2 value. Note: the reading gives the non-inverted value irrespective of what IOCFG2.GDO2_INV is programmed to.	
				It is not recommended to check for PLL lock by reading PKTSTATUS [2] with GDO2_CFG=0x0A.
1			R0	Not used
0	GDO0		R	Current GDO0 value. Note: the reading gives the non-inverted value irrespective of what IOCFG0.GDO0_INV is programmed to.
				It is not recommended to check for PLL lock by reading PKTSTATUS [0] with GDOO_CFG=0x0A.

0x39 (0xF9): VCO_VC_DAC - Current Setting from PLL Calibration Module

Bit	Field Name	Reset	R/W	Description
7:0	VCO_VC_DAC[7:0]		R	Status register for test only.

0x3A (0xFA): TXBYTES - Underflow and Number of Bytes

Bit	Field Name	Reset	R/W	Description
7	TXFIFO_UNDERFLOW		R	
6:0	NUM_TXBYTES		R	Number of bytes in TX FIFO

0x3B (0xFB): RXBYTES – Overflow and Number of Bytes

Bit	Field Name	Reset	R/W	Description
7	RXFIFO_OVERFLOW		R	
6:0	NUM_RXBYTES		R	Number of bytes in RX FIFO

0x3C (0xFC): RCCTRL1_STATUS - Last RC Oscillator Calibration Result

Bit	Field Name	Reset	R/W	Description
7			R0	Not used
6:0	RCCTRL1_STATUS[6:0]		R	Contains the value from the last run of the RC oscillator calibration routine.
				For usage description refer to AN047 [7]





0x3D (0xFD): RCCTRL0_STATUS - Last RC Oscillator Calibration Result

Bit	Field Name	Reset	R/W	Description
7			R0	Not used
6:0	RCCTRL0_STATUS[6:0]		R	Contains the value from the last run of the RC oscillator calibration routine.
				For usage description refer to Application Note AN047 [7].



30 Package Description (QFN 20)

30.1 Recommended PCB Layout for Package (QFN 20)

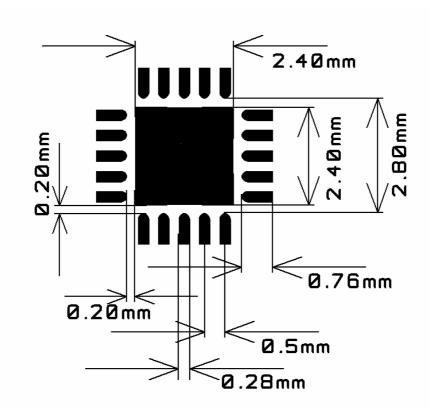


Figure 29: Recommended PCB Layout for QFN 20 Package

Note: Figure 29 is an illustration only and not to scale. There are five 10 mil via holes distributed symmetrically in the ground pad under the package. See also the CC1100EEM reference designs ([3] and [4]).

30.2 Soldering Information

The recommendations for lead-free reflow in IPC/JEDEC J-STD-020 should be followed.

30.3 Ordering Information

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead Finish	MSL Peak Temp (3)
CC1100ERTKR	Active	QFN	RTK	20	3000	Green (RoHS &	Cu NiPdAu	LEVEL3-260C
						no Sb/Br)		1 YEAR
CC1100ERTKT	Active	QFN	RTK	20	250	Green (RoHS &	Cu NiPdAu	LEVEL3-260C
						no Sb/Br)		1 YEAR

Orderable Evaluation Module	Description	Minimum Order Quantity
CC1100E-EMK470	CC1100E Evaluation Module Kit, 470-510 MHz	1
CC1100E-EMK950	CC1100E Evaluation Module Kit, 950-960 MHz	1

Table 42: Ordering Information

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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References

- [1] CC1101 Datasheet
- [2] CC1100 Datasheet
- [3] CC1100E EM 470 MHz Reference Design
- [4] CC1100E EM 950 MHz Reference Design
- [5] CC1100E Errata Note
- [6] ARIB STD-T96 ver.1.0
- [7] AN047 CC1100/CC2500 Wake-On-Radio (swra126.pdf)
- [8] SmartRF[®] Studio (swrc046.zip)
- [9] CC1100 CC1101 CC1100E CC2500 Examples Libraries (swrc021.zip)
- [10] CC1100/CC1150DK, CC1101DK, and CC2500/CC2550DK Examples and Libraries User Manual (swru109.pdf)
- [11] DN010 Close-in Reception with CC1101 (and CC1100E) (swra147.pdf)
- [12] DN015 Permanent Frequency Offset Compensation (swra159.pdf)
- [13] DN505 RSSI Interpretation and Timing (swra114.pdf)
- [14] AN058 Antenna Selection Guide (swra161.pdf)
- [15] DN022 CC11xx OOK/ASK register settings (swra215.pdf)
- [16] DN005 CC11xx Sensitivity versus Frequency Offset and Crystal Accuracy (swra122.pdf)
- [17] DN501 PATABLE Access
- [18] DN504 FEC Implementation



31 General Information

31.1 Document History

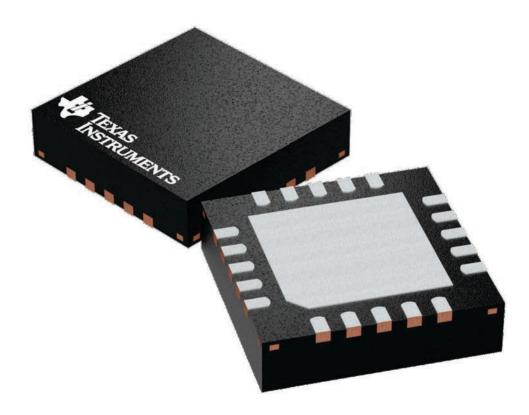
Revision	Date	Description/Changes
SWRS082	April 2009	First data sheet release

Table 43: Document History



4 x 4, 0.5 mm pitch

VERY THIN QUAD FLATPACK



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4224735/A



RGP (S-PVQFN-N20) PLASTIC QUAD FLATPACK NO-LEAD 4,15 3,85 A В 15 11 10 16 4,15 3,85 20 6 Pin 1 Index Area Top and Bottom 0,20 Nominal Lead Frame 1,00 0,80 Seating Plane ○ 0,08 C Seating Height $\frac{0.05}{0.00}$ C THERMAL PAD 20 SIZE AND SHAPE 4X 2,00 SHOWN ON SEPARATE SHEET 16 10 0,50 15

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

 $20X \frac{0,30}{0,18}$

0,10 M C A B 0,05 M C

4203555/G 07/11

🖒 Check thermal pad mechanical drawing in the product datasheet for nominal lead length dimensions.



Bottom View

RGP (S-PVQFN-N20)

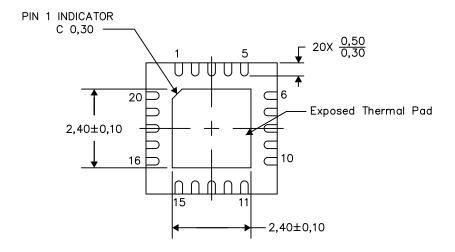
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No—Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206346-7/AA 11/13

NOTES: A. All linear dimensions are in millimeters



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